

# STN Columbus

\* \* \* \* \* Welcome to STN International \* \* \* \* \*

NEWS	1		Web Page for STN Seminar Schedule - N. America
NEWS	2	DEC 01	ChemPort single article sales feature unavailable
NEWS	3	FEB 02	Simultaneous left and right truncation (SLART) added for CERAB, COMPUAB, ELCOM, and SOLIDSTATE
NEWS	4	FEB 02	GENBANK enhanced with SET PLURALS and SET SPELLING
NEWS	5	FEB 06	Patent sequence location (PSL) data added to USGENE
NEWS	6	FEB 10	COMPENDEX reloaded and enhanced
NEWS	7	FEB 11	WTEXTILES reloaded and enhanced
NEWS	8	FEB 19	New patent-examiner citations in 300,000 CA/CAPLUS patent records provide insights into related prior art
NEWS	9	FEB 19	Increase the precision of your patent queries -- use terms from the IPC Thesaurus, Version 2009.01
NEWS	10	FEB 23	Several formats for image display and print options discontinued in USPATFULL and USPAT2
NEWS	11	FEB 23	MEDLINE now offers more precise author group fields and 2009 MeSH terms
NEWS	12	FEB 23	TOXCENTER updates mirror those of MEDLINE - more precise author group fields and 2009 MeSH terms
NEWS	13	FEB 23	Three million new patent records blast AEROSPACE into STN patent clusters
NEWS	14	FEB 25	USGENE enhanced with patent family and legal status display data from INPADOCDB
NEWS	15	MAR 06	INPADOCDB and INPAFAMDB enhanced with new display formats
NEWS	16	MAR 11	EPFULL backfile enhanced with additional full-text applications and grants
NEWS	17	MAR 11	ESBIOBASE reloaded and enhanced
NEWS	18	MAR 20	CAS databases on STN enhanced with new super role for nanomaterial substances
NEWS	19	MAR 23	CA/CAPLUS enhanced with more than 250,000 patent equivalents from China
NEWS	20	MAR 30	IMSPATENTS reloaded and enhanced
NEWS	21	APR 03	CAS coverage of exemplified prophetic substances enhanced
NEWS	22	APR 07	STN is raising the limits on saved answers
NEWS	23	APR 24	CA/CAPLUS now has more comprehensive patent assignee information
NEWS	24	APR 26	USPATFULL and USPAT2 enhanced with patent assignment/reassignment information
NEWS	25	APR 28	CAS patent authority coverage expanded
NEWS	26	APR 28	ENCOMPLIT/ENCOMPLIT2 search fields enhanced
NEWS	27	APR 28	Limits doubled for structure searching in CAS REGISTRY
NEWS	28	MAY 08	STN Express, Version 8.4, now available
NEWS	29	MAY 11	STN on the Web enhanced
NEWS	30	MAY 11	BEILSTEIN substance information now available on STN Easy
NEWS	31	MAY 14	DGENE, PCTGEN and USGENE enhanced with increased limits for exact sequence match searches and introduction of free HIT display format
NEWS	32	MAY 15	INPADOCDB and INPAFAMDB enhanced with Chinese legal status data

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NEWS EXPRESS JUNE 27 08 CURRENT WINDOWS VERSION IS V8.3,  
AND CURRENT DISCOVER FILE IS DATED 06 APRIL 2009.

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FILE 'HOME' ENTERED AT 00:05:08 ON 23 MAY 2009

=> file caplus

COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	0.22	0.22

FILE 'CAPLUS' ENTERED AT 00:05:27 ON 23 MAY 2009

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FILE COVERS 1907 - 23 May 2009 VOL 150 ISS 22

FILE LAST UPDATED: 21 May 2009 (20090521/ED)

REVISED CLASS FIELDS (/NCL) LAST RELOADED: Feb 2009

USPTO MANUAL OF CLASSIFICATIONS THESAURUS ISSUE DATE: Feb 2009

CAplus now includes complete International Patent Classification (IPC) reclassification data for the third quarter of 2008.

CAS Information Use Policies apply and are available at:

<http://www.cas.org/legal/infopolicy.html>

This file contains CAS Registry Numbers for easy and accurate

=> s 22811-02-5 or 10220-46-9 or 2917-26-2 or 2885-00-9 or thioglycolate or mercaptoacetate or hexadecanethiol or hexadecylthiol or mercaptan or octadecanethiol or octadecylthiol

**REGISTRY INITIATED**

Substance data SEARCH and crossover from CAS REGISTRY in progress...

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Use DISPLAY HITSTR (or FHITSTR) to directly view retrieved structures.

L2            2011 L1

**REGISTRY INITIATED**

Substance data SEARCH and crossover from CAS REGISTRY in progress...  
Use DISPLAY HITSTR (or FHITSTR) to directly view retrieved structures.

L4            1621 L3

**REGISTRY INITIATED**

Substance data SEARCH and crossover from CAS REGISTRY in progress...  
Use DISPLAY HITSTR (or FHITSTR) to directly view retrieved structures.

L6            50 L5

**REGISTRY INITIATED**

Substance data SEARCH and crossover from CAS REGISTRY in progress...  
Use DISPLAY HITSTR (or FHITSTR) to directly view retrieved structures.

L8            6 L7

5570 THIOGLYCOLATE  
2218 MERCAPTOACETATE  
1405 HEXADECANETHIOL  
41 HEXADECYLTHIOL  
22248 MERCAPTAN  
1668 OCTADECANETHIOL  
91 OCTADECYLTHIOL

L9            32684 L8 OR L6 OR L4 OR L2 OR THIOGLYCOLATE OR MERCAPTOACETATE OR HEXA  
DECANETHIOL OR HEXADECYLTHIOL OR MERCAPTAN OR OCTADECANETHIOL  
OR OCTADECYLTHIOL

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```
=> s (nonionic or non-ionic or anionic or zwitterionic) and surfactant#
      79712 NONIONIC
      1054666 NON
      307432 IONIC
      9398 NON-IONIC
          (NON(W) IONIC)
      134021 ANIONIC
      13094 ZWITTERIONIC
      275066 SURFACTANT#
L10      84695 (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFACTAN
          T#
```

=> d his

```
(FILE 'HOME' ENTERED AT 00:05:08 ON 23 MAY 2009)

FILE 'CAPLUS' ENTERED AT 00:05:27 ON 23 MAY 2009
      S 22811-02-5/REG# OR 10220-46-9/REG# OR 2917-26-2/REG# OR 28

FILE 'REGISTRY' ENTERED AT 00:12:43 ON 23 MAY 2009
L1      1 S 2885-00-9/RN

FILE 'CAPLUS' ENTERED AT 00:12:44 ON 23 MAY 2009
L2      2011 S L1

FILE 'REGISTRY' ENTERED AT 00:12:44 ON 23 MAY 2009
L3      1 S 2917-26-2/RN

FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009
L4      1621 S L3

FILE 'REGISTRY' ENTERED AT 00:12:45 ON 23 MAY 2009
L5      1 S 10220-46-9/RN

FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009
L6      50 S L5

FILE 'REGISTRY' ENTERED AT 00:12:46 ON 23 MAY 2009
L7      1 S 22811-02-5/RN

FILE 'CAPLUS' ENTERED AT 00:12:46 ON 23 MAY 2009
L8      6 S L7
L9      32684 S L8 OR L6 OR L4 OR L2 OR THIOGLYCOLATE OR MERCAPTOACETATE OR H
L10     84695 S (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFAC
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=> s 19 and 110

```
L11      319 L9 AND L10
```

=> s metal treat##### or treat##### metal

```
      1928101 METAL
      4009269 TREAT#####
          2447 METAL TREAT#####
              (METAL(W) TREAT#####)
      4009717 TREAT#####
      1928101 METAL
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## STN Columbus

4324 TREAT##### METAL

(TREAT#####(W)METAL)

L12 6680 METAL TREAT##### OR TREAT##### METAL

=&gt; l11 and l12

L11 IS NOT A RECOGNIZED COMMAND

The previous command name entered was not recognized by the system.

For a list of commands available to you in the current file, enter

"HELP COMMANDS" at an arrow prompt (=&gt;).

=&gt; s l11 and l12

L13 1 L11 AND L12

=&gt; d

L13 ANSWER 1 OF 1 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:798402 CAPLUS

DN 139:311931

TI Metal coating of hair fibers for cosmetics

IN Vic, Gabin; Livoreil, Aude; Giroud, Franck

PA L'oreal, Fr.

SO Fr. Demande, 18 pp.

CODEN: FRXXBL

DT Patent

LA French

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	FR 2838050	A1	20031010	FR 2002-4352	20020408
	FR 2838050	B1	20060714		
	CN 1449737	A	20031022	CN 2003-108449	20030331
	CN 1213719	C	20050810		
	BR 2003000873	A	20040817	BR 2003-873	20030403
	EP 1352630	A2	20031015	EP 2003-290860	20030407
	EP 1352630	A3	20040324		
	EP 1352630	B1	20060301		
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK				
	US 20030223944	A1	20031204	US 2003-407911	20030407
	JP 2003300840	A	20031021	JP 2003-104420	20030408
	JP 3759120	B2	20060322		
PRAI	FR 2002-4352	A	20020408		
	US 2002-372455P	P	20020416		

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD  
ALL CITATIONS AVAILABLE IN THE RE FORMAT

=&gt; d all

L13 ANSWER 1 OF 1 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:798402 CAPLUS

DN 139:311931

ED Entered STN: 12 Oct 2003

TI Metal coating of hair fibers for cosmetics

IN Vic, Gabin; Livoreil, Aude; Giroud, Franck

PA L'oreal, Fr.

SO Fr. Demande, 18 pp.

CODEN: FRXXBL

## STN Columbus

DT Patent  
 LA French  
 IC ICM A61K007-075  
 CC 62-3 (Essential Oils and Cosmetics)  
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	FR 2838050	A1	20031010	FR 2002-4352	20020408
	FR 2838050	B1	20060714		
	CN 1449737	A	20031022	CN 2003-108449	20030331
	CN 1213719	C	20050810		
	BR 2003000873	A	20040817	BR 2003-873	20030403
	EP 1352630	A2	20031015	EP 2003-290860	20030407
	EP 1352630	A3	20040324		
	EP 1352630	B1	20060301		
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK				
	US 20030223944	A1	20031204	US 2003-407911	20030407
	JP 2003300840	A	20031021	JP 2003-104420	20030408
	JP 3759120	B2	20060322		
PRAI	FR 2002-4352	A	20020408		
	US 2002-372455P	P	20020416		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
FR 2838050	ICM	A61K007-075
	IPCI	A61K0007-075 [ICM, 7]
	IPCR	A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
	ECLA	A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10
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ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;  
A61Q005/00; A61Q005/10  
EP 1352630 IPCI A61K0008-19 [I,C]; A61K0008-30 [I,C]; A61Q0005-00  
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A61K0008-19 [I,A]; A61K0008-46 [I,A]; A61Q0005-00 [I,A]  
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ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;  
A61Q005/00; A61Q005/10  
US 20030223944 IPCI A61K0007-075 [ICM,7]; A61K0007-06 [ICS,7]  
IPCR A61K0008-19 [I,C\*]; A61K0008-19 [I,A]; A61K0008-30  
[I,C\*]; A61K0008-46 [I,A]; A61Q0005-12 [I,C\*];  
A61Q0005-12 [I,A]  
NCL 424/070.100; 510/119.000  
ECLA A61K008/19; A61K008/46; A61Q005/12  
JP 2003300840 IPCI A61K0008-00 [I,A]; A61Q0005-00 [I,A]; A61K0008-18  
[I,A]; A61Q0001-02 [I,A]  
IPCR A61K0008-00 [I,C\*]; A61K0008-00 [I,A]; A61K0008-18  
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[I,A]; A61K0008-72 [I,C\*]; A61K0008-73 [I,A];  
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[I,C\*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C\*];  
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[I,A]; A61Q0005-12 [I,C\*]; A61Q0005-12 [I,A]  
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;  
A61Q005/00; A61Q005/10  
AB The invention relates to a treatment process which confers cosmetic  
properties on hair fibers. The process consists of treating the fibers  
with a metal salt in the presence of a reducing agent, directly on the  
fiber to form the corresponding free metal. Thus, a lock of hair after  
being shampooed, was dried and an aq. soln. of AgNO3 was applied onto the  
hair. After the addn. of NaBH4, the natural pigmented hair was dark, with  
metallic brilliance reflected on it.  
ST metal salt hair cosmetic  
IT Alcohols, biological studies  
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

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PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)

(C1-4; **metal treatment** of hair fibers for cosmetics)

IT Alkanes, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)

(C5-10; **metal treatment** of hair fibers for cosmetics)

IT Polyelectrolytes

## **Surfactants**

(amphoteric; **metal treatment** of hair fibers for cosmetics)

IT Fats and Glyceridic oils, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)

(animal; **metal treatment** of hair fibers for cosmetics)

IT **Surfactants**

(**anionic**; **metal treatment** of hair fibers for cosmetics)

IT Polyelectrolytes

## **Surfactants**

(cationic; **metal treatment** of hair fibers for cosmetics)

IT Cosmetics

(emollients; **metal treatment** of hair fibers for cosmetics)

IT Sulfates, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)  
(hydrogen; **metal treatment** of hair fibers for cosmetics)

IT Antifoaming agents

Antiperspirants

Cosmetics

Hair

Hair preparations

Perfumes

Pigments, nonbiological

Preservatives

Reducing agents

Shampoos

Sunscreens

Thickening agents

(**metal treatment** of hair fibers for cosmetics)

IT Alkaline earth salts

Bromates

Carbonates, biological studies

Disulfides

Halides

Nitrates, biological studies

Paraffin oils

Phosphates, biological studies

Polymers, biological studies

Polysiloxanes, biological studies

Proteins

Rare earth salts

Sulfates, biological studies



Thioethers

Thiosulfates

Transition metal salts

Vitamins

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
(Uses)

(**metal treatment** of hair fibers for cosmetics)

IT Bisulfites

Enzymes, reactions

Sulfites

Thiols, reactions

Thioredoxins

RL: RCT (Reactant); RACT (Reactant or reagent)

(**metal treatment** of hair fibers for cosmetics)

IT Cosmetics

(moisturizers; **metal treatment** of hair fibers for  
cosmetics)

IT **Surfactants**

(**nonionic; metal treatment** of hair fibers  
for cosmetics)

IT Peroxysulfates

RL: RCT (Reactant); RACT (Reactant or reagent)

(peroxymonosulfates; **metal treatment** of hair fibers  
for cosmetics)

IT Alcohols, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
(Uses)

(polyhydric; **metal treatment** of hair fibers for  
cosmetics)

IT Sulfonic acids, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
(Uses)

(salts; **metal treatment** of hair fibers for  
cosmetics)

IT Sulfinic acids

Thiols, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(salts; **metal treatment** of hair fibers for  
cosmetics)

IT Salts, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(thiol; **metal treatment** of hair fibers for  
cosmetics)

IT Lactones

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
(Uses)

(thiolactones; **metal treatment** of hair fibers for  
cosmetics)

IT Fats and Glyceridic oils, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
(Uses)

(vegetable; **metal treatment** of hair fibers for  
cosmetics)

IT 64-17-5, Ethanol, biological studies 67-63-0, Isopropanol, biological  
studies 67-64-1, Acetone, biological studies 78-93-3, Methyl ethyl

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ketone, biological studies 79-20-9, Methyl acetate 110-71-4  
 123-86-4, Butyl acetate 141-78-6, EtOAc, biological studies  
 7429-90-5D, Aluminum, salts 7439-89-6D, Iron, salts 7439-98-7D,  
 Molybdenum, salts 7440-02-0D, Nickel, salts 7440-05-3D, Palladium,  
 salts 7440-06-4D, Platinum, salts 7440-22-4D, Silver, salts  
 7440-31-5D, Tin, salts 7440-32-6D, Titanium, salts 7440-33-7D,  
 Tungsten, salts 7440-36-0D, Antimony, salts 7440-50-8D, Copper, salts  
 7440-57-5D, Gold, salts 7440-66-6D, Zinc, salts 7440-74-6D, Indium,  
 salts 7758-89-6, Cuprous chloride 7761-88-8, Silver nitrate,  
 biological studies 7775-41-9, Silver fluoride 7783-89-3, Silver  
 bromate 7783-90-6, Silver chloride, biological studies 7783-96-2,  
 Silver iodide 7785-23-1, Silver bromide 7787-70-4, Cuprous bromide  
 10025-98-6, Dipotassium palladium tetrachloride 10294-26-5, Silver  
 sulfate 10294-28-7, Gold tribromide 16903-35-8 16923-58-3, Disodium  
 hexachloroplatinate 19045-66-0D, Thiocarbamic acid, salts 73506-93-1,  
 Diethoxyethane

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
 PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
 (Uses)

(**metal treatment** of hair fibers for cosmetics)

IT 50-81-7, Ascorbic acid, reactions 53-57-6, NaDPH 58-68-4, NaDH  
 68-11-1, Thioglycolic acid, reactions 77-92-9D, Citric acid, salts  
 106-51-4, 2,5-Cyclohexadiene-1,4-dione, reactions 123-31-9,  
 Hydroquinone, reactions 280-64-8, 9-BBN 1758-73-2, Formamidinesulfinic  
 acid **2885-00-9**, 1-Octadecanethiol 3483-12-3,  
 Dithiothreitol 6838-83-1, Diisoamylborane 7772-98-7 7775-14-6  
 7803-51-2, Phosphine 13762-51-1 14451-43-5 16853-85-3 16940-66-2  
 17836-88-3 25895-60-7, Sodium cyanoborohydride 37318-49-3, Protein  
 disulfide isomerase 56553-60-7 131760-67-3 145626-87-5

RL: RCT (Reactant); RACT (Reactant or reagent)

(**metal treatment** of hair fibers for cosmetics)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Anon; PATENT ABSTRACTS OF JAPAN 1991, V015(243), PC-0842
- (2) Anon; PATENT ABSTRACTS OF JAPAN 1992, V016(509), PC-0997
- (3) Dong Sung Pharmaceuticals Co L; EP 1243249 A 2002 CAPLUS
- (4) Grollier, J; US 4971596 A 1990 CAPLUS
- (5) Kanebo Ltd; JP 03077806 A 1991 CAPLUS
- (6) Katsumi, M; JP 04187625 A 1992 CAPLUS
- (7) Lapidus, H; US 4195972 A 1980
- (8) Richez, H; US 1055355 A 1913 CAPLUS
- (9) Wella Ag; DE 2806603 A 1979 CAPLUS
- (10) Wella Ag; DE 29621557 U 1997

=> s silver or ag

379544 SILVER

342362 AG

L14 522045 SILVER OR AG

=> d his

(FILE 'HOME' ENTERED AT 00:05:08 ON 23 MAY 2009)

FILE 'CAPLUS' ENTERED AT 00:05:27 ON 23 MAY 2009

S 22811-02-5/REG# OR 10220-46-9/REG# OR 2917-26-2/REG# OR 28

FILE 'REGISTRY' ENTERED AT 00:12:43 ON 23 MAY 2009

L1 1 S 2885-00-9/RN

## STN Columbus

L2 FILE 'CAPLUS' ENTERED AT 00:12:44 ON 23 MAY 2009  
2011 S L1

L3 FILE 'REGISTRY' ENTERED AT 00:12:44 ON 23 MAY 2009  
1 S 2917-26-2/RN

L4 FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009  
1621 S L3

L5 FILE 'REGISTRY' ENTERED AT 00:12:45 ON 23 MAY 2009  
1 S 10220-46-9/RN

L6 FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009  
50 S L5

L7 FILE 'REGISTRY' ENTERED AT 00:12:46 ON 23 MAY 2009  
1 S 22811-02-5/RN

L8 FILE 'CAPLUS' ENTERED AT 00:12:46 ON 23 MAY 2009  
6 S L7

L9 32684 S L8 OR L6 OR L4 OR L2 OR THIOGLYCOLATE OR MERCAPTOACETATE OR H  
L10 84695 S (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFAC  
L11 319 S L9 AND L10  
L12 6680 S METAL TREAT##### OR TREAT##### METAL  
L13 1 S L11 AND L12  
L14 522045 S SILVER OR AG

=> l11 and l14

L11 IS NOT A RECOGNIZED COMMAND

The previous command name entered was not recognized by the system.  
For a list of commands available to you in the current file, enter  
"HELP COMMANDS" at an arrow prompt (=>).

=> s l11 and l14

L15 12 L11 AND L14

=> d 1-12 all

L15 ANSWER 1 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2008:1046144 CAPLUS

DN 149:312963

ED Entered STN: 29 Aug 2008

TI Preparation of conductive supported noble metal nanoparticle catalysts

IN Stucky, Galen D.; Zheng, Nanfeng

PA The Regents of the University of California, USA

SO U.S. Pat. Appl. Publ., 35pp.

CODEN: USXXCO

DT Patent

LA English

INCL 428403000; 216055000; 428402000; 264005000; 264007000; 502100000;  
502300000; 502159000; 502355000; 502350000

CC 56-4 (Nonferrous Metals and Alloys)

Section cross-reference(s): 57, 67

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----	----	-----	-----	-----
PI	US 20080206562	A1	20080828	US 2008-13436	20080112
PRAI	US 2007-884668P	P	20070112		

CLASS

## STN Columbus

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 20080206562	INCL	428403000; 216055000; 428402000; 264005000; 264007000; 502100000; 502300000; 502159000; 502355000; 502350000
	IPCI	B32B0015-02 [I,A]; C23F0001-00 [I,A]; B29B0009-00 [I,A]; B29B0009-16 [I,A]; B01J0031-06 [I,A]; B01J0021-04 [I,A]; B01J0021-08 [I,A]; B01J0023-34 [I,A]; B01J0023-16 [I,C*]; B01J0029-00 [I,A]; B01J0021-18 [I,A]; B01J0021-00 [I,C*]; B01J0027-06 [I,A]; B01J0023-42 [I,A]; B01J0023-44 [I,A]; B01J0023-50 [I,A]; B01J0023-52 [I,A]; B01J0023-48 [I,C*]; B01J0027-02 [I,A]; B01J0027-24 [I,A]; B01J0031-02 [I,A]; B01J0023-755 [I,A]; B01J0031-26 [I,A]
	NCL	428/403.000; 216/055.000; 216/083.000; 264/005.000; 264/007.000; 428/402.000; 502/080.000; 502/087.000; 502/100.000; 502/150.000; 502/159.000; 502/167.000; 502/168.000; 502/171.000; 502/180.000; 502/181.000; 502/200.000; 502/216.000; 502/232.000; 502/300.000; 502/325.000; 502/337.000; 502/339.000; 502/340.000; 502/344.000; 502/345.000; 502/347.000; 502/349.000; 502/350.000; 502/355.000
AB	The prepn. of elec.-conductive noble metal nanoparticle catalysts on catalyst supports such as alumina, silica, titania, clays, zeolites, or carbon black, is described.	
ST	gold <b>silver</b> palladium nanocatalyst support sol gel micelle ceramic	
IT	Solvents (aprotic; prepn. of conductive supported noble metal nanoparticle catalysts)	
IT	Polyethers, uses RL: MOA (Modifier or additive use); USES (Uses) (arom., alkyl-, <b>surfactants</b> ; prepn. of conductive supported noble metal nanoparticle catalysts)	
IT	Thiols, uses RL: MOA (Modifier or additive use); USES (Uses) (caps on catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)	
IT	Bentonite, processes Carbon black, processes Clays, processes Diatomite Silica gel, processes Zeolites (synthetic), processes RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses) (catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)	
IT	Nanoparticles (catalysts; prepn. of conductive supported noble metal nanoparticle catalysts)	
IT	Alcohols, uses RL: MOA (Modifier or additive use); USES (Uses) (ethoxylated, <b>surfactants</b> ; prepn. of conductive supported noble metal nanoparticle catalysts)	
IT	Hydrocarbons, processes RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses) (fluoro, catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)	
IT	<b>Surfactants</b>	

STN Columbus

- (in coatings; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Electroluminescent devices
- Molecular electronic devices
- Optoelectronics
- Secondary batteries
- Semiconductor devices
- Sensors
- Solar cells
- (nanocatalysts for; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Photolysis catalysts
- (nanocatalysts; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Catalysts
- Semiconductor materials
- (nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT **Surfactants**
- (**nonionic**; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Silsesquioxanes
- RL: RGT (Reagent); RACT (Reactant or reagent)
- (octyl- and hexyl-; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Dyes
- (org.-, functional mol.; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Calcination
- Catalyst supports
- Etching
- Reducing agents
- (prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 7440-44-0, Carbon, processes
- RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
- (activated, catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 64-17-5, Ethanol, uses
- RL: NUU (Other use, unclassified); USES (Uses)
- (buffer soln.; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 49543-63-7, 4-(tert-Butyl)benzyl **mercaptan**
- RL: MOA (Modifier or additive use); USES (Uses)
- (cap on nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1322-36-7, Dodecanethiol
- RL: MOA (Modifier or additive use); USES (Uses)
- (caps on catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 7440-02-0P, Nickel, preparation 7440-05-3P, Palladium, preparation
- 7440-06-4P, Platinum, preparation 7440-22-4P, **Silver**, preparation
- 7440-50-8P, Copper, preparation 7440-57-5P, Gold, preparation
- 12006-51-8P, AuCu
- RL: CAT (Catalyst use); SPN (Synthetic preparation); PREP (Preparation); USES (Uses)
- (catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1309-48-4, Magnesium oxide (MgO), processes 1314-23-4, Zirconia, processes
- 1344-28-1, Aluminum oxide (Al<sub>2</sub>O<sub>3</sub>), processes 7631-86-9,

STN Columbus

Silica, processes 7782-42-5, Graphite, processes 13463-67-7, Titania, processes

RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

(catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 1306-38-3, Cerium oxide (CeO<sub>2</sub>), uses 1313-13-9, Manganese oxide (MnO<sub>2</sub>), uses 1313-96-8, Niobium oxide (Nb<sub>2</sub>O<sub>5</sub>)

RL: MOA (Modifier or additive use); USES (Uses)

(coatings on colloidal silica; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 12638-19-6P

RL: CAT (Catalyst use); SPN (Synthetic preparation); PREP (Preparation); USES (Uses)

(nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 2966-50-9, **Silver** trifluoroacetate 14024-17-0, Iron acetyl acetate 14024-61-4 14024-64-7 16902-59-3 17927-72-9 19443-16-4 19443-17-5 23894-00-0 23894-03-3 24772-51-8 27858-32-8, Titanium diisopropoxide bis(ethyl acetoacetate) 62905-51-5 65574-21-2 65583-10-0 66197-44-2 82269-80-5 93918-06-0, Aluminum sec-butoxide bis(ethyl acetoacetate) 98719-26-7 140190-96-1 144665-26-9 204522-78-1 299957-41-8 380240-62-0 1050499-47-2 1050499-48-3 1050499-49-4 1050499-50-7 1050499-51-8 1050499-52-9 1050499-53-0 1050499-54-1

RL: RCT (Reactant); RACT (Reactant or reagent)

(precursors; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 1313-99-1, Nickel oxide, uses 1345-25-1, Ferrous oxide, uses 11104-61-3, Cobalt oxide

RL: MOA (Modifier or additive use); USES (Uses)

(prepn. of conductive supported noble metal nanoparticle catalysts)

IT 78-07-9, Ethyltriethoxysilane 78-10-4, Tetraethoxysilane 681-84-5, Tetramethoxysilane 682-01-9, Tetrapropoxysilane 1185-55-3, Methyltrimethoxysilane 1336-21-6, Ammonium hydroxide ((NH<sub>4</sub>)(OH)) 2031-67-6, Methyltriethoxysilane 4766-57-8, Tetrabutoxysilane 30232-12-3 192082-40-9, Mercaptoundecanoic acid

RL: RGT (Reagent); RACT (Reactant or reagent)

(prepn. of conductive supported noble metal nanoparticle catalysts)

IT 1722-26-5, Triethylamine-borane 4856-95-5 7337-45-3, tert-Butylamine-borane 13774-81-7, Ammonia-borane

RL: RGT (Reagent); RACT (Reactant or reagent)

(reducing agents; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 67-66-3, Chloroform, uses 71-43-2, Benzene, uses 75-09-2, Dichloromethane, uses 108-88-3, Toluene, uses 110-54-3, Hexane, uses 110-82-7, Cyclohexane, uses

RL: NUU (Other use, unclassified); USES (Uses)

(solvent; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 14243-64-2

RL: PEP (Physical, engineering or chemical process); PROC (Process)

(substrates; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 577-11-7, Sodium bis(2-ethylhexyl) sulfosuccinate 9002-89-5, Polyvinyl alcohol 9002-92-0, Brij 30 9004-98-2, Brij 97 9036-19-5, (Octylphenoxy)polyethoxyethanol 12441-09-7D, Sorbitan, ester derivs. 27251-32-7

RL: MOA (Modifier or additive use); USES (Uses)

(**surfactants**; prepn. of conductive supported noble metal

nanoparticle catalysts)

L15 ANSWER 2 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2007:415891 CAPLUS

DN 146:463862

ED Entered STN: 16 Apr 2007

TI Discoloration prevention of metals using organic ultra-thin films and methods therefor

IN Liang, Chenghao; Yang, Changjiang; Huang, Naibao

PA Dalian Maritime University, Peop. Rep. China

SO Faming Zhuanli Shenqing Gongkai Shuomingshu, 10pp.

CODEN: CNXXEV

DT Patent

LA Chinese

CC 42-10 (Coatings, Inks, and Related Products)

Section cross-reference(s): 46, 56

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	CN 1943882	A	20070411	CN 2006-10134093	20061026
PRAI	CN 2006-10134093		20061026		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
CN 1943882	IPCI	B05D0007-14 [I,A]; B05D0007-24 [I,A]; B05D0003-10 [I,A]; C23C0022-05 [I,A]; C07C0321-04 [I,A]; C07C0321-00 [I,C*]
	IPCR	B05D0007-14 [I,C]; B05D0007-14 [I,A]

OS MARPAT 146:463862

AB Film-forming solns. contain 0.001-1 mol/L alkyl thiols and 0.001-1 mol/L **surfactants**. Thus, a coating soln. on **Ag** contained stearyl thiol 15, polyethylene glycol nonylphenyl ether 7, hexadecyltrimethylammonium bromide 2, Pluronic 64 7 g/L.

ST metal discoloration prevention coating **surfactant** thiol; **silver** discoloration prevention coating **surfactant** thiol

IT **Surfactants**

(**anionic**; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT **Surfactants**

(cationic; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

## IT Discoloration prevention

(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

## IT Quaternary ammonium compounds, uses

Thiols, uses

RL: TEM (Technical or engineered material use); USES (Uses)

(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

## IT Coating materials

(discoloration-resistant; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

## IT 691397-13-4, Pluronic L 64

RL: TEM (Technical or engineered material use); USES (Uses)

(Pluronic L 64; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT 57-09-0, Hexadecyltrimethylammonium bromide **2885-00-9**, Stearylmercaptan 7440-22-4, **Silver**, uses 9016-45-9, Polyethylene glycol nonylphenyl ether

## STN Columbus

RL: TEM (Technical or engineered material use); USES (Uses)  
 (coating materials contg. thiols and **surfactants** for  
 discoloration prevention of metals)

L15 ANSWER 3 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

## Full Text

AN 2007:150387 CAPLUS  
 DN 146:236227  
 ED Entered STN: 09 Feb 2007  
 TI Conductive adhesive composition comprising pressure sensitive adhesive and electrolyte  
 IN Menon, Vinod P.; Kumar, Kanta; Nelson, Carl T.; Rizzardi, Don A.  
 PA 3M Innovative Properties Company, USA  
 SO U.S. Pat. Appl. Publ., 20pp.  
 CODEN: USXXCO  
 DT Patent  
 LA English  
 INCL 600391000; 600392000; 252500000  
 CC 63-7 (Pharmaceuticals)  
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 20070032719	A1	20070208	US 2005-197216	20050804
	AU 2006278717	A1	20070215	AU 2006-278717	20060801
	CA 2617273	A1	20070215	CA 2006-2617273	20060801
	WO 2007019115	A1	20070215	WO 2006-US29794	20060801
	W:			AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW	
	RW:			AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM	
	EP 1917318	A1	20080507	EP 2006-789019	20060801
	R:			AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LI, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR	
	JP 2009503235	T	20090129	JP 2008-525088	20060801
	MX 2008001425	A	20080416	MX 2008-1425	20080129
	KR 2008040689	A	20080508	KR 2008-702725	20080201
	CN 101238189	A	20080806	CN 2006-80028822	20080204
	IN 2008CN00571	A	20081128	IN 2008-CN571	20080204
PRAI	US 2005-197216	A	20050804		
	WO 2006-US29794	W	20060801		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 20070032719	INCL	600391000; 600392000; 252500000
	IPCI	A61B0005-04 [I,A]; H01B0001-12 [I,A]; H01B0001-00 [I,A]
	IPCR	A61B0005-04 [I,C]; A61B0005-04 [I,A]; H01B0001-00 [I,C]; H01B0001-00 [I,A]; H01B0001-12 [I,C]; H01B0001-12 [I,A]
	NCL	600/391.000; 252/500.000; 600/392.000
	ECLA	C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4; C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L
AU 2006278717	IPCI	C09J0009-00 [I,C]; C09J0009-02 [I,A]



## STN Columbus

	IPCR	C09J0009-00 [I,C]; C09J0009-02 [I,A]
	ECLA	C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4; C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L
CA 2617273	IPCI	A61B0005-0408 [I,A]; A61B0018-14 [I,A]; A61K0050-00 [I,A]; A61N0001-04 [I,A]; C09J0009-02 [I,A]; C09J0009-00 [I,C*]; C09J0011-06 [I,A]; C09J0011-02 [I,C*]
	IPCR	C09J0009-00 [I,C]; C09J0009-02 [I,A]; A61B0005-0408 [I,C]; A61B0005-0408 [I,A]; A61B0018-14 [I,C]; A61B0018-14 [I,A]; A61K0050-00 [I,C]; A61K0050-00 [I,A]; A61N0001-04 [I,C]; A61N0001-04 [I,A]; C09J0011-02 [I,C]; C09J0011-06 [I,A]
WO 2007019115	IPCI	C09J0009-02 [I,A]; C09J0009-00 [I,C*]
	IPCR	C09J0009-00 [I,C]; C09J0009-02 [I,A]
	ECLA	C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4; C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L
EP 1917318	IPCI	C09J0009-02 [I,A]; C09J0009-00 [I,C*]
	IPCR	C09J0009-00 [I,C]; C09J0009-02 [I,A]
JP 2009503235	IPCI	C09J0201-00 [I,A]; C09J0009-02 [I,A]; C09J0009-00 [I,C*]; C09J0004-02 [I,A]; A61L0024-00 [I,A]; A61N0001-04 [I,A]
	FTERM	4C053/BB04; 4C053/BB06; 4C053/BB07; 4C053/BB23; 4C053/BB35; 4C053/BB36; 4C081/AA10; 4C081/AA12; 4C081/AC04; 4C081/BB03; 4C081/BB04; 4C081/CA061; 4C081/CA071; 4C081/CA081; 4C081/CA101; 4C081/CA16; 4C081/CA181; 4C081/CA211; 4C081/CA281; 4C081/CE07; 4C081/CE09; 4C081/CE10; 4C081/DA02; 4C081/DA12; 4C081/DB07; 4C081/DC03; 4C081/DC04; 4J040/FA041; 4J040/FA081; 4J040/FA091; 4J040/FA101; 4J040/FA131; 4J040/FA141; 4J040/FA161; 4J040/FA281; 4J040/FA291; 4J040/HB04; 4J040/HB10; 4J040/HB11; 4J040/HB14; 4J040/HC01; 4J040/HD02; 4J040/HD18; 4J040/HD23; 4J040/JA03; 4J040/JB09; 4J040/KA12; 4J040/KA13; 4J040/KA32; 4J040/KA38; 4J040/KA39; 4J040/MA14; 4J040/NA02
MX 2008001425	IPCI	C09J0009-02 [I,A]; C09J0009-00 [I,C*]
KR 2008040689	IPCI	C09J0009-02 [I,A]; C09J0009-00 [I,C*]
CN 101238189	IPCI	C09J0009-02 [I,A]; C09J0009-00 [I,C*]
IN 2008CN00571	IPCI	C09J0009-02 [ICM,7]; C09J0009-00 [ICM,7,C*]

OS MARPAT 146:236227

AB A conductive adhesive compn. is provided and articles that include the adhesive compn. as a component thereof. The conductive adhesive compn. comprises: (a) pressure sensitive adhesive; (b) electrolyte comprising water sol. or water dispersible org. chloride; and (c) humectant. In some embodiments, the conductive adhesive compn. is a bicontinuous compn. comprising an aq. phase and an oil phase, and the bicontinuous compn. may be derived from a polymerizable microemulsion compn., the microemulsion compn. comprising: an aq. phase comprising one or more hydrophilic monomers or oligomers and/or one or more amphiphilic monomers or oligomers in water, the water-sol. or water-dispersible org. chloride, **surfactant** and humectant; and an oil phase comprising one or more hydrophobic monomers or oligomers. Biomedical articles such as biomedical electrodes, may incorporate the foregoing adhesive as a component. For example, adhesive precursor comprised of acrylic acid 15 g, 2-hydroxyethyl methacrylate 20 g, tetrakis(hydroxymethyl)phosphonium chloride 11 g, 1,3-butylene glycol 25 g, glycerol 10 g, water 19 g, Irgacure 2959 0.55 g and polyethylene glycol diacrylate 0.15 g. The precursor was coated using a knife coater onto a release liner as substrate. The knife was set so that a 25 mil (0.64 mm) thick coating was obtained. Polymn. was induced in the coated microemulsion by exposure to UV radiation. A total dose of

1800 mJ/cm<sup>2</sup> was applied over approx. 7 min, forming a conductive, bicontinuous adhesive. This conductive adhesive had an excellent adhesion to human skin.

- ST polymer acrylate electrolyte chloride conductive adhesive
- IT Polyurethanes, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (acrylates; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Electric conductors  
 (adhesive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fats and Glyceridic oils, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (almond, amidopropalkonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT **Surfactants**  
 (anionic; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fats and Glyceridic oils, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (avocado, amidopropalkonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT **Surfactants**  
 (cationic; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Onium compounds  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Quaternary ammonium compounds, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (chlorides; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fatty acids, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (coco, trimethylammonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Chain transfer agents  
 Crosslinking agents  
 Electrodes  
 Electrolytes  
 Human  
 Humectants  
 Hydrogels  
**Surfactants**  
 (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Alcohols, uses  
 Thiols, uses  
 RL: NUU (Other use, unclassified); USES (Uses)  
 (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Acrylic polymers, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Sulfonium compounds  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

- IT Adhesives  
(conductive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Soybean oil  
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(dimethylammonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT **Surfactants**  
(**nonionic**; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Chlorides, biological studies  
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(org.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Adhesives  
(pressure-sensitive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fatty acids, biological studies  
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(tallow, bishydroxyethyl/dime quaternary ammonium compds.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 558-13-4, Carbon tetrabromide 25103-09-7, Isooctyl **thioglycolate**  
, uses  
RL: NUU (Other use, unclassified); USES (Uses)  
(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 1070-70-8, 1,4-Butanediol diacrylate 1321-74-0, Divinylbenzene, reactions 10526-04-2, 1,8-Octanediol diacrylate 13048-33-4, 1,6-Hexanediol diacrylate  
RL: RCT (Reactant); RACT (Reactant or reagent)  
(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 56-34-8, Tetraethylammonium chloride 56-37-1, Benzyltriethylammonium chloride 56-81-5, Glycerin, biological studies 56-93-9, Benzyltrimethylammonium chloride 57-55-6, Propylene glycol, biological studies 67-48-1 77-99-6, Trimethylolpropane 88-12-0D, polymer 107-21-1, Ethylene glycol, biological studies 107-88-0, 1,3-Butanediol 110-63-4, 1,4-Butanediol, biological studies 112-00-5, Dodecyltrimethylammonium chloride 112-02-7, Hexadecyltrimethylammonium chloride 112-03-8, Octadecyltrimethylammonium chloride 124-64-1, Tetrakis(hydroxymethyl)phosphonium chloride 139-08-2, Tetradecyldimethylbenzylammonium chloride 593-81-7D, Trimethylammonium chloride, coco fatty acid derivs. 7173-51-5 9004-98-2, Brij 98 9042-76-6 17301-53-0, Behenyltrimethylammonium chloride 24567-53-1, Phosphonium chloride 25265-71-8, Dipropylene glycol 26570-48-9, Polyethylene oxide diacrylate 26597-36-4 32862-91-2, Oxonium chloride 60182-11-8, Polyethylene glycol acrylate 93507-51-8 106797-53-9, IRGACURE 2959 123776-56-7 145687-02-1, Pemulen TR 2 463965-14-2 923929-97-9 923929-99-1 924299-17-2, Hetoxol OL 35  
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 7783-90-6, **Silver** chloride, biological studies  
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(conductive ink soln.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

## STN Columbus

DN 143:351549  
 ED Entered STN: 05 Oct 2005  
 TI Water-based sulfur-containing composition chemical mechanical polishing of nonferrous metals  
 IN Johns, Peter Gamon; Harrison, Clare Elizabeth  
 PA Middlesex Silver Co. Limited, UK  
 SO Brit. UK Pat. Appl., 29 pp.  
 CODEN: BAXXDU  
 DT Patent  
 LA English  
 IC ICM C23F011-16  
 ICS C23F011-00  
 CC 57-7 (Ceramics)  
 Section cross-reference(s): 56

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	GB 2412666	A	20051005	GB 2004-7163	20040330
	GB 2412666	B	20081008		
	AU 2005229275	A1	20051013	AU 2005-229275	20050324
	CA 2559989	A1	20051013	CA 2005-2559989	20050324
	WO 2005095675	A1	20051013	WO 2005-GB50043	20050324
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW				
	RW: BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG				
	EP 1730325	A1	20061213	EP 2005-718135	20050324
	R: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LI, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR				
	CN 1946878	A	20070411	CN 2005-80013434	20050324
	JP 2007537354	T	20071220	JP 2007-505641	20050324
	IN 2006DN05356	A	20070713	IN 2006-DN5356	20060915
	MX 2006010964	A	20061116	MX 2006-10964	20060925
	US 20070277906	A1	20071206	US 2007-594477	20070702
PRAI	GB 2004-7163	A	20040330		
	WO 2005-GB50043	W	20050324		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
GB 2412666	ICM	C23F011-16
	ICS	C23F011-00
	IPCI	C23F0011-10 [I,C]; C23F0011-16 [I,A]; C23F0011-00 [I,C]; C23F0011-00 [I,A]
	IPCR	C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]
	ECLA	C23F011/16; C23F011/16B
AU 2005229275	IPCI	C11D0003-00 [I,C*]; C09G0001-00 [I,C*]; C11D0003-34 [I,C*]; C11D0011-00 [I,C*]; C23F0011-10 [I,C*]; C11D0003-00 [I,A]; C09G0001-02 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C23F0011-16 [I,A]
	IPCR	C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C09G0001-00

## STN Columbus

		[I,C*]; C09G0001-02 [I,A]; C11D0003-34 [I,C*];
		C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00
		[I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A]
CA 2559989	ECLA	C23F011/16; C23F011/16B
	IPCI	C09G0001-02 [I,A]; C09G0001-00 [I,C*]; C11D0003-00
		[I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A];
		C23F0011-16 [I,A]; C23F0011-10 [I,C*]
	IPCR	C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00
		[I,C]; C09G0001-02 [I,A]; C11D0003-00 [I,C];
		C11D0003-00 [I,A]; C11D0003-34 [I,C]; C11D0003-34
		[I,A]; C11D0011-00 [I,C]; C11D0011-00 [I,A]
	ECLA	C23F011/16; C23F011/16B
WO 2005095675	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*];
		C11D0003-00 [ICS,7]; C11D0003-34 [ICS,7]; C11D0011-00
		[ICS,7]; C09G0001-02 [ICS,7]; C09G0001-00 [ICS,7,C*]
	IPCR	C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00
		[I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*];
		C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00
		[I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
EP 1730325	IPCI	C23F0011-16 [I,A]; C23F0011-10 [I,C*]; C11D0003-00
		[I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A];
		C09G0001-02 [I,A]; C09G0001-00 [I,C*]
	IPCR	C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00
		[I,C]; C09G0001-02 [I,A]; C11D0003-00 [I,C];
		C11D0003-00 [I,A]; C11D0003-34 [I,C]; C11D0003-34
		[I,A]; C11D0011-00 [I,C]; C11D0011-00 [I,A]
	ECLA	C23F011/16; C23F011/16B
CN 1946878	IPCI	C23F0011-16 [I,A]; C23F0011-10 [I,C*]; C11D0003-00
		[I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A];
		C09G0001-02 [I,A]; C09G0001-00 [I,C*]
	IPCR	C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00
		[I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*];
		C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34
		[I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]
	ECLA	C23F011/16; C23F011/16B
JP 2007537354	IPCI	C23C0022-58 [I,A]; C11D0003-34 [I,A]; C23C0022-68
		[I,A]; C23C0022-05 [I,C*]; C11D0003-20 [I,A];
		C11D0001-52 [I,A]; C11D0001-38 [I,C*]; C11D0001-72
		[I,A]; C11D0001-79 [I,A]; C11D0001-755 [I,A];
		C11D0001-75 [I,A]; C11D0001-722 [I,A]; C11D0001-14
		[I,A]; C11D0001-02 [I,C*]; C11D0001-90 [I,A];
		C11D0001-88 [I,C*]; C11D0003-04 [I,A]; C11D0001-68
		[I,A]; C09K0003-14 [I,A]
	IPCR	C23C0022-05 [I,C]; C23C0022-58 [I,A]; C09G0001-00
		[I,C*]; C09G0001-02 [I,A]; C09K0003-14 [I,C];
		C09K0003-14 [I,A]; C11D0001-02 [I,C]; C11D0001-14
		[I,A]; C11D0001-38 [I,C]; C11D0001-52 [I,A];
		C11D0001-68 [I,C]; C11D0001-68 [I,A]; C11D0001-72
		[I,C]; C11D0001-72 [I,A]; C11D0001-722 [I,C];
		C11D0001-722 [I,A]; C11D0001-75 [I,C]; C11D0001-75
		[I,A]; C11D0001-755 [I,C]; C11D0001-755 [I,A];
		C11D0001-79 [I,C]; C11D0001-79 [I,A]; C11D0001-88
		[I,C]; C11D0001-90 [I,A]; C11D0003-00 [I,C*];
		C11D0003-00 [I,A]; C11D0003-04 [I,C]; C11D0003-04
		[I,A]; C11D0003-20 [I,C]; C11D0003-20 [I,A];
		C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00
		[I,C*]; C11D0011-00 [I,A]; C23C0022-68 [I,A];
		C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	FTERM	4H003/AB27; 4H003/AC02; 4H003/AC10; 4H003/AC13;

## STN Columbus

4H003/AD04; 4H003/BA12; 4H003/DA15; 4H003/EA12;  
 4H003/EA19; 4H003/EB05; 4H003/EB18; 4H003/EB21;  
 4H003/ED02; 4H003/FA05; 4K026/AA01; 4K026/AA06;  
 4K026/CA15; 4K026/CA37; 4K026/DA02; 4K026/DA03  
 IN 2006DN05356 IPCI C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C\*]  
 MX 2006010964 IPCI C09G0001-02 [ICM,7]; C09G0001-00 [ICM,7,C\*];  
 C11D0011-00 [ICS,7]; C11D0003-00 [ICS,7]; C11D0003-34  
 [ICS,7]; C23F0011-16 [ICS,7]; C23F0011-10 [ICS,7,C\*]  
 US 20070277906 IPCI C23F0011-16 [I,A]; C23F0011-10 [I,C\*]; C09G0001-02  
 [I,A]; C09G0001-00 [I,C\*]; C11D0011-00 [I,A];  
 C11D0003-00 [I,A]; C11D0003-34 [I,A]  
 NCL 148/022.000  
 OS MARPAT 143:351549  
 AB A compn. and assocd. method of manuf. of a water based compn. comprising a  
 treatment agent selected from an alkanethiol, alkyl thioglycollate, and  
 dialkyl sulfide or dialkyl disulfide. The compn. also includes at least  
 one of an amphoteric, **non-ionic** or cationic **surfactant**, where the  
 treatment agent is directly dissolved or dispersed the water contg. the  
 amphoteric, **non-ionic** or cationic **surfactant**. The compn. is  
 particularly useful for the treatment of **Ag**-Cu-Ge alloy, copper, brass,  
 and nickel. A solid polishing medium can also be included in the compn.,  
 for example, silica or pptd. chalk, alumina, or silica.  
 ST chalk alumina silica alkanethiol thioglycollate chem mech polishing copper  
 IT Thiols, processes  
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical  
 process); TEM (Technical or engineered material use); PROC (Process); USES  
 (Uses)  
 (alkanethiol; water-based sulfur-contg. compn. chem. mech. polishing of  
 metals)  
 IT Disulfides  
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical  
 process); TEM (Technical or engineered material use); PROC (Process); USES  
 (Uses)  
 (alkyl; water-based sulfur-contg. compn. chem. mech. polishing of  
 metals)  
 IT Chalk  
 Diatomite  
 RL: TEM (Technical or engineered material use); USES (Uses)  
 (as abrasive; water-based sulfur-contg. compn. chem. mech. polishing of  
 metals)  
 IT **Surfactants**  
 (cationic; water-based sulfur-contg. compn. chem. mech. polishing of  
 metals)  
 IT Polishing  
 (chem.-mech.; water-based sulfur-contg. compn. chem. mech. polishing of  
 metals)  
 IT Polishing materials  
 (paste; water-based sulfur-contg. compn. chem. mech. polishing of  
 metals)  
 IT Thioethers  
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical  
 process); TEM (Technical or engineered material use); PROC (Process); USES  
 (Uses)  
 (water-based sulfur-contg. compn. chem. mech. polishing of metals)  
 IT 1344-28-1, Alumina, uses  
 RL: TEM (Technical or engineered material use); USES (Uses)  
 (abrasive; water-based sulfur-contg. compn. chem. mech. polishing of  
 metals)  
 IT 9004-82-4, Sodium laureth sulfate  
 RL: MOA (Modifier or additive use); USES (Uses)

- (**anionic surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 7631-86-9, Silica, uses  
RL: TEM (Technical or engineered material use); USES (Uses)  
(as abrasive; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 36574-66-0D, N-coco acyl derivs.  
RL: MOA (Modifier or additive use); USES (Uses)  
(cocamidopropyl betaine, **surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 7440-02-0, Nickel, processes 7440-50-8, Copper, processes 11144-43-7  
12597-71-6, Brass, processes 74969-69-0  
RL: PEP (Physical, engineering or chemical process); PYP (Physical process); PROC (Process)  
(polished substrate; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 62-56-6, Thiourea, uses **2885-00-9**, Octadecyl **mercaptan**  
RL: TEM (Technical or engineered material use); USES (Uses)  
(polishing compn. component; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT **2917-26-2**, Hexadecyl **mercaptan**  
RL: MOA (Modifier or additive use); USES (Uses)  
(**surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 68-11-1D, alkyl esters  
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)  
(water-based sulfur-contg. compn. chem. mech. polishing of metals)

RE.CNT 6 THERE ARE 6 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Anon; EP 0492487 A1 CAPLUS
- (2) Anon; GB 0956927 A
- (3) Anon; GB 1117510 A
- (4) Anon; US 3503883 A
- (5) Anon; US 3518098 A
- (6) Anon; US 5650385 A CAPLUS

L15 ANSWER 5 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2005:622423 CAPLUS  
DN 143:295501  
ED Entered STN: 19 Jul 2005  
TI Single Etch Patterning of Stacked **Silver** and Molybdenum Alloy Layers on Glass Using Microcontact Wave Printing  
AU Burdinski, Dirk; Brans, Harold J. A.; Decre, Michel M. J.  
CS Philips Research, Eindhoven, 5656 AA, Neth.  
SO Journal of the American Chemical Society (2005), 127(31), 10786-10787  
CODEN: JACSAT; ISSN: 0002-7863  
PB American Chemical Society  
DT Journal  
LA English  
CC 74-13 (Radiation Chemistry, Photochemistry, and Photographic and Other Reprographic Processes)  
Section cross-reference(s): 56  
AB Stacked thin layers of **silver** alloy (AgPdCu) and MoCr layers on 10  
× 15 cm<sup>2</sup> glass substrates were patterned by microcontact wave printing and etching. Patterns of etch-resistant **octadecanethiol** self-assembled monolayers (SAMs) were wave printed with regular backplane

stabilized PDMS stamps. Pattern development was achieved by etching both metal layers in a single step, employing a nitric acid-based etching bath. Trifluoroacetic acid and a nitrite salt were identified as essential bath components for a homogeneous etching process. Etch defects could be eliminated by the addn. of a decanesulfonate, which stabilizes the SAM resist via a defect healing mechanism.

- ST etching **silver** molybdenum alloy electrode display
- IT Liquid crystal displays  
(active matrix; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing as electrodes for)
- IT **Surfactants**  
(**anionic**; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT Lithography  
(microcontact printing; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT Autocatalysis  
Electrodes  
Etching  
Glass substrates  
Self-assembled monolayers  
(single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT 64-19-7, Acetic acid, processes 76-05-1, Trifluoroacetic acid, processes 7632-00-0, Sodium nitrite 7664-38-2, Phosphoric acid, processes 7697-37-2, Nitric acid, processes  
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)  
(etchant; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT 2885-00-9, 1-Octadecanethiol  
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)  
(ink, self-assembled monolayer; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT 188820-19-1 317855-00-8  
RL: CPS (Chemical process); DEV (Device component use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)  
(single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT 13419-61-9, Sodium decane sulfonate  
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)  
(**surfactant** for etching soln.; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

RE.CNT 31 THERE ARE 31 CITED REFERENCES AVAILABLE FOR THIS RECORD

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- (6) Creager, S; Langmuir 1993, V9, P2330 CAPLUS
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L15 ANSWER 6 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2004:847649 CAPLUS  
 DN 141:353637  
 ED Entered STN: 15 Oct 2004  
 TI Pretreatment of **Ag**-alloy surface with organosulfur compounds for  
 tarnishing prevention  
 IN Johns, Peter Gammon; Harrison, Clare Elizabeth  
 PA Middlesex Silver Co. Limited, UK  
 SO PCT Int. Appl., 43 pp.  
 CODEN: PIXXD2  
 DT Patent  
 LA English  
 IC ICM C23F011-16  
 CC 56-6 (Nonferrous Metals and Alloys)

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2004087996	A1	20041014	WO 2004-GB1373	20040330
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW				
	RW: BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG				
	AU 2004225693	A1	20041014	AU 2004-225693	20040330
	CA 2520807	A1	20041014	CA 2004-2520807	20040330
	EP 1611267	A1	20060104	EP 2004-724313	20040330
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, PL, SK				
	CN 1780937	A	20060531	CN 2004-80011375	20040330

## STN Columbus

JP 2006523266	T	20061012	JP 2006-506057	20040330
IN 2005DN04346	A	20070831	IN 2005-DN4346	20050926
MX 2005010452	A	20060510	MX 2005-10452	20050928
US 20070039665	A1	20070222	US 2005-551476	20050929
PRAI GB 2003-7290	A	20030331		
WO 2004-GB1373	W	20040330		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
WO 2004087996	ICM	C23F011-16
	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
AU 2004225693	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
CA 2520807	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
EP 1611267	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
CN 1780937	IPCI	C23F0011-16 [I,A]; C23F0011-10 [I,C*]
	ECLA	C23F011/16; C23F011/16B
JP 2006523266	IPCI	C23F0011-00 [I,A]; C22C0005-06 [I,A]; C22C0005-08 [I,A]
	IPCR	C23F0011-00 [I,C]; C23F0011-00 [I,A]; C22C0005-06 [I,C]; C22C0005-06 [I,A]; C22C0005-08 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	FTERM	4K062/AA01; 4K062/BB21; 4K062/BC22; 4K062/FA16
IN 2005DN04346	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
MX 2005010452	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
	ECLA	C23F011/16; C23F011/16B
US 20070039665	IPCI	C23G0001-00 [I,A]; C23C0022-58 [I,A]; C23C0022-05 [I,C*]
	NCL	148/271.000; 134/002.000
AB	The <b>Ag</b> alloys contg. minor Ge (esp. <b>Ag</b> -Cu-Ge alloys) to decrease the fire stain discoloration are pretreated on the surface with an alkanethiol, alkyl thioglycollate, dialkyl sulfide, or dialkyl disulfide to prevent tarnishing. The treatment with organosulfur compds. is suitable for manufd. <b>Ag</b> -alloy articles to prevent tarnished appearance during transit and the subsequent extended display without special packaging. The <b>Ag</b> -alloy surface is optionally treated with aq. soln. contg. an alkanethiol, alkyl thioglycollate, dialkyl sulfide, or dialkyl disulfide, as well as a mixt. of <b>anionic surfactant</b> and amphoteric or <b>nonionic surfactant</b> to solubilize the treatment agent. The typical ternary alloy contains <b>Ag</b> 80-96, Cu 1-19.9, and Ge 0.1-5%.	
ST	<b>silver</b> copper germanium alloy tarnishing prevention organosulfur	
IT	<b>Surfactants</b>	
	(anionic, in tarnishing prevention; <b>Ag</b> -alloy surface treated with organosulfur compds. for tarnishing prevention)	
IT	<b>Surfactants</b>	
	(in tarnishing prevention; <b>Ag</b> -alloy surface treated with organosulfur compds. for tarnishing prevention)	
IT	<b>Surfactants</b>	
	(nonionic, in tarnishing prevention; <b>Ag</b> -alloy surface treated with organosulfur compds. for tarnishing prevention)	
IT	Tarnishing	
	(prevention of; <b>Ag</b> -alloy surface treated with organosulfur compds. for tarnishing prevention)	
IT	Thioethers	

STN Columbus

Thiols, uses

RL: TEM (Technical or engineered material use); USES (Uses)  
(tarnishing prevention by; **Ag**-alloy surface treated with  
organosulfur compds. for tarnishing prevention)

IT 7440-56-4, Germanium, uses

RL: MOA (Modifier or additive use); USES (Uses)  
(**Ag** alloys contg., tarnishing prevention on; **Ag**  
-alloy surface treated with organosulfur compds. for tarnishing  
prevention)

IT 106-94-5, n-Propyl bromide

RL: TEM (Technical or engineered material use); USES (Uses)  
(solvent, in tarnishing prevention; **Ag**-alloy surface treated  
with organosulfur compds. for tarnishing prevention)

IT 2885-00-9, Octadecyl mercaptan 2917-26-2,

Cetyl mercaptan

RL: CPS (Chemical process); PEP (Physical, engineering or chemical  
process); PROC (Process)  
(tarnishing prevention by; **Ag**-alloy surface treated with  
organosulfur compds. for tarnishing prevention)

IT 39282-03-6, Sterling **silver** 103221-24-5 476614-10-5  
476614-12-7 476614-13-8

RL: CPS (Chemical process); PEP (Physical, engineering or chemical  
process); PROC (Process)  
(tarnishing prevention on; **Ag**-alloy surface treated with  
organosulfur compds. for tarnishing prevention)

IT 9080-17-5, Ammonium polysulfide

RL: CPS (Chemical process); PEP (Physical, engineering or chemical  
process); PROC (Process)  
(test soln. with, for tarnishing; **Ag**-alloy surface treated  
with organosulfur compds. for tarnishing prevention)

RE.CNT 9 THERE ARE 9 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Carlton, C; US 3503883 A 1970
- (2) Carpenter, J; US 3398003 A 1968 CAPLUS
- (3) Gamon, J; EP 0729398 A 1996 CAPLUS
- (4) Gamon, J; WO 02095082 A 2002 CAPLUS
- (5) Goddard & Sons Ltd J; GB 1070384 A 1967 CAPLUS
- (6) Goddard & Sons Ltd J; GB 1130540 A 1968
- (7) Han, S; JOURNAL OF THE AMERICAN CHEMICAL SOCIETY 2001, V123, P2422 CAPLUS
- (8) Metaleurop Rech; GB 2255348 A 1992 CAPLUS
- (9) Nippon Germanium Lab Co Ltd; EP 1130124 A 2001 CAPLUS

L15 ANSWER 7 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:851241 CAPLUS

DN 139:330251

ED Entered STN: 30 Oct 2003

TI **Silver** (carboxylate-n-alkyl thiolate) particles for photothermographic  
of thermographic imaging

IN Ghyzel, Peter J.; Lelental, Mark; Dickinson, David A.; Pitt, Alan R.;  
Wear, Trevor J.

PA Eastman Kodak Company, USA

SO U.S., 14 pp.

CODEN: USXXAM

DT Patent

LA English

IC ICM G03C001-498

INCL 430619000; 430611000; 430620000; 430631000

CC 74-2 (Radiation Chemistry, Photochemistry, and Photographic and Other  
Reprographic Processes)

## STN Columbus

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 6638708	B1	20031028	US 2002-200417	20020722
	EP 1385047	A1	20040128	EP 2003-77179	20030710
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK				
	JP 2004054276	A	20040219	JP 2003-199297	20030718
PRAI	US 2002-200417	A	20020722		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 6638708	ICM	G03C001-498
	INCL	430619000; 430611000; 430620000; 430631000
	IPCI	G03C0001-498 [ICM, 7]
	IPCR	B41M0005-30 [I,C*]; B41M0005-323 [I,A]; G03C0001-498 [I,C*]; G03C0001-498 [I,A]
	NCL	430/619.000; 430/611.000; 430/620.000; 430/631.000
	ECLA	G03C001/498B; G03C001/498E1
EP 1385047	IPCI	G03C0001-498 [ICM, 7]
	IPCR	B41M0005-30 [I,C*]; B41M0005-323 [I,A]; G03C0001-498 [I,C*]; G03C0001-498 [I,A]
	ECLA	G03C001/498B; G03C001/498E1
JP 2004054276	IPCI	G03C0001-498 [ICM, 7]; B41M0005-30 [ICS, 7]
	IPCR	G03C0001-498 [I,A]; G03C0001-498 [I,C*]
	FTERM	2H026/AA07; 2H026/BB46; 2H123/AB00; 2H123/AB03; 2H123/AB25; 2H123/AB28; 2H123/BC00; 2H123/BC12; 2H123/CB00; 2H123/CB03

AB The present disclosure relates to dispersions of **silver** (carboxylate-n-alkyl thiolate). The carboxylates are typically **silver** salts of long chain fatty acids and the n-alkyl thiolate is preferably 1-dodecanethiol. These **silver** (carboxylate-n-alkyl thiolate) particles can be used to formulate imaging forming compns. that are useful in aq. thermog. or photothermog. imaging elements.

ST photog emulsion **silver** carboxylate alkyl thiolate particle photothermog

IT Photographic emulsions  
(heat-developable; **silver** (carboxylate-n-alkyl thiolate)  
particles for photothermog. of thermog. imaging)

IT **Surfactants**  
(**nonionic**; **silver** (carboxylate-n-alkyl thiolate)  
particles for photothermog. of thermog. imaging)

IT Nanoparticles  
(**silver** (carboxylate-n-alkyl thiolate) particles for  
photothermog. of thermog. imaging)

IT 111-31-9, 1-Hexanethiol 112-55-0, 1-Dodecanethiol 112-85-6, Behenic acid **2885-00-9**, 1-Octadecanethiol

RL: TEM (Technical or engineered material use); USES (Uses)  
(**silver** (carboxylate-n-alkyl thiolate) particles for  
photothermog. of thermog. imaging)

RE.CNT 5 THERE ARE 5 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Anon; EP 0803764 A1 2001 CAPLUS
- (2) Goffe; US 3666477 A 1972 CAPLUS
- (3) Lelental; US 6391537 B2 2002 CAPLUS
- (4) Voicu, R; Structure and Dynamics of Selectively Deuterated Self-Assembled Silver n-Octadecanethiolate Layered Materials P2266
- (5) Voicu, R; Thermal Behavior of a Self-Assembled Silver n-Dodecanethiolate Layered Material Monitored by DSC P2642

## STN Columbus

Full Text

AN 2003:798402 CAPLUS  
 DN 139:311931  
 ED Entered STN: 12 Oct 2003  
 TI Metal coating of hair fibers for cosmetics  
 IN Vic, Gabin; Livoreil, Aude; Giroud, Franck  
 PA L'oreal, Fr.  
 SO Fr. Demande, 18 pp.  
 CODEN: FRXXBL  
 DT Patent  
 LA French  
 IC ICM A61K007-075  
 CC 62-3 (Essential Oils and Cosmetics)  
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	FR 2838050	A1	20031010	FR 2002-4352	20020408
	FR 2838050	B1	20060714		
	CN 1449737	A	20031022	CN 2003-108449	20030331
	CN 1213719	C	20050810		
	BR 2003000873	A	20040817	BR 2003-873	20030403
	EP 1352630	A2	20031015	EP 2003-290860	20030407
	EP 1352630	A3	20040324		
	EP 1352630	B1	20060301		
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK				
	US 20030223944	A1	20031204	US 2003-407911	20030407
	JP 2003300840	A	20031021	JP 2003-104420	20030408
	JP 3759120	B2	20060322		
PRAI	FR 2002-4352	A	20020408		
	US 2002-372455P	P	20020416		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
FR 2838050	ICM	A61K007-075
	IPCI	A61K0007-075 [ICM, 7]
	IPCR	A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
	ECLA	A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10
CN 1449737	IPCI	A61K0007-06 [ICM, 7]; A61K0007-06 [ICS, 7]
	IPCR	A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02

## STN Columbus

[I,C\*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C\*];  
A61Q0005-00 [I,A]; A61Q0005-10 [I,C\*]; A61Q0005-10  
[I,A]; A61Q0005-12 [I,C\*]; A61Q0005-12 [I,A]  
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;  
A61Q005/00; A61Q005/10  
BR 2003000873 IPCI A61K0007-06 [ICM,7]  
IPCR A61K0008-00 [I,C\*]; A61K0008-00 [I,A]; A61K0008-18  
[I,C\*]; A61K0008-18 [I,A]; A61K0008-19 [I,C\*];  
A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23  
[I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A];  
A61K0008-27 [I,A]; A61K0008-30 [I,C\*]; A61K0008-31  
[I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A];  
A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64  
[I,A]; A61K0008-72 [I,C\*]; A61K0008-73 [I,A];  
A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02  
[I,C\*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C\*];  
A61Q0005-00 [I,A]; A61Q0005-10 [I,C\*]; A61Q0005-10  
[I,A]; A61Q0005-12 [I,C\*]; A61Q0005-12 [I,A]  
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;  
A61Q005/00; A61Q005/10  
EP 1352630 IPCI A61K0008-19 [I,C]; A61K0008-30 [I,C]; A61Q0005-00  
[I,C]; A61Q0005-10 [I,C]; A61Q0005-10 [I,A];  
A61K0008-19 [I,A]; A61K0008-46 [I,A]; A61Q0005-00 [I,A]  
IPCR A61K0008-00 [I,C\*]; A61K0008-00 [I,A]; A61Q0005-10  
[I,A]; A61K0008-18 [I,C\*]; A61K0008-18 [I,A];  
A61K0008-19 [I,C]; A61K0008-19 [I,A]; A61K0008-20  
[I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A];  
A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30  
[I,C]; A61K0008-31 [I,A]; A61K0008-34 [I,A];  
A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46  
[I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C\*];  
A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891  
[I,A]; A61Q0001-02 [I,C\*]; A61Q0001-02 [I,A];  
A61Q0005-00 [I,C]; A61Q0005-00 [I,A]; A61Q0005-10  
[I,C]; A61Q0005-12 [I,C\*]; A61Q0005-12 [I,A]  
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;  
A61Q005/00; A61Q005/10  
US 20030223944 IPCI A61K0007-075 [ICM,7]; A61K0007-06 [ICS,7]  
IPCR A61K0008-19 [I,C\*]; A61K0008-19 [I,A]; A61K0008-30  
[I,C\*]; A61K0008-46 [I,A]; A61Q0005-12 [I,C\*];  
A61Q0005-12 [I,A]  
NCL 424/070.100; 510/119.000  
ECLA A61K008/19; A61K008/46; A61Q005/12  
JP 2003300840 IPCI A61K0008-00 [I,A]; A61Q0005-00 [I,A]; A61K0008-18  
[I,A]; A61Q0001-02 [I,A]  
IPCR A61K0008-00 [I,C\*]; A61K0008-00 [I,A]; A61K0008-18  
[I,C\*]; A61K0008-18 [I,A]; A61K0008-19 [I,C\*];  
A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23  
[I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A];  
A61K0008-27 [I,A]; A61K0008-30 [I,C\*]; A61K0008-31  
[I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A];  
A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64  
[I,A]; A61K0008-72 [I,C\*]; A61K0008-73 [I,A];  
A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02  
[I,C\*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C\*];  
A61Q0005-00 [I,A]; A61Q0005-10 [I,C\*]; A61Q0005-10  
[I,A]; A61Q0005-12 [I,C\*]; A61Q0005-12 [I,A]  
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;  
A61Q005/00; A61Q005/10

AB The invention relates to a treatment process which confers cosmetic

properties on hair fibers. The process consists of treating the fibers with a metal salt in the presence of a reducing agent, directly on the fiber to form the corresponding free metal. Thus, a lock of hair after being shampooed, was dried and an aq. soln. of AgNO<sub>3</sub> was applied onto the hair. After the addn. of NaBH<sub>4</sub>, the natural pigmented hair was dark, with metallic brilliance reflected on it.

- ST metal salt hair cosmetic
- IT Alcohols, biological studies
  - RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)
  - (C1-4; metal treatment of hair fibers for cosmetics)
- IT Alkanes, biological studies
  - RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)
  - (C5-10; metal treatment of hair fibers for cosmetics)
- IT Polyelectrolytes
  - Surfactants**
  - (amphoteric; metal treatment of hair fibers for cosmetics)
- IT Fats and Glyceridic oils, biological studies
  - RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)
  - (animal; metal treatment of hair fibers for cosmetics)
- IT **Surfactants**
  - (**anionic**; metal treatment of hair fibers for cosmetics)
- IT Polyelectrolytes
  - Surfactants**
  - (cationic; metal treatment of hair fibers for cosmetics)
- IT Cosmetics
  - (emollients; metal treatment of hair fibers for cosmetics)
- IT Sulfates, reactions
  - RL: RCT (Reactant); RACT (Reactant or reagent)
  - (hydrogen; metal treatment of hair fibers for cosmetics)
- IT Antifoaming agents
- Antiperspirants
- Cosmetics
- Hair
- Hair preparations
- Perfumes
- Pigments, nonbiological
- Preservatives
- Reducing agents
- Shampoos
- Sunscreens
- Thickening agents
  - (metal treatment of hair fibers for cosmetics)
- IT Alkaline earth salts
  - Bromates
  - Carbonates, biological studies
  - Disulfides
  - Halides
  - Nitrates, biological studies
  - Paraffin oils
  - Phosphates, biological studies
  - Polymers, biological studies
  - Polysiloxanes, biological studies
  - Proteins
  - Rare earth salts

# STN Columbus

Sulfates, biological studies

Thioethers

Thiosulfates

Transition metal salts

Vitamins

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(metal treatment of hair fibers for cosmetics)

IT Bisulfites

Enzymes, reactions

Sulfites

Thiols, reactions

Thioredoxins

RL: RCT (Reactant); RACT (Reactant or reagent)

(metal treatment of hair fibers for cosmetics)

IT Cosmetics

(moisturizers; metal treatment of hair fibers for cosmetics)

IT **Surfactants**

(**nonionic**; metal treatment of hair fibers for cosmetics)

IT Peroxysulfates

RL: RCT (Reactant); RACT (Reactant or reagent)

(peroxymonosulfates; metal treatment of hair fibers for cosmetics)

IT Alcohols, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(polyhydric; metal treatment of hair fibers for cosmetics)

IT Sulfonic acids, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(salts; metal treatment of hair fibers for cosmetics)

IT Sulfinic acids

Thiols, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(salts; metal treatment of hair fibers for cosmetics)

IT Salts, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(thiol; metal treatment of hair fibers for cosmetics)

IT Lactones

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(thiolactones; metal treatment of hair fibers for cosmetics)

IT Fats and Glyceridic oils, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(vegetable; metal treatment of hair fibers for cosmetics)

IT 64-17-5, Ethanol, biological studies 67-63-0, Isopropanol, biological

studies 67-64-1, Acetone, biological studies 78-93-3, Methyl ethyl

ketone, biological studies 79-20-9, Methyl acetate 110-71-4

123-86-4, Butyl acetate 141-78-6, EtOAc, biological studies

7429-90-5D, Aluminum, salts 7439-89-6D, Iron, salts 7439-98-7D,

Molybdenum, salts 7440-02-0D, Nickel, salts 7440-05-3D, Palladium,

salts 7440-06-4D, Platinum, salts 7440-22-4D, **Silver**, salts

7440-31-5D, Tin, salts 7440-32-6D, Titanium, salts 7440-33-7D,

Tungsten, salts 7440-36-0D, Antimony, salts 7440-50-8D, Copper, salts

7440-57-5D, Gold, salts 7440-66-6D, Zinc, salts 7440-74-6D, Indium,



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salts 7758-89-6, Cuprous chloride 7761-88-8, **Silver** nitrate,  
biological studies 7775-41-9, **Silver** fluoride 7783-89-3,  
**Silver** bromate 7783-90-6, **Silver** chloride, biological  
studies 7783-96-2, **Silver** iodide 7785-23-1, **Silver**  
bromide 7787-70-4, Cuprous bromide 10025-98-6, Dipotassium palladium  
tetrachloride 10294-26-5, **Silver** sulfate 10294-28-7, Gold  
tribromide 16903-35-8 16923-58-3, Disodium hexachloroplatinate  
19045-66-0D, Thiocarbamic acid, salts 73506-93-1, Diethoxyethane  
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
(Uses)

(metal treatment of hair fibers for cosmetics)

IT 50-81-7, Ascorbic acid, reactions 53-57-6, NaDPH 58-68-4, NaDH  
68-11-1, Thioglycolic acid, reactions 77-92-9D, Citric acid, salts  
106-51-4, 2,5-Cyclohexadiene-1,4-dione, reactions 123-31-9,  
Hydroquinone, reactions 280-64-8, 9-BBN 1758-73-2, Formamidinesulfinic  
acid **2885-00-9**, 1-Octadecanethiol 3483-12-3,  
Dithiothreitol 6838-83-1, Diisoamylborane 7772-98-7 7775-14-6  
7803-51-2, Phosphine 13762-51-1 14451-43-5 16853-85-3 16940-66-2  
17836-88-3 25895-60-7, Sodium cyanoborohydride 37318-49-3, Protein  
disulfide isomerase 56553-60-7 131760-67-3 145626-87-5  
RL: RCT (Reactant); RACT (Reactant or reagent)

(metal treatment of hair fibers for cosmetics)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD  
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L15 ANSWER 9 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:737150 CAPLUS

DN 139:250305

ED Entered STN: 19 Sep 2003

TI Invisible patch for the controlled delivery of cosmetic, dermatological,  
and pharmaceutical active ingredients onto the skin

IN Shefer, Adi; Shefer, Samuel

PA USA

SO U.S. Pat. Appl. Publ., 17 pp., Cont.-in-part of U. S. Ser. No. 91,935.  
CODEN: USXXCO

DT Patent

LA English

IC ICM A61K031-715

ICS A61K009-70

INCL 424449000; 514061000

CC 63-6 (Pharmaceuticals)

Section cross-reference(s): 62

FAN.CNT 2

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	US 20030175333	A1	20030918	US 2003-376736	20030228
	US 20030175328	A1	20030918	US 2002-91935	20020306
	CA 2515098	A1	20040916	CA 2004-2515098	20040227

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WO 2004078122	A2	20040916	WO 2004-US6106	20040227
WO 2004078122	A3	20050203		
W:	AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI			
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EP 1603499	A2	20051214	EP 2004-715783	20040227
R:	AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK			
JP 2006519263	T	20060824	JP 2006-508924	20040227
PRAI US 2002-91935	A2	20020306		
US 2003-376736	A	20030228		
WO 2004-US6106	W	20040227		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 20030175333	ICM	A61K031-715
	ICS	A61K009-70
	INCL	424449000; 514061000
	IPCI	A61K0031-715 [I,C*]; A61K0009-70 [ICS,7]
	IPCR	A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61F0013-02 [I,C*]; A61F0013-02 [I,A]; A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-02 [I,C*]; A61K0008-02 [I,A]; A61K0008-11 [I,C*]; A61K0008-11 [I,A]; A61K0008-30 [I,C*]; A61K0008-35 [I,A]; A61K0008-368 [I,A]; A61K0008-44 [I,A]; A61K0008-67 [I,A]; A61K0008-72 [I,C*]; A61K0008-72 [I,A]; A61K0008-73 [I,A]; A61K0008-96 [I,C*]; A61K0008-97 [I,A]; A61K0009-50 [I,C*]; A61K0009-50 [I,A]; A61K0009-51 [I,C*]; A61K0009-51 [I,A]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0031-01 [I,C*]; A61K0031-01 [I,A]; A61K0031-045 [I,C*]; A61K0031-045 [I,A]; A61K0031-047 [I,A]; A61K0031-05 [I,A]; A61K0031-075 [I,C*]; A61K0031-085 [I,A]; A61K0031-121 [I,C*]; A61K0031-121 [I,A]; A61K0031-155 [I,C*]; A61K0031-155 [I,A]; A61K0031-165 [I,C*]; A61K0031-165 [I,A]; A61K0031-345 [I,C*]; A61K0031-345 [I,A]; A61K0031-4453 [I,C*]; A61K0031-4453 [I,A]; A61K0031-545 [I,C*]; A61K0031-545 [I,A]; A61K0031-60 [I,C*]; A61K0031-60 [I,A]; A61K0031-616 [I,A]; A61K0031-65 [I,C*]; A61K0031-65 [I,A]; A61K0031-7042 [I,C*]; A61K0031-7048 [I,A]; A61K0033-00 [I,C*]; A61K0033-00 [I,A]; A61K0033-18 [I,C*]; A61K0033-18 [I,A]; A61K0033-28 [I,C*]; A61K0033-28 [I,A]; A61K0033-38 [I,C*]; A61K0033-38 [I,A]; A61K0036-18 [I,C*]; A61K0036-18 [I,A]; A61K0036-88 [I,C*]; A61K0036-896 [I,A]; A61K0045-00 [I,C*]; A61K0045-00 [I,A]; A61K0047-32 [I,C*]; A61K0047-32 [I,A]; A61K0047-34 [I,C*]; A61K0047-34 [I,A]; A61K0047-36 [I,C*]; A61K0047-36 [I,A]; A61K0047-38 [I,C*]; A61K0047-38 [I,A]; A61K0047-42 [I,C*]; A61K0047-42 [I,A]; A61L0015-16 [I,C*]; A61L0015-44 [I,A]; A61P0017-00 [I,C*]; A61P0017-00 [I,A]; A61P0017-02 [I,A]; A61P0017-10 [I,A]; A61P0017-12 [I,A]; A61P0017-16 [I,A]; A61Q0009-04 [I,C*]; A61Q0009-04 [I,A]; A61Q0017-04 [I,C*]; A61Q0017-04 [I,A]; A61Q0019-00 [I,C*];

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A61Q0019-00 [I,A]; A61Q0019-02 [I,C\*]; A61Q0019-02 [I,A]; A61Q0019-04 [I,C\*]; A61Q0019-04 [I,A];  
 A61Q0019-08 [I,C\*]; A61Q0019-08 [I,A]  
 NCL 424/449.000; 514/061.000  
 ECLA A61K008/02C; A61K008/35; A61K008/368; A61K008/44;  
 A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97;  
 A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00;  
 A61Q019/04; A61Q019/08; K61K  
 US 20030175328 IPCI A61K0009-70 [ICM,7]  
 IPCR A61F0013-00 [I,C\*]; A61F0013-00 [I,A]; A61F0013-02 [I,C\*]; A61F0013-02 [I,A]; A61K0008-00 [I,C\*];  
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 A61K0008-72 [I,C\*]; A61K0008-72 [I,A]; A61K0008-73 [I,A]; A61K0008-96 [I,C\*]; A61K0008-97 [I,A];  
 A61K0009-50 [I,C\*]; A61K0009-50 [I,A]; A61K0009-51 [I,C\*]; A61K0009-51 [I,A]; A61K0009-70 [I,C\*];  
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 A61Q0009-04 [I,C\*]; A61Q0009-04 [I,A]; A61Q0017-04 [I,C\*]; A61Q0017-04 [I,A]; A61Q0019-00 [I,C\*];  
 A61Q0019-00 [I,A]; A61Q0019-02 [I,C\*]; A61Q0019-02 [I,A]; A61Q0019-04 [I,C\*]; A61Q0019-04 [I,A];  
 A61Q0019-08 [I,C\*]; A61Q0019-08 [I,A]  
 NCL 424/449.000  
 ECLA A61K008/02C; A61K008/35; A61K008/368; A61K008/44;  
 A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97;  
 A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00;  
 A61Q019/04; A61Q019/08; K61K  
 CA 2515098 IPCI A61K0009-70 [ICM,7]; A61K0007-00 [ICS,7]; A61K0045-00 [ICS,7]; A61M0037-00 [ICS,7]  
 IPCR A61F0013-00 [I,C\*]; A61F0013-00 [I,A]; A61K [I,S];  
 A61K0009-70 [I,C\*]; A61K0009-70 [I,A]; A61K0045-00 [I,C\*]; A61K0045-00 [I,A]; A61M0037-00 [I,C\*];  
 A61M0037-00 [I,A]  
 WO 2004078122 IPCI A61K [ICM,7]

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EP 1603499	IPCR	A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61K [I,S]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0045-00 [I,C*]; A61K0045-00 [I,A]; A61M0037-00 [I,C*]; A61M0037-00 [I,A]
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	IPCR	A61K0008-02 [I,C]; A61K0008-02 [I,A]; A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61K [I,S]; A61K0008-30 [I,C]; A61K0008-33 [I,A]; A61K0008-34 [I,A]; A61K0008-36 [I,A]; A61K0008-37 [I,A]; A61K0008-41 [I,A]; A61K0008-43 [I,A]; A61K0008-46 [I,A]; A61K0008-49 [I,A]; A61K0008-55 [I,A]; A61K0008-58 [I,A]; A61K0008-60 [I,A]; A61K0008-72 [I,C]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61K0008-84 [I,A]; A61K0008-88 [I,A]; A61K0009-70 [I,C]; A61K0009-70 [I,A]; A61K0045-00 [I,C]; A61K0045-00 [I,A]; A61K0047-10 [I,C]; A61K0047-10 [I,A]; A61K0047-12 [I,C]; A61K0047-12 [I,A]; A61K0047-14 [I,C]; A61K0047-14 [I,A]; A61K0047-16 [I,C]; A61K0047-18 [I,A]; A61K0047-20 [I,C]; A61K0047-20 [I,A]; A61K0047-22 [I,C]; A61K0047-22 [I,A]; A61K0047-24 [I,C]; A61K0047-24 [I,A]; A61K0047-28 [I,C]; A61K0047-28 [I,A]; A61K0047-32 [I,C]; A61K0047-32 [I,A]; A61K0047-34 [I,C]; A61K0047-34 [I,A]; A61K0047-36 [I,C]; A61K0047-36 [I,A]; A61K0047-38 [I,C]; A61K0047-38 [I,A]; A61K0047-42 [I,C]; A61K0047-42 [I,A]; A61M0037-00 [I,C*]; A61M0037-00 [I,A]; A61Q0019-00 [I,C]; A61Q0019-00 [I,A]
	FTERM	4C076/AA72; 4C076/AA95; 4C076/BB31; 4C076/CC01; 4C076/CC03; 4C076/CC04; 4C076/CC18; 4C076/DD03; 4C076/DD04; 4C076/DD07; 4C076/DD08; 4C076/DD09; 4C076/DD13; 4C076/DD17; 4C076/DD38A; 4C076/DD66A; 4C076/EE06A; 4C076/EE10A; 4C076/EE12A; 4C076/EE13A; 4C076/EE17A; 4C076/EE23A; 4C076/EE26A; 4C076/EE27; 4C076/EE30A; 4C076/EE31A; 4C076/EE32A; 4C076/EE38A; 4C076/FF31; 4C076/FF35; 4C083/AA112; 4C083/AB032; 4C083/AC122; 4C083/AC131; 4C083/AC181; 4C083/AC371; 4C083/AC391; 4C083/AC421; 4C083/AC441; 4C083/AC532; 4C083/AC682; 4C083/AC772; 4C083/AC781; 4C083/AC791; 4C083/AD041; 4C083/AD042; 4C083/AD051; 4C083/AD071; 4C083/AD072; 4C083/AD091; 4C083/AD111; 4C083/AD131; 4C083/AD151; 4C083/AD201; 4C083/AD202; 4C083/AD211; 4C083/AD241; 4C083/AD261; 4C083/AD271; 4C083/AD281;

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4C083/AD282; 4C083/AD351; 4C083/AD391; 4C083/AD642;  
 4C083/AD662; 4C083/CC02; 4C083/DD12; 4C083/EE12;  
 4C083/EE13; 4C083/EE14; 4C083/EE16; 4C083/EE22;  
 4C084/AA17; 4C084/MA32; 4C084/MA63; 4C084/NA10;  
 4C084/ZA891

- AB The present invention relates to a patch for controlled topical or transdermal delivery of effective levels of cosmetic, dermatol., and pharmaceutical active ingredients onto the skin, hair follicles, and sebaceous glands, with minimal discomfort and ease of use. The patch can be transparent or clear and comprises a rate-controlling matrix layer. The matrix layer comprises water-sensitive, bioadhesive, film forming polymers, a water sol. oligomer, and a **surfactant**. The cosmetic, dermatol., and pharmaceutical active ingredients are sol. or dispersed in the matrix. The patch becomes tacky when wetted and adheres onto the skin. The adhesive properties of the patch are sufficient to maintain the patch in place on the skin for the recommended treatment period while allowing the patch to be readily removed without causing skin irritation or leaving adhesive residue on the skin. For example, an antibiotic patch contained polyvinyl alc. 50, PVP 1, polysorbate 20 5, Maltrin 180 10, lactitol 5, glycerin 10, and chloramphenicol 0.55%.
- ST patch bioadhesive polymer oligosaccharide **surfactant**; antibiotic patch PVA PVP polysorbate chloramphenicol
- IT Glycosides  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (alkyl polyglycosides; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**  
 (amphoteric; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**  
 (anionic; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**  
 (cationic; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Essential oils  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (clove; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Hair preparations  
 (conditioners; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics  
 (depilatories; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Acne  
 Burn  
 Dandruff  
 Pruritus  
 Rhus diversiloba  
 Rhus toxicodendron  
 (drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Alcohols, biological studies  
 Amides, biological studies  
 Esters, biological studies  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)

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- (ethoxylated; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Hair preparations
  - (growth stimulants; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Vein, disease
  - (hemorrhoid, drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Syrups (sweetening agents)
  - (hydrolyzed starch; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Allergy inhibitors
  - Aloe barbadensis
  - Analgesics
  - Anti-infective agents
  - Anti-inflammatory agents
  - Antibacterial agents
  - Antibiotics
  - Antiemetics
  - Antihistamines
  - Antimicrobial agents
  - Antioxidants
  - Antiperspirants
  - Antitussives
  - Antiviral agents
  - Chelating agents
  - Chemotherapy
  - Cholinergic antagonists
  - Deodorants
  - Disinfectants
  - Fungicides
  - Hemostatics
  - Immunomodulators
  - Insecticides
  - Radical scavengers
  - Sunscreens
  - Suntanning agents
  - Vasoconstrictors
  - Vasodilators
  - Wound healing promoters
    - (invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Amine oxides
  - Amino acids, biological studies
  - Carbohydrates, biological studies
  - Caseins, biological studies
  - Flavonoids
  - Gelatins, biological studies
  - Glycerides, biological studies
  - Lanolin
  - Lecithins
  - Oligosaccharides, biological studies
  - Paraffin oils
  - Peptides, biological studies
  - Polyamides, biological studies
  - Polyesters, biological studies
  - Polyoxyalkylenes, biological studies
  - Polyoxyalkylenes, biological studies
  - Polysaccharides, biological studies
  - Proteins

# STN Columbus

Retinoids

Vitamins

RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);

USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

IT Anesthetics

(local; invisible patches contg. bioadhesive polymers and **surfactants**)

IT Cosmetics

(moisturizers; invisible patches contg. bioadhesive polymers and **surfactants**)

IT **Surfactants**

(**nonionic**; invisible patches contg. bioadhesive polymers and **surfactants**)

IT Amines, biological studies

RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);

USES (Uses)

(polyamines, nonpolymeric; invisible patches contg. bioadhesive polymers and **surfactants**)

IT Alcohols, biological studies

RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);

USES (Uses)

(polyhydric, propoxylated; invisible patches contg. bioadhesive polymers and **surfactants**)

IT Quaternary ammonium compounds, biological studies

RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);

USES (Uses)

(polymers; invisible patches contg. bioadhesive polymers and **surfactants**)

IT Skin, disease

(rash, drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)

IT Cosmetics

(skin-lightening; invisible patches contg. bioadhesive polymers and **surfactants**)

IT Drug delivery systems

(tapes; invisible patches contg. bioadhesive polymers and **surfactants**)

IT Cosmetics

(wrinkle-preventing; invisible patches contg. bioadhesive polymers and **surfactants**)

IT **Surfactants**

(**zwitterionic**; invisible patches contg. bioadhesive polymers and **surfactants**)

IT 36574-66-0D, N-coco acyl derivs.

RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);

USES (Uses)

(cocoamidopropylbetaine; invisible patches contg. bioadhesive polymers and **surfactants**)

IT 68-26-8, Retinol 96-26-4, Dihydroxyacetone 814-71-1, Calcium

**thioglycolate** 34452-51-2, Potassium **thioglycolate**

RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

IT 50-70-4, Sorbitol, biological studies 50-70-4D, Sorbitol, oligomers

contg. 50-78-2, Aspirin 50-81-7, Vitamin C, biological studies

50-99-7D, Glucose, esters 50-99-7D, D-Glucose, oligomers contg.

55-56-1, Chlorhexidine 56-81-5, Glycerin, biological studies 56-86-0D,

Glutamic acid, N-acyl derivs. 57-48-7D, Fructose, oligomers contg.

STN Columbus

57-50-1D, Sucrose, esters 57-50-1D, Sucrose, oligomers contg. 57-55-6, Propylene glycol, biological studies 58-86-6D, Xylose, oligomers contg. 59-23-4D, Galactose, oligomers contg. 59-87-0, Nitrofurazone 60-54-8, Tetracycline 69-65-8D, Mannitol, oligomers contg. 69-72-7, Salicylic acid, biological studies 69-79-4D, Maltose, oligomers contg. 87-99-0D, Xylitol, oligomers contg. 106-11-6, Diethylene glycol monostearate 107-36-8D, Isethionic acid, cocoyl derivs. 108-46-3, Resorcinol, biological studies 108-95-2, Phenol, biological studies 114-07-8, Erythromycin 115-83-3, Pentaerythritol tetrastearate 144-55-8, Sodium bicarbonate, biological studies 151-21-3, Sodium lauryl sulfate, biological studies 404-86-4, Capsaicin 497-19-8, Sodium carbonate, biological studies 585-86-4D, Lactitol, oligomers contg. 585-88-6D, Maltitol, oligomers contg. 770-35-4, Phenoxyisopropanol 1338-41-6, Sorbitan monostearate 1406-18-4, Vitamin E 2216-51-5 3380-34-5, Triclosan 3458-28-4D, D-Mannose, oligomers contg. 6284-40-8 7439-97-6, Mercury, biological studies 7440-22-4, **Silver**, biological studies 7553-56-2, Iodine, biological studies 8011-96-9, Calamine 8050-81-5, Simethicone 9000-01-5, Gum arabic 9002-89-5, Polyvinyl alcohol 9002-98-6 9003-05-8, Polyacrylamide 9003-39-8, Polyvinylpyrrolidone 9004-64-2, Hydroxypropyl cellulose 9005-25-8, Starch, biological studies 9005-25-8D, Starch, hydrolyzates 9005-64-5, Polysorbate 20 9011-13-6, Styrene-maleic anhydride copolymer 9011-16-9, Methyl vinyl ether-maleic anhydride copolymer 11099-07-3, Glycerin stearate 11111-12-9, Cephalosporin 11140-06-0, Glycerin palmitate 12694-22-3, Diglyceryl monostearate 13718-94-0D, Palatinose, oligomers contg. 15687-27-1, Ibuprofen 18323-44-9, Clindamycin 25322-68-3, Polyethylene glycol 25322-69-4 25655-41-8, Povidone iodine 26658-19-5, Sorbitan tristearate 27195-16-0, Sucrose distearate 30233-64-8, Glyceryl monobehenate 39529-26-5, Decaglyceryl decastearate 42852-72-2 53998-08-6, Sarcosinate 63119-59-5, Diglycerin distearate 68424-04-4, Polydextrose 71185-87-0, Hexaglyceryl tristearate 75537-01-8, Gantrez S-97 95461-64-6, Decaglyceryl pentastearate 99734-29-9, Tetraglyceryl tristearate 99880-64-5, Glyceryl dibehenate 106392-12-5, Polyoxyethylene polyoxypropylene block copolymer  
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

IT 56-75-7, Chloramphenicol 94-09-7, Benzocaine

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

L15 ANSWER 10 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1992:536001 CAPLUS

DN 117:136001

OREF 117:23503a,23506a

ED Entered STN: 04 Oct 1992

TI Aqueous emulsion for temporary protection of **silver** and copper surfaces against tarnishing

IN Grossmann, Hermann

PA Doduco GmbH und Co. Dr. Eugen Duerrwaechter, Germany

SO Eur. Pat. Appl., 6 pp.

CODEN: EPXXDW

DT Patent

LA German

IC ICM C23F011-16

CC 56-10 (Nonferrous Metals and Alloys)

FAN.CNT 1



## STN Columbus

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	EP 492487	A1	19920701	EP 1991-121903	19911220
	EP 492487	B1	19960320		
	R: DE, ES, FR, GB, IT, NL				
	DE 4041596	A1	19920702	DE 1990-4041596	19901222
	ES 2086471	T3	19960701	ES 1991-121903	19911220
PRAI	DE 1990-4041596	A	19901222		
	DE 1991-4124955	A	19910727		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
EP 492487	ICM	C23F011-16
	IPCI	C23F0011-16 [ICM,5]; C23F0011-10 [ICM,5,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16B
DE 4041596	IPCI	C23F0011-12 [ICM,5]; C23F0011-16 [ICS,5]; C23F0011-10 [ICS,5,C*]; C09K0015-06 [ICA,5]; C09K0015-12 [ICA,5]; C09K0015-00 [ICA,5,C*]; B01F0017-42 [ICA,5]; B01F0017-38 [ICA,5]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16B
ES 2086471	IPCI	C23F0011-16 [ICM,6]; C23F0011-10 [ICM,6,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16B
AB	The emulsion of pH 1-10 (preferably 2-4) comprises a hydrophobic inhibitor of a C <sub>≥</sub> 12 thioalc. with ≥ 1 SH group and its ester 0.05-50 (preferably 2-20), emulsifier 0.05-50 (2-20), and an <b>anionic</b> or <b>nonionic surfactant</b> ≤ 2 (0.05-1 g/L). The emulsifier comprises an alkoxyated and preferably ethoxyated branched C4-20 alc., an alkyl or alkylphenyl ether of polyethylene glycol. <b>Ag</b> , Cu, and their alloys are treated with the emulsion at >T (m.p. of inhibitor), rinsed with H2O at <T, and dried with hot air. An example emulsion of pH 3 and suitable for treatment of <b>Ag</b> and <b>Ag</b> alloys contains <b>octadecanethiol</b> 0.5-30, polyethylene glycol alkyl ether 0.5-30, and SDS ≤ 1 g/L H2O.	
ST	tarnishing inhibitor <b>silver</b> copper; thiol SDS tarnishing inhibitor <b>silver</b> ; SDS thiol tarnishing inhibitor copper; polyethylene glycol ether tarnishing inhibitor	
IT	Thiols, uses RL: USES (Uses) (corrosion inhibitors, for copper and <b>silver</b> , with emulsifiers of alkyl or alkylphenyl ether of polyethylene glycol)	
IT	Tarnishing (of <b>silver</b> and copper alloys, aq. emulsion for prevention of)	
IT	Corrosion inhibitors (thiols, with emulsifiers of alkyl or alkyl Ph ether of polyethylene glycol)	
IT	Alcohols, compounds RL: PROC (Process) (C8-16, ethoxyated, corrosion inhibitor emulsion contg., thiol, for copper and <b>silver</b> and their alloys)	
IT	copper alloy, base <b>silver</b> alloy, base RL: RCT (Reactant); RACT (Reactant or reagent) (tarnishing of, thiol inhibitor for)	
IT	25322-68-3D, Polyethylene glycol, alkyl and alkylphenyl ethers 151-21-3, uses RL: PROC (Process)	

(corrosion inhibitor emulsion contg., thiol, for copper and **silver** and their alloys)

## IT 2885-00-9, Octadecanethiol

RL: PROC (Process)

(corrosion inhibitors, for copper and **silver**, with emulsifiers of alkyl or alkylphenyl ether of polyethylene glycol)

IT 7440-22-4, **Silver**, reactions 7440-50-8, Copper, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(tarnishing of, thiol inhibitor for)

L15 ANSWER 11 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1991:89162 CAPLUS

DN 114:89162

OREF 114:15093a,15096a

ED Entered STN: 09 Mar 1991

TI **Silver** metal liquidlike films (MELLFs). The effect of **surfactants**

AU Yogeve, D.; Efrima, S.

CS Dep. Chem., Ben-Gurion Univ. Negev, Beer-Sheva, 84105, Israel

SO Langmuir (1991), 7(2), 267-71

CODEN: LANGD5; ISSN: 0743-7463

DT Journal

LA English

CC 66-4 (Surface Chemistry and Colloids)

Section cross-reference(s): 73, 74

AB The effects of **surfactants** on the prodn. and stabilization of **Ag** metal liquidlike films (MELLFs) were studied. The main role of the **surfactant** is in stabilizing the **Ag** MELLFs and improving their properties (reflectivity, "fluidity"). A variety of different **surfactants** were found to be active, and of those investigated, **anionic** fluoroalkyl **surfactants** seem to be the most effective. In the case of **anionic surfactants**, the counteraction has a significant effect on the **Ag** MELLF, esp. if it is a surface-active agent in itself. The effects of the **surfactants** on the interfacial tension and their effect on the measured reflectivities of the MELLFs are discussed in the context of the interfacial colloidal model of **Ag** MELLFs.

ST **silver** metal liquidlike film formation; **surfactant** effect metal liquidlike film; interfacial tension metal liquidlike film

IT Films

(metal liq.-like, **surfactant** effects on formation of)

IT Interfacial tension

(of **surfactant** solns., **silver** metal liq.-like film formation in relation to)

IT Sulfonic acids, compounds

RL: PRP (Properties)

(perfluoroalkane, ammonium and potassium salts, **surfactant** effect of, on **silver** metal liq.-like film formation)

IT **Surfactants**

(**silver** metal liq.-like film formation in presence of)

IT Carboxylic acids, compounds

RL: PRP (Properties)

(perfluoro, ammonium salts, **surfactant** effect of, on **silver** metal liq.-like film formation)

IT 7440-22-4, **Silver**, uses and miscellaneous

RL: USES (Uses)

(liq.-like metal film formation by, **surfactant** effects on)

IT 577-11-7 2885-00-9, 1-Octadecanethiol 9002-93-1,

Triton X 100 52584-45-9, Monflor 31 57534-41-5, Zonyl FSN

60529-61-5, Monflor 32 67479-85-0, Zonyl FSC 67479-86-1, Zonyl FSP

RL: PRP (Properties)

## STN Columbus

(silver metal liq.-like film formation in presence of)

L15 ANSWER 12 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1987:33631 CAPLUS

DN 106:33631

OREF 106:5655a,5658a

ED Entered STN: 07 Feb 1987

TI Maleimide copolymer and thermoplastic resin prepared by using this copolymer

IN Kimura, Atsushi; Toyooka, Yutaka; Kishida, Kazuo

PA Mitsubishi Rayon Co., Ltd., Japan

SO PCT Int. Appl., 41 pp.

CODEN: PIXXD2

DT Patent

LA Japanese

IC ICM C08F002-18

ICS C08F212-04; C08L033-14; C08L035-06; C08L051-04

CC 35-4 (Chemistry of Synthetic High Polymers)

Section cross-reference(s): 38

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----	----	-----	-----	-----
PI	WO 8604337	A1	19860731	WO 1986-JP17	19860117
	W: AU, US				
	RW: DE, FR, GB, IT, NL				
	JP 61163903	A	19860724	JP 1985-4907	19850117
	JP 61174248	A	19860805	JP 1985-12705	19850128
	AU 8653567	A	19860813	AU 1986-53567	19860117
	EP 208790	A1	19870121	EP 1986-900840	19860117
	R: DE, FR, GB, IT, NL				
	CA 1262299	A1	19891010	CA 1986-518902	19860923
PRAI	JP 1985-4907	A	19850117		
	JP 1985-12705	A	19850128		
	WO 1986-JP17	A	19860117		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
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WO 8604337	ICM	C08F002-18
	ICS	C08F212-04; C08L033-14; C08L035-06; C08L051-04
	IPCI	C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08L0033-14 [ICS, 4]; C08L0033-00 [ICS, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*]
	IPCR	C08F0002-12 [I, C*]; C08F0002-18 [I, A]; C08F0222-00 [I, C*]; C08F0222-40 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-04 [I, A]
	ECLA	C08F222/40; C08L035/06+B5; C08L051/04+B2
JP 61163903	IPCI	C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08F0002-00 [ICA, 4]
JP 61174248	IPCI	C08L0033-18 [ICM, 4]; C08L0033-00 [ICM, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*]
	IPCR	C08L0033-00 [I, C*]; C08L0033-00 [I, A]; C08L0007-00 [I, C*]; C08L0007-00 [I, A]; C08L0021-00 [I, C*]; C08L0021-00 [I, A]; C08L0023-00 [I, C*]; C08L0023-00 [I, A]; C08L0033-02 [I, A]; C08L0033-18 [I, A];

## STN Columbus

C08L0033-24 [I,A]; C08L0035-00 [I,C\*]; C08L0035-06 [I,A]; C08L0051-00 [I,C\*]; C08L0051-00 [I,A]; C08L0051-02 [I,A]; C08L0051-04 [I,A]; C08L0101-00 [I,C\*]; C08L0101-00 [I,A]

AU 8653567 IPCI C08F0002-18 [ICM,4]; C08F0002-12 [ICM,4,C\*]; C08F0212-04 [ICS,4]; C08F0212-00 [ICS,4,C\*]; C08L0033-14 [ICS,4]; C08L0033-00 [ICS,4,C\*]; C08L0035-06 [ICS,4]; C08L0035-00 [ICS,4,C\*]; C08L0051-04 [ICS,4]; C08L0051-00 [ICS,4,C\*]

IPCR C08F0002-12 [I,C\*]; C08F0002-18 [I,A]; C08F0222-00 [I,C\*]; C08F0222-40 [I,A]; C08L0035-00 [I,C\*]; C08L0035-06 [I,A]; C08L0051-00 [I,C\*]; C08L0051-04 [I,A]

EP 208790 ECLA C08F222/40; C08L035/06+B5; C08L051/04+B2

IPCI C08F0002-18 [ICM,4]; C08F0002-12 [ICM,4,C\*]; C08F0212-04 [ICS,4]; C08F0212-00 [ICS,4,C\*]; C08L0033-14 [ICS,4]; C08L0033-00 [ICS,4,C\*]; C08L0035-06 [ICS,4]; C08L0035-00 [ICS,4,C\*]; C08L0051-04 [ICS,4]; C08L0051-00 [ICS,4,C\*]

IPCR C08F0002-12 [I,C\*]; C08F0002-18 [I,A]; C08F0222-00 [I,C\*]; C08F0222-40 [I,A]; C08L0035-00 [I,C\*]; C08L0035-06 [I,A]; C08L0051-00 [I,C\*]; C08L0051-04 [I,A]

CA 1262299 ECLA C08F222/40; C08L035/06+B5; C08L051/04+B2

IPCI C08F0212-04 [ICM,4]; C08F0212-00 [ICM,4,C\*]; C08L0025-02 [ICS,4]; C08L0025-00 [ICS,4,C\*]; C08L0051-04 [ICS,4]; C08L0051-00 [ICS,4,C\*]

IPCR C08F0212-00 [I,C\*]; C08F0212-04 [I,A]; C08L0025-00 [I,C\*]; C08L0025-02 [I,A]; C08L0051-00 [I,C\*]; C08L0051-04 [I,A]

AB A maleimide polymer with excellent heat stability during high-temp. molding and giving a product with excellent resistance to discoloration, heat, and impact when blended with a graft rubber, is prepd. by polymn. of a monomer selected from an arom. vinyl monomer, an unsatd. nitrile, and Me methacrylate 50-95, a maleimide 5-50, and other monomers 0-30% in the presence of a Ca phosphate-based dispersing agent and a **nonionic surfactant** [RO(CH<sub>2</sub>CH<sub>2</sub>O)<sub>n</sub>]mPO(OA)<sub>3-m</sub> (R = C8-30 alkyl, aralkyl; A = H, metal; m = 1-3, n = 5-50). The process minimizes the scale formation of formed polymers on a reactor wall during polymn. Thus, a mixt. of arylonitrile 20, styrene 170, and N-phenylmaleimide 10 parts in 100 parts water contg. AIBN 0.1, tert-Bu benzoate 0.1, tert-dodecyl **mercaptan** 0.3, Gafac GB 520 0.003, and Ca<sub>3</sub>PO<sub>4</sub> 0.5 part was suspension-polymd. at 80° for 3 h and at 120° for 2 h to give polymer beads (particle diam. 180 μ, glass-transition temp. 125°). During the polymn., no scale formation was obsd. A blend of 55 parts maleimide copolymer and 45 parts graft polymer from polybutadiene 50, acrylonitrile 15, and styrene 35 parts contg. Mg stearate 0.3, tris(nonylphenyl) phosphite 0.1, and Antage W 400 0.2 phr was injection-molded at 280-290° to give a sample exhibiting yellowing index (at 280°) 31, notched Izod impact strength 16.4 kg-cm/cm<sup>2</sup>, Rockwell hardness (R) 102, and Vicat softening point 108°, with no **silver** streak formation, compared with 44, 16, 101, and 104, with **silver** streak formation, when a maleimide copolymer prepd. in the presence of poly(vinyl alc.) as a dispersing agent was used.

ST phenylmaleimide copolymer suspension polymn; acrylonitrile copolymer suspension polymn; styrene copolymer suspension polymn; calcium phosphate dispersant suspension polymn; polyethylene glycol lauryl ether phosphate;

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**nonionic** phosphate **surfactant** suspension polymn; scale prevention  
suspension polymn dispersant; ABS blend maleimide copolymer molding; heat  
stability maleimide copolymer molding

- IT Plastics, molded  
RL: USES (Uses)  
(ABS polymer-maleimide-contg. polymers, heat- and impact-resistant,  
heat-stable)
- IT Heat-resistant materials  
(maleimide-contg. polymers, heat stability improvement of)
- IT Dispersing agents  
(polyalkylene glycol phosphate-tricalcium phosphate, in suspension  
polymn. of maleimide-contg. monomer mixts., for scale formation  
prevention)
- IT Scale (coating)  
(prevention of, on reactor wall during suspension polymn. of  
maleimide-contg. monomer mixts., dispersing agents for)
- IT Polymerization  
(suspension, of maleimide-contg. monomer mixts., dispersing agents for,  
for scale formation prevention)
- IT 9003-56-9  
RL: USES (Uses)  
(phenylmaleimide copolymer blends, heat-stable, resistant to  
discoloration, heat and impact)
- IT 31621-07-5P, Acrylonitrile-N-phenylmaleimide-styrene copolymer  
94858-30-7P, Acrylonitrile- $\alpha$ -methylstyrene-N-phenylmaleimide-styrene  
copolymer 101482-57-9P, Acrylonitrilemethyl  
methacrylate-N-phenylmaleimide-styrene copolymer  
RL: PREP (Preparation)  
(prepn. of, by suspension polymn., dispersing agents for, for improved  
heat stability and scale prevention during polymn.)
- IT 51811-79-1, Gafac RE 610  
RL: USES (Uses)  
(suspending agents, Gafac RE 610, in suspension polymn. of  
maleimide-contg. monomer mixts., for scale formation prevention during  
polymn.)
- IT 35604-29-6, Gafac GB 520  
RL: USES (Uses)  
(suspension agent, Gafac GB 520, in suspension polymn. of  
maleimide-contg. monomer mixts., for scale formation prevention during  
polymn.)
- IT 7758-87-4, Tricalcium phosphate  
RL: USES (Uses)  
(suspension agent, in suspension polymn. of maleimide-contg. monomer  
mixts., for scale formation prevention during polymn.)

RE.CNT 7 THERE ARE 7 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Anon; JP 4983785 A
- (2) Anon; JP 5495689 A
- (3) Anon; JP 57125242 A CAPLUS
- (4) Anon; JP 57167341 A CAPLUS
- (5) Anon; JP 58129043 A CAPLUS
- (6) Anon; JP 58206657 A CAPLUS
- (7) Anon; JP 59184243 A CAPLUS

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(FILE 'HOME' ENTERED AT 00:05:08 ON 23 MAY 2009)

STN Columbus

FILE 'CAPLUS' ENTERED AT 00:05:27 ON 23 MAY 2009  
S 22811-02-5/REG# OR 10220-46-9/REG# OR 2917-26-2/REG# OR 28

L1 FILE 'REGISTRY' ENTERED AT 00:12:43 ON 23 MAY 2009  
1 S 2885-00-9/RN

L2 FILE 'CAPLUS' ENTERED AT 00:12:44 ON 23 MAY 2009  
2011 S L1

L3 FILE 'REGISTRY' ENTERED AT 00:12:44 ON 23 MAY 2009  
1 S 2917-26-2/RN

L4 FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009  
1621 S L3

L5 FILE 'REGISTRY' ENTERED AT 00:12:45 ON 23 MAY 2009  
1 S 10220-46-9/RN

L6 FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009  
50 S L5

L7 FILE 'REGISTRY' ENTERED AT 00:12:46 ON 23 MAY 2009  
1 S 22811-02-5/RN

L8 FILE 'CAPLUS' ENTERED AT 00:12:46 ON 23 MAY 2009  
6 S L7  
L9 32684 S L8 OR L6 OR L4 OR L2 OR THIOGLYCOLATE OR MERCAPTOACETATE OR H  
L10 84695 S (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFAC  
L11 319 S L9 AND L10  
L12 6680 S METAL TREAT##### OR TREAT##### METAL  
L13 1 S L11 AND L12  
L14 522045 S SILVER OR AG  
L15 12 S L11 AND L14

=> s (nonionic or non-ionic) and anionic and zwitterionic and surfactant#

79712 NONIONIC  
1054666 NON  
307432 IONIC  
9398 NON-IONIC  
(NON(W) IONIC)  
134021 ANIONIC  
13094 ZWITTERIONIC  
275066 SURFACTANT#

L16 1173 (NONIONIC OR NON-IONIC) AND ANIONIC AND ZWITTERIONIC AND SURFAC  
ANT#

=> s l11 and l16

L17 3 L11 AND L16

=> d 1-3 all

L17 ANSWER 1 OF 3 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2008:619503 CAPLUS

DN 148:545131

ED Entered STN: 23 May 2008

TI Detergent compositions in the form of microemulsions and use thereof in  
the treatment of alopecia

IN Ben Alloum, Abdelkrim

PA Morocco

## STN Columbus

SO PCT Int. Appl., 63pp.  
 CODEN: PIXXD2  
 DT Patent  
 LA French  
 CC 62-4 (Essential Oils and Cosmetics)  
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2008060130	A2	20080522	WO 2007-MA11	20071105
	WO 2008060130	A3	20081211		
	W:	AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW			
	RW:	AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AP, EA, EP, OA			
PRAI	MA 2006-29458	A	20061116		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
WO 2008060130	IPCI	A61Q0007-00 [I,A]; A61Q0019-10 [I,A]; A61P0017-14 [I,A]; A61K0008-37 [I,A]; A61K0008-06 [I,A]; A61K0008-39 [I,A]; A61K0008-55 [I,A]; A61K0008-86 [I,A]; A61Q0007-00 [I,C]; A61Q0007-00 [I,A]; A61K0008-04 [I,C]; A61K0008-06 [I,A]; A61K0008-30 [I,C]; A61K0008-37 [I,A]; A61K0008-39 [I,A]; A61K0008-55 [I,A]; A61K0008-72 [I,C]; A61K0008-86 [I,A]; A61P0017-00 [I,C]; A61P0017-14 [I,A]; A61Q0019-10 [I,C]; A61Q0019-10 [I,A]
	IPCR	A61Q0007-00 [I,C]; A61Q0007-00 [I,A]; A61K0008-04 [I,C]; A61K0008-06 [I,A]; A61K0008-30 [I,C]; A61K0008-37 [I,A]; A61K0008-39 [I,A]; A61K0008-55 [I,A]; A61K0008-72 [I,C]; A61K0008-86 [I,A]; A61P0017-00 [I,C]; A61P0017-14 [I,A]; A61Q0019-10 [I,C]; A61Q0019-10 [I,A]
	ECLA	A61K008/06C; A61K008/36C; A61K008/92C; A61Q007/00

OS MARPAT 148:545131

AB The invention relates to detergent compns. in the form of stable, transparent oil-in-water-type microemulsions which are prepd. in accordance with the invention and which take the form of a liq. or gel. The aforementioned compns. comprise water, electrolytes, fatty acids, a combination of fatty acid salt type surface-active agents and at least one **nonionic** surface-active agent, an oil preferably selected from oils contg. long-chain triglycerides and, if desired, other auxiliary agents, additives and active principles. Said compns. can be used, in particular, to clean and condition keratinous matter such as hair or skin. The inventive compns. can micro-emulsify sebum on contact. The invention also relates to a cosmetic method for the treatment of androgenic alopecia or the prevention of hair loss. A microemulsion contained sunflower oil 3.26, free fatty acids 2.51, glycerin 2.04, copra oil fatty acids 19.84, Tergitol NP-9 16.32, sodium lactate 1.02, sodium chloride 0.65, disodium EDTA 0.16, and water 54.20%. Efficacy of the compn. in patient with alopecia is shown.

ST detergent microemulsion alopecia oil **surfactant** hair loss

# STN Columbus

- IT Alcohols, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(C9-11, ethoxylated; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fatty acids, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(alkali metal salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Phenols, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(alkyl; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alcohols, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(amino; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT **Surfactants**  
(anionic; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(avocado; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(babassu; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(borage seed; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT **Surfactants**  
(cationic; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alopecia  
Cosmetic microemulsions  
Detergents  
Electrolytes  
Human  
**Surfactants**  
(detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Amines, biological studies  
Coconut oil  
Corn oil  
Fatty acids, biological studies  
Linseed oil  
Olive oil  
Palm oil  
Soybean oil  
Sunflower oil  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alcohols, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(ethoxylated; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)



# STN Columbus

- (evening primrose; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alkali metal salts  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(fatty acid salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Amides, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(fatty; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Glycerides, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(long-chain; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alopecia  
(male pattern; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT **Surfactants**  
(**nonionic**; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alcohols, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(polyhydric; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fatty acids, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(potassium salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Amino acids, biological studies  
Carboxylic acids, biological studies  
Fatty acids, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fatty acids, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(sodium salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(vegetable; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(wheat germ; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT **Surfactants**  
(**zwitterionic**; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT 50-21-5D, Lactic acid, salts 50-70-4D, Sorbitol, esters 56-81-5D, Glycerol, esters 56-84-8D, Aspartic acid, salts 57-50-1D, Sucrose, esters 72-17-3, Sodium lactate 77-92-9D, Citric acid, salts 87-69-4D, Tartaric acid, salts 98-11-3D, Benzenesulfonic acid, alkyl derivs., salts 104-15-4, p-Toluenesulfonic acid, biological studies 367-51-1, Sodium **thioglycolate** 7447-40-7, Potassium chloride, biological studies 7647-14-5, Sodium chloride, biological studies 7664-38-2D, Phosphoric acid, salts 7757-82-6, Sodium sulfate, biological studies 9016-45-9, Tergitol NP-9 12125-02-9, Ammonium chloride, biological studies 12441-09-7D, Sorbitan, esters  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)

## STN Columbus

(detergent compns. in form of microemulsions and use in treatment of alopecia)

L17 ANSWER 2 OF 3 CAPLUS COPYRIGHT 2009 ACS on STN

## Full Text

AN 2005:216634 CAPLUS

DN 142:284776

ED Entered STN: 11 Mar 2005

TI Method and compositions for straightening hair using a reducing and an oxidizing agent in combination with heat

IN Mueller, Burkhard; Schellin, Aaltje; Neubueser, Inge

PA Hans Schwarzkopf & Henkel GmbH & Co. KG, Germany

SO PCT Int. Appl., 49 pp.

CODEN: PIXXD2

DT Patent

LA German

IC ICM A61K007-09

ICS A61K007-075

CC 62-3 (Essential Oils and Cosmetics)

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2005020943	A1	20050310	WO 2004-EP9151	20040814
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW				
	RW: BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG				
	DE 10338883	A1	20050324	DE 2003-10338883	20030823
	BR 2004009291	A	20060411	BR 2004-9291	20040814
	EP 1656184	A1	20060517	EP 2004-764143	20040814
	EP 1656184	B1	20080326		
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, FI, RO, CY, TR, BG, CZ, EE, HU, PL, SK				
	JP 2007503379	T	20070222	JP 2006-523591	20040814
	AT 390175	T	20080415	AT 2004-764143	20040814
	ES 2300812	T3	20080616	ES 2004-764143	20040814
	US 20060150344	A1	20060713	US 2005-297707	20051208
	HK 1086211	A1	20080815	HK 2006-106137	20060526
PRAI	DE 2003-10338883	A	20030823		
	WO 2004-EP9151	W	20040814		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
WO 2005020943	ICM	A61K007-09
	ICS	A61K007-075
	IPCI	A61K0007-09 [ICM,7]; A61K0007-075 [ICS,7]
	IPCR	A61K0008-30 [I,C*]; A61K0008-41 [I,A]; A61K0008-49 [I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
	ECLA	A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K

## STN Columbus

DE 10338883	IPCI	A61K0007-09 [ICM,7]
	IPCR	A61K0008-30 [I,C*]; A61K0008-41 [I,A]; A61K0008-49 [I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
	ECLA	A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K
BR 2004009291	IPCI	A61K0007-09 [ICM,7]; A61K0007-075 [ICS,7]
	ECLA	A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K
EP 1656184	IPCI	A61Q0005-04 [I,C]; A61Q0005-04 [I,A]; A61K0008-30 [I,C]; A61K0008-41 [I,A]; A61K0008-44 [I,A]; A61K0008-64 [I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C]; A61K0008-81 [I,A]; A61K0008-898 [I,A]; A61K0008-96 [I,C]; A61K0008-98 [I,A]; A61Q0005-12 [I,C]; A61Q0005-12 [I,A]
	IPCR	A61K0008-49 [I,A]; A61K0008-73 [I,A]
	ECLA	A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K
JP 2007503379	IPCI	A61K0008-892 [I,A]; A61K0008-81 [I,A]; A61K0008-41 [I,A]; A61K0008-891 [I,A]; A61K0008-72 [I,C*]; A61K0008-64 [I,A]; A61Q0005-12 [I,A]; A61K0008-22 [I,A]; A61K0008-19 [I,C*]; A61K0008-46 [I,A]; A61K0008-30 [I,C*]
	IPCR	A61K0008-72 [I,C]; A61K0008-892 [I,A]; A61K0008-19 [I,C]; A61K0008-22 [I,A]; A61K0008-30 [I,C]; A61K0008-41 [I,A]; A61K0008-46 [I,A]; A61K0008-49 [I,A]; A61K0008-64 [I,A]; A61K0008-65 [I,A]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61K0008-891 [I,A]; A61Q0005-12 [I,C]; A61Q0005-12 [I,A]
	FTERM	4C083/AB082; 4C083/AB312; 4C083/AB411; 4C083/AB412; 4C083/AC022; 4C083/AC072; 4C083/AC122; 4C083/AC172; 4C083/AC182; 4C083/AC302; 4C083/AC352; 4C083/AC422; 4C083/AC482; 4C083/AC612; 4C083/AC642; 4C083/AC691; 4C083/AC692; 4C083/AC771; 4C083/AC772; 4C083/AC782; 4C083/AC852; 4C083/AC892; 4C083/AD131; 4C083/AD132; 4C083/AD151; 4C083/AD152; 4C083/AD161; 4C083/AD162; 4C083/AD281; 4C083/AD282; 4C083/AD411; 4C083/AD412; 4C083/BB32; 4C083/BB34; 4C083/BB36; 4C083/BB53; 4C083/CC31; 4C083/CC33; 4C083/DD06; 4C083/DD23; 4C083/DD27; 4C083/DD38; 4C083/EE05; 4C083/EE06; 4C083/EE07; 4C083/EE21; 4C083/EE28
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	IPCR	A61Q0005-04 [I,C]; A61Q0005-04 [I,A]; A61K0008-30 [I,C]; A61K0008-41 [I,A]; A61K0008-49 [I,A]; A61K0008-64 [I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61K0008-898 [I,A]; A61K0008-96 [I,C]; A61K0008-98 [I,A]; A61Q0005-12 [I,C]; A61Q0005-12 [I,A]
	ECLA	A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K
ES 2300812	IPCI	A61Q0005-04 [I,C]; A61Q0005-04 [I,A]; A61K0008-30

## STN Columbus

[I,C]; A61K0008-41 [I,A]; A61K0008-44 [I,A];  
A61K0008-64 [I,A]; A61K0008-65 [I,A]; A61K0008-72  
[I,C]; A61K0008-81 [I,A]; A61K0008-898 [I,A];  
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IPCR A61Q0005-04 [I,C]; A61Q0005-04 [I,A]; A61K0008-30  
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A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12;  
K61K  
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IPCR A61K0008-00 [I,A]; A61K0008-00 [I,C]  
NCL 008/405.000  
ECLA A61K008/898; A61K008/41L; A61K008/58C; A61K008/64;  
A61K008/64C; A61K008/65; A61K008/73C; A61K008/81K4;  
A61K008/81R; A61K008/891; A61Q005/12; K61K  
HK 1086211 IPCI A61Q [I,S]; A61K [N,S]  
IPCR A61K0008-30 [I,C\*]; A61K0008-41 [I,A]; A61K0008-49  
[I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C\*];  
A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61Q0005-12  
[I,C\*]; A61Q0005-12 [I,A]  
ECLA A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65;  
A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12;  
K61K  
AB The invention concerns a method and compns. for straightening hair by (i)  
applying an aq. soln. that contains a keratin-reducing agent (A); (ii)  
rinsing the reducing-agent contg. soln. after a time period; (iii) drying  
the hair; (iv) exposing the hair to straightening under heat treatment at  
120-220 °C by ironing; (v) applying an aq. soln. that contains an  
oxidn. agent (B); (vi) rinsing off the soln. after a time period elapsed.  
Both A and B solns. contain conditioning agents selected from the group of  
cationic polymers, quaternary ammonium compds., silicones and protein  
hydrolyzates. Thus a component A included (wt./wt.%): 1,2-propylene  
glycol 2.00; cetyl/stearyl alc. (50-50% mixt.) 9.00; Lanette E 0.50; Brij  
35 P 0.50; Natrosol 250 HR 0.25; ammonia (25% aq.soln.) 5.00; Turpinal SL  
0.25; ammonium **thioglycolate** (71% aq.soln.) 18.00; ammonium bicarbonate  
4.00; Promois Silk 1000 1.00; Dow Corning 1403 fluid 0.50; perfume 1.00;  
water to 100. Component B contained (wt./wt.%): cetearyl alc. 4.00;  
Eumulgin B3 0.50; ammonia (25% aq.soln.) 0.80; dipicolinic acid 0.10;  
Turpinal SL 1.70; Rheocare CTH(E) 1.00; hydrogen peroxide (50% aq.soln.)  
4.00; water to 100.  
ST hair straightening compn reducing oxidizing agent conditioner heat  
IT Polysiloxanes, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
((aminoethyl)amino]propyl hydroxy, di-Me; method and compns. for  
straightening hair using reducing and oxidizing agents in combination  
with heat)  
IT **Surfactants**  
(amphoteric; method and compns. for straightening hair using reducing  
and oxidizing agents in combination with heat)  
IT **Surfactants**  
(**anionic**; method and compns. for straightening hair using  
reducing and oxidizing agents in combination with heat)  
IT Polyelectrolytes

STN Columbus

(cationic; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT Hair preparations  
(conditioners; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT Cyclosiloxanes  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(di-Me; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT Quaternary ammonium compounds, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(ester group-contg.; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT Fibroin  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(hydrolyzates; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT Onium compounds  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(imidazolium compds., 2-(C9-19 and C9-19-unsatd. alkyl)-1-[(C10-20 and C10-20-unsatd. amido)ethyl]-4,5-dihydro-1-Me, Me sulfates, Rewoquat W 575PG; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT Heat treatment  
Oxidizing agents  
Reducing agents  
Viscosity  
(method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT Polysiloxanes, biological studies  
Protein hydrolyzates  
Quaternary ammonium compounds, biological studies  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT **Surfactants**  
(**nonionic**; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT Hair preparations  
(straighteners; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT **Surfactants**  
(**zwitterionic**; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

IT 112-02-7, Dehyquart A-CA 2809-21-4, Turpinal SL 5421-46-5, Ammonium **thioglycolate** 7651-02-7, Tegoamide S18 7722-84-1, Hydrogen peroxide, biological studies 8045-77-0, Lanette E 9002-92-0, Brij 35 P 9004-62-0, Natrosol 250 HR 9006-65-9, Dimethicone 16962-53-1D, Trimethyl ammonium, alkyl halogenide derivs. 17000-00-9D, Methylammonium, trialkyl halogenide derivs. 17000-01-0D, Dimethylammonium, dialkyl halogenide derivs. 17301-53-0, Genamin KDMP 26062-79-3, Merquat 100 26161-33-1, Rheocare CTH(E) 31692-79-2, Dimethiconol 32208-04-1, Dehyquart F75 81859-24-7, Polymer JR 400 195868-36-1, Phenyltrimethicone 205537-77-5, Dow Corning 1403 473664-54-9, Salcare SC 96  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

RE.CNT 12 THERE ARE 12 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

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L17 ANSWER 3 OF 3 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:737150 CAPLUS

DN 139:250305

ED Entered STN: 19 Sep 2003

TI Invisible patch for the controlled delivery of cosmetic, dermatological, and pharmaceutical active ingredients onto the skin

IN Shefer, Adi; Shefer, Samuel

PA USA

SO U.S. Pat. Appl. Publ., 17 pp., Cont.-in-part of U. S. Ser. No. 91,935.  
CODEN: USXXCO

DT Patent

LA English

IC ICM A61K031-715

ICS A61K009-70

INCL 424449000; 514061000

CC 63-6 (Pharmaceuticals)

Section cross-reference(s): 62

FAN.CNT 2

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 20030175333	A1	20030918	US 2003-376736	20030228
	US 20030175328	A1	20030918	US 2002-91935	20020306
	CA 2515098	A1	20040916	CA 2004-2515098	20040227
	WO 2004078122	A2	20040916	WO 2004-US6106	20040227
	WO 2004078122	A3	20050203		
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI				
	RW: BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG				
	EP 1603499	A2	20051214	EP 2004-715783	20040227
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK				
	JP 2006519263	T	20060824	JP 2006-508924	20040227
PRAI	US 2002-91935	A2	20020306		
	US 2003-376736	A	20030228		
	WO 2004-US6106	W	20040227		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 20030175333	ICM	A61K031-715
	ICS	A61K009-70

## STN Columbus

INCL	424449000; 514061000
IPCI	A61K0031-715 [ICM,7]; A61K0009-70 [ICS,7]
IPCR	A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61F0013-02 [I,C*]; A61F0013-02 [I,A]; A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-02 [I,C*]; A61K0008-02 [I,A]; A61K0008-11 [I,C*]; A61K0008-11 [I,A]; A61K0008-30 [I,C*]; A61K0008-35 [I,A]; A61K0008-368 [I,A]; A61K0008-44 [I,A]; A61K0008-67 [I,A]; A61K0008-72 [I,C*]; A61K0008-72 [I,A]; A61K0008-73 [I,A]; A61K0008-96 [I,C*]; A61K0008-97 [I,A]; A61K0009-50 [I,C*]; A61K0009-50 [I,A]; A61K0009-51 [I,C*]; A61K0009-51 [I,A]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0031-01 [I,C*]; A61K0031-01 [I,A]; A61K0031-045 [I,C*]; A61K0031-045 [I,A]; A61K0031-047 [I,A]; A61K0031-05 [I,A]; A61K0031-075 [I,C*]; A61K0031-085 [I,A]; A61K0031-121 [I,C*]; A61K0031-121 [I,A]; A61K0031-155 [I,C*]; A61K0031-155 [I,A]; A61K0031-165 [I,C*]; A61K0031-165 [I,A]; A61K0031-345 [I,C*]; A61K0031-345 [I,A]; A61K0031-4453 [I,C*]; A61K0031-4453 [I,A]; A61K0031-545 [I,C*]; A61K0031-545 [I,A]; A61K0031-60 [I,C*]; A61K0031-60 [I,A]; A61K0031-616 [I,A]; A61K0031-65 [I,C*]; A61K0031-65 [I,A]; A61K0031-7042 [I,C*]; A61K0031-7048 [I,A]; A61K0033-00 [I,C*]; A61K0033-00 [I,A]; A61K0033-18 [I,C*]; A61K0033-18 [I,A]; A61K0033-28 [I,C*]; A61K0033-28 [I,A]; A61K0033-38 [I,C*]; A61K0033-38 [I,A]; A61K0036-18 [I,C*]; A61K0036-18 [I,A]; A61K0036-88 [I,C*]; A61K0036-896 [I,A]; A61K0045-00 [I,C*]; A61K0045-00 [I,A]; A61K0047-32 [I,C*]; A61K0047-32 [I,A]; A61K0047-34 [I,C*]; A61K0047-34 [I,A]; A61K0047-36 [I,C*]; A61K0047-36 [I,A]; A61K0047-38 [I,C*]; A61K0047-38 [I,A]; A61K0047-42 [I,C*]; A61K0047-42 [I,A]; A61L0015-16 [I,C*]; A61L0015-44 [I,A]; A61P0017-00 [I,C*]; A61P0017-00 [I,A]; A61P0017-02 [I,A]; A61P0017-10 [I,A]; A61P0017-12 [I,A]; A61P0017-16 [I,A]; A61Q0009-04 [I,C*]; A61Q0009-04 [I,A]; A61Q0017-04 [I,C*]; A61Q0017-04 [I,A]; A61Q0019-00 [I,C*]; A61Q0019-00 [I,A]; A61Q0019-02 [I,C*]; A61Q0019-02 [I,A]; A61Q0019-04 [I,C*]; A61Q0019-04 [I,A]; A61Q0019-08 [I,C*]; A61Q0019-08 [I,A]
NCL	424/449.000; 514/061.000
ECLA	A61K008/02C; A61K008/35; A61K008/368; A61K008/44; A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97; A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00; A61Q019/04; A61Q019/08; K61K
US 20030175328	IPCI A61K0009-70 [ICM,7]
	IPCR A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61F0013-02 [I,C*]; A61F0013-02 [I,A]; A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-02 [I,C*]; A61K0008-02 [I,A]; A61K0008-11 [I,C*]; A61K0008-11 [I,A]; A61K0008-30 [I,C*]; A61K0008-35 [I,A]; A61K0008-368 [I,A]; A61K0008-44 [I,A]; A61K0008-67 [I,A]; A61K0008-72 [I,C*]; A61K0008-72 [I,A]; A61K0008-73 [I,A]; A61K0008-96 [I,C*]; A61K0008-97 [I,A]; A61K0009-50 [I,C*]; A61K0009-50 [I,A]; A61K0009-51 [I,C*]; A61K0009-51 [I,A]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0031-01 [I,C*]; A61K0031-01 [I,A]; A61K0031-045 [I,C*]; A61K0031-045 [I,A]; A61K0031-047 [I,A]; A61K0031-05 [I,A]; A61K0031-075

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[I,C\*]; A61K0031-085 [I,A]; A61K0031-121 [I,C\*];  
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 A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97;  
 A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00;  
 A61Q019/04; A61Q019/08; K61K  
 CA 2515098 IPCI A61K0009-70 [ICM,7]; A61K0007-00 [ICS,7]; A61K0045-00  
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4C076/CC03; 4C076/CC04; 4C076/CC18; 4C076/DD03;  
4C076/DD04; 4C076/DD07; 4C076/DD08; 4C076/DD09;  
4C076/DD13; 4C076/DD17; 4C076/DD38A; 4C076/DD66A;  
4C076/EE06A; 4C076/EE10A; 4C076/EE12A; 4C076/EE13A;  
4C076/EE17A; 4C076/EE23A; 4C076/EE26A; 4C076/EE27;  
4C076/EE30A; 4C076/EE31A; 4C076/EE32A; 4C076/EE38A;  
4C076/FF31; 4C076/FF35; 4C083/AA112; 4C083/AB032;  
4C083/AC122; 4C083/AC131; 4C083/AC181; 4C083/AC371;  
4C083/AC391; 4C083/AC421; 4C083/AC441; 4C083/AC532;  
4C083/AC682; 4C083/AC772; 4C083/AC781; 4C083/AC791;  
4C083/AD041; 4C083/AD042; 4C083/AD051; 4C083/AD071;  
4C083/AD072; 4C083/AD091; 4C083/AD111; 4C083/AD131;  
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4C083/AD241; 4C083/AD261; 4C083/AD271; 4C083/AD281;  
4C083/AD282; 4C083/AD351; 4C083/AD391; 4C083/AD642;  
4C083/AD662; 4C083/CC02; 4C083/DD12; 4C083/EE12;  
4C083/EE13; 4C083/EE14; 4C083/EE16; 4C083/EE22;  
4C084/AA17; 4C084/MA32; 4C084/MA63; 4C084/NA10;  
4C084/ZA891

AB The present invention relates to a patch for controlled topical or transdermal delivery of effective levels of cosmetic, dermatol., and pharmaceutical active ingredients onto the skin, hair follicles, and sebaceous glands, with minimal discomfort and ease of use. The patch can be transparent or clear and comprises a rate-controlling matrix layer. The matrix layer comprises water-sensitive, bioadhesive, film forming polymers, a water sol. oligomer, and a **surfactant**. The cosmetic, dermatol., and pharmaceutical active ingredients are sol. or dispersed in the matrix. The patch becomes tacky when wetted and adheres onto the skin. The adhesive properties of the patch are sufficient to maintain the patch in place on the skin for the recommended treatment period while allowing the patch to be readily removed without causing skin irritation or leaving adhesive residue on the skin. For example, an antibiotic patch contained polyvinyl alc. 50, PVP 1, polysorbate 20 5, Maltrin 180 10, lactitol 5, glycerin 10, and chloramphenicol 0.55%.

ST patch bioadhesive polymer oligosaccharide **surfactant**; antibiotic patch PVA PVP polysorbate chloramphenicol

STN Columbus

- IT Glycosides  
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
USES (Uses)  
(alkyl polyglycosides; invisible patches contg. bioadhesive polymers  
and **surfactants**)
- IT **Surfactants**  
(amphoteric; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT **Surfactants**  
(**anionic**; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT **Surfactants**  
(cationic; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Essential oils  
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
USES (Uses)  
(clove; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Hair preparations  
(conditioners; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Cosmetics  
(depilatories; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Acne  
Burn  
Dandruff  
Pruritus  
Rhus diversiloba  
Rhus toxicodendron  
(drugs for; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Alcohols, biological studies  
Amides, biological studies  
Esters, biological studies  
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
USES (Uses)  
(ethoxylated; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Hair preparations  
(growth stimulants; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Vein, disease  
(hemorrhoid, drugs for; invisible patches contg. bioadhesive polymers  
and **surfactants**)
- IT Syrups (sweetening agents)  
(hydrolyzed starch; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Allergy inhibitors  
Aloe barbadensis  
Analgesics  
Anti-infective agents  
Anti-inflammatory agents  
Antibacterial agents  
Antibiotics  
Antiemetics  
Antihistamines  
Antimicrobial agents  
Antioxidants

Antiperspirants  
 Antitussives  
 Antiviral agents  
 Chelating agents  
 Chemotherapy  
 Cholinergic antagonists  
 Deodorants  
 Disinfectants  
 Fungicides  
 Hemostatics  
 Immunomodulators  
 Insecticides  
 Radical scavengers  
 Sunscreens  
 Suntanning agents  
 Vasoconstrictors  
 Vasodilators  
 Wound healing promoters  
     (invisible patches contg. bioadhesive polymers and **surfactants**  
     )

- IT Amine oxides  
 Amino acids, biological studies  
 Carbohydrates, biological studies  
 Caseins, biological studies  
 Flavonoids  
 Gelatins, biological studies  
 Glycerides, biological studies  
 Lanolin  
 Lecithins  
 Oligosaccharides, biological studies  
 Paraffin oils  
 Peptides, biological studies  
 Polyamides, biological studies  
 Polyesters, biological studies  
 Polyoxyalkylenes, biological studies  
 Polyoxyalkylenes, biological studies  
 Polysaccharides, biological studies  
 Proteins  
 Retinoids  
 Vitamins  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
 USES (Uses)  
     (invisible patches contg. bioadhesive polymers and **surfactants**  
     )
- IT Anesthetics  
     (local; invisible patches contg. bioadhesive polymers and  
     **surfactants**)
- IT Cosmetics  
     (moisturizers; invisible patches contg. bioadhesive polymers and  
     **surfactants**)
- IT **Surfactants**  
     (**nonionic**; invisible patches contg. bioadhesive polymers and  
     **surfactants**)
- IT Amines, biological studies  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
 USES (Uses)  
     (polyamines, nonpolymeric; invisible patches contg. bioadhesive  
     polymers and **surfactants**)
- IT Alcohols, biological studies  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);

# STN Columbus

- USES (Uses)  
(polyhydric, propoxylated; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Quaternary ammonium compounds, biological studies  
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
USES (Uses)  
(polymers; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Skin, disease  
(rash, drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics  
(skin-lightening; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Drug delivery systems  
(tapes; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics  
(wrinkle-preventing; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**  
(**zwitterionic**; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 36574-66-0D, N-coco acyl derivs.  
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
USES (Uses)  
(cocoamidopropylbetaine; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 68-26-8, Retinol 96-26-4, Dihydroxyacetone 814-71-1, Calcium **thioglycolate** 34452-51-2, Potassium **thioglycolate**  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 50-70-4, Sorbitol, biological studies 50-70-4D, Sorbitol, oligomers contg. 50-78-2, Aspirin 50-81-7, Vitamin C, biological studies 50-99-7D, Glucose, esters 50-99-7D, D-Glucose, oligomers contg. 55-56-1, Chlorhexidine 56-81-5, Glycerin, biological studies 56-86-0D, Glutamic acid, N-acyl derivs. 57-48-7D, Fructose, oligomers contg. 57-50-1D, Sucrose, esters 57-50-1D, Sucrose, oligomers contg. 57-55-6, Propylene glycol, biological studies 58-86-6D, Xylose, oligomers contg. 59-23-4D, Galactose, oligomers contg. 59-87-0, Nitrofurazone 60-54-8, Tetracycline 69-65-8D, Mannitol, oligomers contg. 69-72-7, Salicylic acid, biological studies 69-79-4D, Maltose, oligomers contg. 87-99-0D, Xylitol, oligomers contg. 106-11-6, Diethylene glycol monostearate 107-36-8D, Isethionic acid, cocoyl derivs. 108-46-3, Resorcinol, biological studies 108-95-2, Phenol, biological studies 114-07-8, Erythromycin 115-83-3, Pentaerythritol tetrastearate 144-55-8, Sodium bicarbonate, biological studies 151-21-3, Sodium lauryl sulfate, biological studies 404-86-4, Capsaicin 497-19-8, Sodium carbonate, biological studies 585-86-4D, Lactitol, oligomers contg. 585-88-6D, Maltitol, oligomers contg. 770-35-4, Phenoxyisopropanol 1338-41-6, Sorbitan monostearate 1406-18-4, Vitamin E 2216-51-5 3380-34-5, Triclosan 3458-28-4D, D-Mannose, oligomers contg. 6284-40-8 7439-97-6, Mercury, biological studies 7440-22-4, Silver, biological studies 7553-56-2, Iodine, biological studies 8011-96-9, Calamine 8050-81-5, Simethicone 9000-01-5, Gum arabic 9002-89-5, Polyvinyl alcohol 9002-98-6 9003-05-8, Polyacrylamide 9003-39-8, Polyvinylpyrrolidone 9004-64-2, Hydroxypropyl cellulose 9005-25-8, Starch, biological studies 9005-25-8D, Starch, hydrolyzates 9005-64-5, Polysorbate 20 9011-13-6, Styrene-maleic anhydride copolymer

# STN Columbus

9011-16-9, Methyl vinyl ether-maleic anhydride copolymer 11099-07-3, Glycerin stearate 11111-12-9, Cephalosporin 11140-06-0, Glycerin palmitate 12694-22-3, Diglyceryl monostearate 13718-94-0D, Palatinose, oligomers contg. 15687-27-1, Ibuprofen 18323-44-9, Clindamycin 25322-68-3, Polyethylene glycol 25322-69-4 25655-41-8, Povidone iodine 26658-19-5, Sorbitan tristearate 27195-16-0, Sucrose distearate 30233-64-8, Glyceryl monobehenate 39529-26-5, Decaglyceryl decastearate 42852-72-2 53998-08-6, Sarcosinate 63119-59-5, Diglycerin distearate 68424-04-4, Polydextrose 71185-87-0, Hexaglyceryl tristearate 75537-01-8, Gantrez S-97 95461-64-6, Decaglyceryl pentastearate 99734-29-9, Tetraglyceryl tristearate 99880-64-5, Glyceryl dibehenate 106392-12-5, Polyoxyethylene polyoxypropylene block copolymer  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
 USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

IT 56-75-7, Chloramphenicol 94-09-7, Benzocaine

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

=> d his

(FILE 'HOME' ENTERED AT 00:05:08 ON 23 MAY 2009)

FILE 'CAPLUS' ENTERED AT 00:05:27 ON 23 MAY 2009

S 22811-02-5/REG# OR 10220-46-9/REG# OR 2917-26-2/REG# OR 28

FILE 'REGISTRY' ENTERED AT 00:12:43 ON 23 MAY 2009

L1 1 S 2885-00-9/RN

FILE 'CAPLUS' ENTERED AT 00:12:44 ON 23 MAY 2009

L2 2011 S L1

FILE 'REGISTRY' ENTERED AT 00:12:44 ON 23 MAY 2009

L3 1 S 2917-26-2/RN

FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009

L4 1621 S L3

FILE 'REGISTRY' ENTERED AT 00:12:45 ON 23 MAY 2009

L5 1 S 10220-46-9/RN

FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009

L6 50 S L5

FILE 'REGISTRY' ENTERED AT 00:12:46 ON 23 MAY 2009

L7 1 S 22811-02-5/RN

FILE 'CAPLUS' ENTERED AT 00:12:46 ON 23 MAY 2009

L8 6 S L7

L9 32684 S L8 OR L6 OR L4 OR L2 OR THIOGLYCOLATE OR MERCAPTOACETATE OR H

L10 84695 S (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFAC

L11 319 S L9 AND L10

L12 6680 S METAL TREAT#### OR TREAT##### METAL

L13 1 S L11 AND L12

L14 522045 S SILVER OR AG

L15 12 S L11 AND L14

L16 1173 S (NONIONIC OR NON-IONIC) AND ANIONIC AND ZWITTERIONIC AND SURF

## STN Columbus

L17 3 S L11 AND L16

=&gt; s l11 and l14

L18 12 L11 AND L14

=&gt; s l18 not l15

L19 0 L18 NOT L15

=&gt; d l18 1-12 all

L18 ANSWER 1 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2008:1046144 CAPLUS

DN 149:312963

ED Entered STN: 29 Aug 2008

TI Preparation of conductive supported noble metal nanoparticle catalysts

IN Stucky, Galen D.; Zheng, Nanfeng

PA The Regents of the University of California, USA

SO U.S. Pat. Appl. Publ., 35pp.

CODEN: USXXCO

DT Patent

LA English

INCL 428403000; 216055000; 428402000; 264005000; 264007000; 502100000;  
502300000; 502159000; 502355000; 502350000

CC 56-4 (Nonferrous Metals and Alloys)

Section cross-reference(s): 57, 67

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 20080206562	A1	20080828	US 2008-13436	20080112
PRAI	US 2007-884668P	P	20070112		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 20080206562	INCL	428403000; 216055000; 428402000; 264005000; 264007000; 502100000; 502300000; 502159000; 502355000; 502350000
	IPCI	B32B0015-02 [I,A]; C23F0001-00 [I,A]; B29B0009-00 [I,A]; B29B0009-16 [I,A]; B01J0031-06 [I,A]; B01J0021-04 [I,A]; B01J0021-08 [I,A]; B01J0023-34 [I,A]; B01J0023-16 [I,C*]; B01J0029-00 [I,A]; B01J0021-18 [I,A]; B01J0021-00 [I,C*]; B01J0027-06 [I,A]; B01J0023-42 [I,A]; B01J0023-44 [I,A]; B01J0023-50 [I,A]; B01J0023-52 [I,A]; B01J0023-48 [I,C*]; B01J0027-02 [I,A]; B01J0027-24 [I,A]; B01J0031-02 [I,A]; B01J0023-755 [I,A]; B01J0031-26 [I,A]
	NCL	428/403.000; 216/055.000; 216/083.000; 264/005.000; 264/007.000; 428/402.000; 502/080.000; 502/087.000; 502/100.000; 502/150.000; 502/159.000; 502/167.000; 502/168.000; 502/171.000; 502/180.000; 502/181.000; 502/200.000; 502/216.000; 502/232.000; 502/300.000; 502/325.000; 502/337.000; 502/339.000; 502/340.000; 502/344.000; 502/345.000; 502/347.000; 502/349.000; 502/350.000; 502/355.000

AB The prepn. of elec.-conductive noble metal nanoparticle catalysts on catalyst supports such as alumina, silica, titania, clays, zeolites, or carbon black, is described.

ST gold **silver** palladium nanocatalyst support sol gel micelle ceramic

IT Solvents

(aprotic; prepn. of conductive supported noble metal nanoparticle

- catalysts)
- IT Polyethers, uses  
RL: MOA (Modifier or additive use); USES (Uses)  
(arom., alkyl-, **surfactants**; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Thiols, uses  
RL: MOA (Modifier or additive use); USES (Uses)  
(caps on catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Bentonite, processes  
Carbon black, processes  
Clays, processes  
Diatomite  
Silica gel, processes  
Zeolites (synthetic), processes  
RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)  
(catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Nanoparticles  
(catalysts; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Alcohols, uses  
RL: MOA (Modifier or additive use); USES (Uses)  
(ethoxylated, **surfactants**; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Hydrocarbons, processes  
RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)  
(fluoro, catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT **Surfactants**  
(in coatings; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Electroluminescent devices  
Molecular electronic devices  
Optoelectronics  
Secondary batteries  
Semiconductor devices  
Sensors  
Solar cells  
(nanocatalysts for; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Photolysis catalysts  
(nanocatalysts; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Catalysts  
Semiconductor materials  
(nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT **Surfactants**  
(**nonionic**; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Silsesquioxanes  
RL: RGT (Reagent); RACT (Reactant or reagent)  
(octyl- and hexyl-; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Dyes  
(org.-, functional mol.; prepn. of conductive supported noble metal nanoparticle catalysts)

# STN Columbus

- IT Calcination  
Catalyst supports  
Etching  
Reducing agents  
(prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 7440-44-0, Carbon, processes  
RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)  
(activated, catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 64-17-5, Ethanol, uses  
RL: NUU (Other use, unclassified); USES (Uses)  
(buffer soln.; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 49543-63-7, 4-(tert-Butyl)benzyl **mercaptan**  
RL: MOA (Modifier or additive use); USES (Uses)  
(cap on nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1322-36-7, Dodecanethiol  
RL: MOA (Modifier or additive use); USES (Uses)  
(caps on catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 7440-02-0P, Nickel, preparation 7440-05-3P, Palladium, preparation  
7440-06-4P, Platinum, preparation 7440-22-4P, **Silver**,  
preparation 7440-50-8P, Copper, preparation 7440-57-5P, Gold,  
preparation 12006-51-8P, AuCu  
RL: CAT (Catalyst use); SPN (Synthetic preparation); PREP (Preparation);  
USES (Uses)  
(catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1309-48-4, Magnesium oxide (MgO), processes 1314-23-4, Zirconia,  
processes 1344-28-1, Aluminum oxide (Al<sub>2</sub>O<sub>3</sub>), processes 7631-86-9,  
Silica, processes 7782-42-5, Graphite, processes 13463-67-7, Titania,  
processes  
RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)  
(catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1306-38-3, Cerium oxide (CeO<sub>2</sub>), uses 1313-13-9, Manganese oxide (MnO<sub>2</sub>),  
uses 1313-96-8, Niobium oxide (Nb<sub>2</sub>O<sub>5</sub>)  
RL: MOA (Modifier or additive use); USES (Uses)  
(coatings on colloidal silica; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 12638-19-6P  
RL: CAT (Catalyst use); SPN (Synthetic preparation); PREP (Preparation);  
USES (Uses)  
(nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 2966-50-9, **Silver** trifluoroacetate 14024-17-0, Iron acetyl  
acetate 14024-61-4 14024-64-7 16902-59-3 17927-72-9 19443-16-4  
19443-17-5 23894-00-0 23894-03-3 24772-51-8 27858-32-8, Titanium  
diisopropoxide bis(ethyl acetoacetate) 62905-51-5 65574-21-2  
65583-10-0 66197-44-2 82269-80-5 93918-06-0, Aluminum sec-butoxide  
bis(ethyl acetoacetate) 98719-26-7 140190-96-1 144665-26-9  
204522-78-1 299957-41-8 380240-62-0 1050499-47-2 1050499-48-3  
1050499-49-4 1050499-50-7 1050499-51-8 1050499-52-9 1050499-53-0  
1050499-54-1  
RL: RCT (Reactant); RACT (Reactant or reagent)  
(precursors; prepn. of conductive supported noble metal nanoparticle catalysts)



## STN Columbus

- IT 1313-99-1, Nickel oxide, uses 1345-25-1, Ferrous oxide, uses  
11104-61-3, Cobalt oxide  
RL: MOA (Modifier or additive use); USES (Uses)  
(prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 78-07-9, Ethyltriethoxysilane 78-10-4, Tetraethoxysilane 681-84-5,  
Tetramethoxysilane 682-01-9, Tetrapropoxysilane 1185-55-3,  
Methyltrimethoxysilane 1336-21-6, Ammonium hydroxide ((NH4)(OH))  
2031-67-6, Methyltriethoxysilane 4766-57-8, Tetrabutoxysilane  
30232-12-3 192082-40-9, Mercaptoundecanoic acid  
RL: RGT (Reagent); RACT (Reactant or reagent)  
(prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1722-26-5, Triethylamine-borane 4856-95-5 7337-45-3,  
tert-Butylamine-borane 13774-81-7, Ammonia-borane  
RL: RGT (Reagent); RACT (Reactant or reagent)  
(reducing agents; prepn. of conductive supported noble metal  
nanoparticle catalysts)
- IT 67-66-3, Chloroform, uses 71-43-2, Benzene, uses 75-09-2,  
Dichloromethane, uses 108-88-3, Toluene, uses 110-54-3, Hexane, uses  
110-82-7, Cyclohexane, uses  
RL: NUU (Other use, unclassified); USES (Uses)  
(solvent; prepn. of conductive supported noble metal nanoparticle  
catalysts)
- IT 14243-64-2  
RL: PEP (Physical, engineering or chemical process); PROC (Process)  
(substrates; prepn. of conductive supported noble metal nanoparticle  
catalysts)
- IT 577-11-7, Sodium bis(2-ethylhexyl) sulfosuccinate 9002-89-5, Polyvinyl  
alcohol 9002-92-0, Brij 30 9004-98-2, Brij 97 9036-19-5,  
(Octylphenoxy)polyethoxyethanol 12441-09-7D, Sorbitan, ester derivs.  
27251-32-7  
RL: MOA (Modifier or additive use); USES (Uses)  
(**surfactants**; prepn. of conductive supported noble metal  
nanoparticle catalysts)

L18 ANSWER 2 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2007:415891 CAPLUS

DN 146:463862

ED Entered STN: 16 Apr 2007

TI Discoloration prevention of metals using organic ultra-thin films and  
methods therefor

IN Liang, Chenghao; Yang, Changjiang; Huang, Naibao

PA Dalian Maritime University, Peop. Rep. China

SO Faming Zhuanli Shenqing Gongkai Shuomingshu, 10pp.

CODEN: CNXXEV

DT Patent

LA Chinese

CC 42-10 (Coatings, Inks, and Related Products)

Section cross-reference(s): 46, 56

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----	----	-----	-----	-----
PI	CN 1943882	A	20070411	CN 2006-10134093	20061026
PRAI	CN 2006-10134093		20061026		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
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CN 1943882	IPC1	B05D0007-14 [I,A]; B05D0007-24 [I,A]; B05D0003-10 [I,A]; C23C0022-05 [I,A]; C07C0321-04 [I,A]; C07C0321-00 [I,C*]

## STN Columbus

IPCR B05D0007-14 [I,C]; B05D0007-14 [I,A]

OS MARPAT 146:463862

AB Film-forming solns. contain 0.001-1 mol/L alkyl thiols and 0.001-1 mol/L **surfactants**. Thus, a coating soln. on **Ag** contained stearyl thiol 15, polyethylene glycol nonylphenyl ether 7, hexadecyltrimethylammonium bromide 2, Pluronic 64 7 g/L.

ST metal discoloration prevention coating **surfactant** thiol; **silver** discoloration prevention coating **surfactant** thiol

IT **Surfactants**  
(**anionic**; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT **Surfactants**  
(cationic; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT Discoloration prevention  
(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT Quaternary ammonium compounds, uses  
Thiols, uses  
RL: TEM (Technical or engineered material use); USES (Uses)  
(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT Coating materials  
(discoloration-resistant; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT 691397-13-4, Pluronic L 64  
RL: TEM (Technical or engineered material use); USES (Uses)  
(Pluronic L 64; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT 57-09-0, Hexadecyltrimethylammonium bromide **2885-00-9**, Stearylmercaptan 7440-22-4, **Silver**, uses 9016-45-9, Polyethylene glycol nonylphenyl ether  
RL: TEM (Technical or engineered material use); USES (Uses)  
(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

L18 ANSWER 3 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2007:150387 CAPLUS

DN 146:236227

ED Entered STN: 09 Feb 2007

TI Conductive adhesive composition comprising pressure sensitive adhesive and electrolyte

IN Menon, Vinod P.; Kumar, Kanta; Nelson, Carl T.; Rizzardi, Don A.

PA 3M Innovative Properties Company, USA

SO U.S. Pat. Appl. Publ., 20pp.  
CODEN: USXXCO

DT Patent

LA English

INCL 600391000; 600392000; 252500000

CC 63-7 (Pharmaceuticals)

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 20070032719	A1	20070208	US 2005-197216	20050804
	AU 2006278717	A1	20070215	AU 2006-278717	20060801
	CA 2617273	A1	20070215	CA 2006-2617273	20060801
	WO 2007019115	A1	20070215	WO 2006-US29794	20060801
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD,				

## STN Columbus

GE, GH, GM, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP,  
 KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN,  
 MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU,  
 SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG,  
 US, UZ, VC, VN, ZA, ZM, ZW  
 RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,  
 IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ,  
 CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH,  
 GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY,  
 KG, KZ, MD, RU, TJ, TM  
 EP 1917318 A1 20080507 EP 2006-789019 20060801  
 R: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,  
 IS, IT, LI, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR  
 JP 2009503235 T 20090129 JP 2008-525088 20060801  
 MX 2008001425 A 20080416 MX 2008-1425 20080129  
 KR 2008040689 A 20080508 KR 2008-702725 20080201  
 CN 101238189 A 20080806 CN 2006-80028822 20080204  
 IN 2008CN00571 A 20081128 IN 2008-CN571 20080204  
 PRAI US 2005-197216 A 20050804  
 WO 2006-US29794 W 20060801

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 20070032719	INCL	600391000; 600392000; 252500000
	IPCI	A61B0005-04 [I,A]; H01B0001-12 [I,A]; H01B0001-00 [I,A]
	IPCR	A61B0005-04 [I,C]; A61B0005-04 [I,A]; H01B0001-00 [I,C]; H01B0001-00 [I,A]; H01B0001-12 [I,C]; H01B0001-12 [I,A]
	NCL	600/391.000; 252/500.000; 600/392.000
	ECLA	C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4; C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L
AU 2006278717	IPCI	C09J0009-00 [I,C]; C09J0009-02 [I,A]
	IPCR	C09J0009-00 [I,C]; C09J0009-02 [I,A]
	ECLA	C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4; C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L
CA 2617273	IPCI	A61B0005-0408 [I,A]; A61B0018-14 [I,A]; A61K0050-00 [I,A]; A61N0001-04 [I,A]; C09J0009-02 [I,A]; C09J0009-00 [I,C*]; C09J0011-06 [I,A]; C09J0011-02 [I,C*]
	IPCR	C09J0009-00 [I,C]; C09J0009-02 [I,A]; A61B0005-0408 [I,C]; A61B0005-0408 [I,A]; A61B0018-14 [I,C]; A61B0018-14 [I,A]; A61K0050-00 [I,C]; A61K0050-00 [I,A]; A61N0001-04 [I,C]; A61N0001-04 [I,A]; C09J0011-02 [I,C]; C09J0011-06 [I,A]
WO 2007019115	IPCI	C09J0009-02 [I,A]; C09J0009-00 [I,C*]
	IPCR	C09J0009-00 [I,C]; C09J0009-02 [I,A]
	ECLA	C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4; C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L
EP 1917318	IPCI	C09J0009-02 [I,A]; C09J0009-00 [I,C*]
	IPCR	C09J0009-00 [I,C]; C09J0009-02 [I,A]
JP 2009503235	IPCI	C09J0201-00 [I,A]; C09J0009-02 [I,A]; C09J0009-00 [I,C*]; C09J0004-02 [I,A]; A61L0024-00 [I,A]; A61N0001-04 [I,A]
	FTERM	4C053/BB04; 4C053/BB06; 4C053/BB07; 4C053/BB23; 4C053/BB35; 4C053/BB36; 4C081/AA10; 4C081/AA12; 4C081/AC04; 4C081/BB03; 4C081/BB04; 4C081/CA061; 4C081/CA071; 4C081/CA081; 4C081/CA101; 4C081/CA16; 4C081/CA181; 4C081/CA211; 4C081/CA281; 4C081/CE07; 4C081/CE09; 4C081/CE10; 4C081/DA02; 4C081/DA12; 4C081/DB07; 4C081/DC03; 4C081/DC04; 4J040/FA041;

# STN Columbus

4J040/FA081; 4J040/FA091; 4J040/FA101; 4J040/FA131;  
4J040/FA141; 4J040/FA161; 4J040/FA281; 4J040/FA291;  
4J040/HB04; 4J040/HB10; 4J040/HB11; 4J040/HB14;  
4J040/HC01; 4J040/HD02; 4J040/HD18; 4J040/HD23;  
4J040/JA03; 4J040/JB09; 4J040/KA12; 4J040/KA13;  
4J040/KA32; 4J040/KA38; 4J040/KA39; 4J040/MA14;  
4J040/NA02

- MX 2008001425 IPCI C09J0009-02 [I,A]; C09J0009-00 [I,C\*]  
KR 2008040689 IPCI C09J0009-02 [I,A]; C09J0009-00 [I,C\*]  
CN 101238189 IPCI C09J0009-02 [I,A]; C09J0009-00 [I,C\*]  
IN 2008CN00571 IPCI C09J0009-02 [ICM,7]; C09J0009-00 [ICM,7,C\*]  
OS MARPAT 146:236227  
AB A conductive adhesive compn. is provided and articles that include the adhesive compn. as a component thereof. The conductive adhesive compn. comprises: (a) pressure sensitive adhesive; (b) electrolyte comprising water sol. or water dispersible org. chloride; and (c) humectant. In some embodiments, the conductive adhesive compn. is a bicontinuous compn. comprising an aq. phase and an oil phase, and the bicontinuous compn. may be derived from a polymerizable microemulsion compn., the microemulsion compn. comprising: an aq. phase comprising one or more hydrophilic monomers or oligomers and/or one or more amphiphilic monomers or oligomers in water, the water-sol. or water-dispersible org. chloride, **surfactant** and humectant; and an oil phase comprising one or more hydrophobic monomers or oligomers. Biomedical articles such as biomedical electrodes, may incorporate the foregoing adhesive as a component. For example, adhesive precursor comprised of acrylic acid 15 g, 2-hydroxyethyl methacrylate 20 g, tetrakis(hydroxymethyl)phosphonium chloride 11 g, 1,3-butylene glycol 25 g, glycerol 10 g, water 19 g, Irgacure 2959 0.55 g and polyethylene glycol diacrylate 0.15 g. The precursor was coated using a knife coater onto a release liner as substrate. The knife was set so that a 25 mil (0.64 mm) thick coating was obtained. Polymn. was induced in the coated microemulsion by exposure to UV radiation. A total dose of 1800 mJ/cm<sup>2</sup> was applied over approx. 7 min, forming a conductive, bicontinuous adhesive. This conductive adhesive had an excellent adhesion to human skin.  
ST polymer acrylate electrolyte chloride conductive adhesive  
IT Polyurethanes, biological studies  
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(acrylates; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)  
IT Electric conductors  
(adhesive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)  
IT Fats and Glyceridic oils, biological studies  
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(almond, amidopropalkonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)  
IT **Surfactants**  
(**anionic**; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)  
IT Fats and Glyceridic oils, biological studies  
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(avocado, amidopropalkonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)  
IT **Surfactants**  
(**cationic**; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)  
IT Onium compounds  
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(chloride; conductive adhesive compn. comprising pressure sensitive

- adhesive and electrolyte)
- IT Quaternary ammonium compounds, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (chlorides; conductive adhesive compn. comprising pressure sensitive  
 adhesive and electrolyte)
- IT Fatty acids, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (coco, trimethylammonium chloride; conductive adhesive compn.  
 comprising pressure sensitive adhesive and electrolyte)
- IT Chain transfer agents  
 Crosslinking agents  
 Electrodes  
 Electrolytes  
 Human  
 Humectants  
 Hydrogels  
**Surfactants**  
 (conductive adhesive compn. comprising pressure sensitive adhesive and  
 electrolyte)
- IT Alcohols, uses  
 Thiols, uses  
 RL: NUU (Other use, unclassified); USES (Uses)  
 (conductive adhesive compn. comprising pressure sensitive adhesive and  
 electrolyte)
- IT Acrylic polymers, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (conductive adhesive compn. comprising pressure sensitive adhesive and  
 electrolyte)
- IT Sulfonium compounds  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (conductive adhesive compn. comprising pressure sensitive adhesive and  
 electrolyte)
- IT Adhesives  
 (conductive; conductive adhesive compn. comprising pressure sensitive  
 adhesive and electrolyte)
- IT Soybean oil  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (dimethylammonium chloride; conductive adhesive compn. comprising  
 pressure sensitive adhesive and electrolyte)
- IT **Surfactants**  
 (**nonionic**; conductive adhesive compn. comprising pressure  
 sensitive adhesive and electrolyte)
- IT Chlorides, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (org.; conductive adhesive compn. comprising pressure sensitive  
 adhesive and electrolyte)
- IT Adhesives  
 (pressure-sensitive; conductive adhesive compn. comprising pressure  
 sensitive adhesive and electrolyte)
- IT Fatty acids, biological studies  
 RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
 (tallow, bishydroxyethyl/dime quaternary ammonium compds.; conductive  
 adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 558-13-4, Carbon tetrabromide 25103-09-7, Isooctyl **thioglycolate**  
 , uses  
 RL: NUU (Other use, unclassified); USES (Uses)  
 (conductive adhesive compn. comprising pressure sensitive adhesive and  
 electrolyte)
- IT 1070-70-8, 1,4-Butanediol diacrylate 1321-74-0, Divinylbenzene,  
 reactions 10526-04-2, 1,8-Octanediol diacrylate 13048-33-4,

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1,6-Hexanediol diacrylate

RL: RCT (Reactant); RACT (Reactant or reagent)

(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT 56-34-8, Tetraethylammonium chloride 56-37-1, Benzyltriethylammonium chloride 56-81-5, Glycerin, biological studies 56-93-9, Benzyltrimethylammonium chloride 57-55-6, Propylene glycol, biological studies 67-48-1 77-99-6, Trimethylolpropane 88-12-0D, polymer 107-21-1, Ethylene glycol, biological studies 107-88-0, 1,3-Butanediol 110-63-4, 1,4-Butanediol, biological studies 112-00-5, Dodecyltrimethylammonium chloride 112-02-7, Hexadecyltrimethylammonium chloride 112-03-8, Octadecyltrimethylammonium chloride 124-64-1, Tetrakis(hydroxymethyl)phosphonium chloride 139-08-2, Tetradecyldimethylbenzylammonium chloride 593-81-7D, Trimethylammonium chloride, coco fatty acid derivs. 7173-51-5 9004-98-2, Brij 98 9042-76-6 17301-53-0, Behenyltrimethylammonium chloride 24567-53-1, Phosphonium chloride 25265-71-8, Dipropylene glycol 26570-48-9, Polyethylene oxide diacrylate 26597-36-4 32862-91-2, Oxonium chloride 60182-11-8, Polyethylene glycol acrylate 93507-51-8 106797-53-9, IRGACURE 2959 123776-56-7 145687-02-1, Pemulen TR 2 463965-14-2 923929-97-9 923929-99-1 924299-17-2, Hetoxol OL 35

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT 7783-90-6, **Silver** chloride, biological studies

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(conductive ink soln.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

L18 ANSWER 4 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2005:1062684 CAPLUS

DN 143:351549

ED Entered STN: 05 Oct 2005

TI Water-based sulfur-containing composition chemical mechanical polishing of nonferrous metals

IN Johns, Peter Gamon; Harrison, Clare Elizabeth

PA Middlesex Silver Co. Limited, UK

SO Brit. UK Pat. Appl., 29 pp.

CODEN: BAXXDU

DT Patent

LA English

IC ICM C23F011-16

ICS C23F011-00

CC 57-7 (Ceramics)

Section cross-reference(s): 56

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	GB 2412666	A	20051005	GB 2004-7163	20040330
	GB 2412666	B	20081008		
	AU 2005229275	A1	20051013	AU 2005-229275	20050324
	CA 2559989	A1	20051013	CA 2005-2559989	20050324
	WO 2005095675	A1	20051013	WO 2005-GB50043	20050324
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW				

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RW: BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM,  
 AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK,  
 EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT,  
 RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML,  
 MR, NE, SN, TD, TG

EP 1730325 A1 20061213 EP 2005-718135 20050324  
 R: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,  
 IS, IT, LI, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR  
 CN 1946878 A 20070411 CN 2005-80013434 20050324  
 JP 2007537354 T 20071220 JP 2007-505641 20050324  
 IN 2006DN05356 A 20070713 IN 2006-DN5356 20060915  
 MX 2006010964 A 20061116 MX 2006-10964 20060925  
 US 20070277906 A1 20071206 US 2007-594477 20070702  
 PRAI GB 2004-7163 A 20040330  
 WO 2005-GB50043 W 20050324

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
GB 2412666	ICM	C23F011-16
	ICS	C23F011-00
	IPCI	C23F0011-10 [I,C]; C23F0011-16 [I,A]; C23F0011-00 [I,C]; C23F0011-00 [I,A]
	IPCR	C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]
	ECLA	C23F011/16; C23F011/16B
AU 2005229275	IPCI	C11D0003-00 [I,C*]; C09G0001-00 [I,C*]; C11D0003-34 [I,C*]; C11D0011-00 [I,C*]; C23F0011-10 [I,C*]; C11D0003-00 [I,A]; C09G0001-02 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C23F0011-16 [I,A]
	IPCR	C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
CA 2559989	IPCI	C09G0001-02 [I,A]; C09G0001-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C23F0011-16 [I,A]; C23F0011-10 [I,C*]
	IPCR	C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00 [I,C]; C09G0001-02 [I,A]; C11D0003-00 [I,C]; C11D0003-00 [I,A]; C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00 [I,C]; C11D0011-00 [I,A]
	ECLA	C23F011/16; C23F011/16B
WO 2005095675	IPCI	C23F0011-16 [ICM, 7]; C23F0011-10 [ICM, 7, C*]; C11D0003-00 [ICS, 7]; C11D0003-34 [ICS, 7]; C11D0011-00 [ICS, 7]; C09G0001-02 [ICS, 7]; C09G0001-00 [ICS, 7, C*]
	IPCR	C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
EP 1730325	IPCI	C23F0011-16 [I,A]; C23F0011-10 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C09G0001-02 [I,A]; C09G0001-00 [I,C*]
	IPCR	C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00 [I,C]; C09G0001-02 [I,A]; C11D0003-00 [I,C]; C11D0003-00 [I,A]; C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00 [I,C]; C11D0011-00 [I,A]
	ECLA	C23F011/16; C23F011/16B

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CN 1946878 IPCI C23F0011-16 [I,A]; C23F0011-10 [I,C\*]; C11D0003-00 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C09G0001-02 [I,A]; C09G0001-00 [I,C\*]  
 IPCR C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00 [I,C\*]; C09G0001-02 [I,A]; C11D0003-00 [I,C\*]; C11D0003-00 [I,A]; C11D0003-34 [I,C\*]; C11D0003-34 [I,A]; C11D0011-00 [I,C\*]; C11D0011-00 [I,A]  
 ECLA C23F011/16; C23F011/16B  
 JP 2007537354 IPCI C23C0022-58 [I,A]; C11D0003-34 [I,A]; C23C0022-68 [I,A]; C23C0022-05 [I,C\*]; C11D0003-20 [I,A]; C11D0001-52 [I,A]; C11D0001-38 [I,C\*]; C11D0001-72 [I,A]; C11D0001-79 [I,A]; C11D0001-755 [I,A]; C11D0001-75 [I,A]; C11D0001-722 [I,A]; C11D0001-14 [I,A]; C11D0001-02 [I,C\*]; C11D0001-90 [I,A]; C11D0001-88 [I,C\*]; C11D0003-04 [I,A]; C11D0001-68 [I,A]; C09K0003-14 [I,A]  
 IPCR C23C0022-05 [I,C]; C23C0022-58 [I,A]; C09G0001-00 [I,C\*]; C09G0001-02 [I,A]; C09K0003-14 [I,C]; C09K0003-14 [I,A]; C11D0001-02 [I,C]; C11D0001-14 [I,A]; C11D0001-38 [I,C]; C11D0001-52 [I,A]; C11D0001-68 [I,C]; C11D0001-68 [I,A]; C11D0001-72 [I,C]; C11D0001-72 [I,A]; C11D0001-722 [I,C]; C11D0001-722 [I,A]; C11D0001-75 [I,C]; C11D0001-75 [I,A]; C11D0001-755 [I,C]; C11D0001-755 [I,A]; C11D0001-79 [I,C]; C11D0001-79 [I,A]; C11D0001-88 [I,C]; C11D0001-90 [I,A]; C11D0003-00 [I,C\*]; C11D0003-00 [I,A]; C11D0003-04 [I,C]; C11D0003-04 [I,A]; C11D0003-20 [I,C]; C11D0003-20 [I,A]; C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00 [I,C\*]; C11D0011-00 [I,A]; C23C0022-68 [I,A]; C23F0011-10 [I,C\*]; C23F0011-16 [I,A]  
 FTERM 4H003/AB27; 4H003/AC02; 4H003/AC10; 4H003/AC13; 4H003/AD04; 4H003/BA12; 4H003/DA15; 4H003/EA12; 4H003/EA19; 4H003/EB05; 4H003/EB18; 4H003/EB21; 4H003/ED02; 4H003/FA05; 4K026/AA01; 4K026/AA06; 4K026/CA15; 4K026/CA37; 4K026/DA02; 4K026/DA03  
 IN 2006DN05356 IPCI C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C\*]  
 MX 2006010964 IPCI C09G0001-02 [ICM,7]; C09G0001-00 [ICM,7,C\*]; C11D0011-00 [ICS,7]; C11D0003-00 [ICS,7]; C11D0003-34 [ICS,7]; C23F0011-16 [ICS,7]; C23F0011-10 [ICS,7,C\*]  
 US 20070277906 IPCI C23F0011-16 [I,A]; C23F0011-10 [I,C\*]; C09G0001-02 [I,A]; C09G0001-00 [I,C\*]; C11D0011-00 [I,A]; C11D0003-00 [I,A]; C11D0003-34 [I,A]  
 NCL 148/022.000  
 OS MARPAT 143:351549  
 AB A compn. and assocd. method of manuf. of a water based compn. comprising a treatment agent selected from an alkanethiol, alkyl thioglycollate, and dialkyl sulfide or dialkyl disulfide. The compn. also includes at least one of an amphoteric, **non-ionic** or cationic **surfactant**, where the treatment agent is directly dissolved or dispersed the water contg. the amphoteric, **non-ionic** or cationic **surfactant**. The compn. is particularly useful for the treatment of **Ag**-Cu-Ge alloy, copper, brass, and nickel. A solid polishing medium can also be included in the compn., for example, silica or pptd. chalk, alumina, or silica.  
 ST chalk alumina silica alkanethiol thioglycollate chem mech polishing copper  
 IT Thiols, processes  
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)  
 (alkanethiol; water-based sulfur-contg. compn. chem. mech. polishing of



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- metals)
- IT Disulfides  
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)  
(alkyl; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT Chalk  
Diatomite  
RL: TEM (Technical or engineered material use); USES (Uses)  
(as abrasive; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT **Surfactants**  
(cationic; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT Polishing  
(chem.-mech.; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT Polishing materials  
(paste; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT Thioethers  
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)  
(water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 1344-28-1, Alumina, uses  
RL: TEM (Technical or engineered material use); USES (Uses)  
(abrasive; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 9004-82-4, Sodium laureth sulfate  
RL: MOA (Modifier or additive use); USES (Uses)  
(**anionic surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 7631-86-9, Silica, uses  
RL: TEM (Technical or engineered material use); USES (Uses)  
(as abrasive; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 36574-66-0D, N-coco acyl derivs.  
RL: MOA (Modifier or additive use); USES (Uses)  
(cocamidopropyl betaine, **surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 7440-02-0, Nickel, processes 7440-50-8, Copper, processes 11144-43-7  
12597-71-6, Brass, processes 74969-69-0  
RL: PEP (Physical, engineering or chemical process); PYP (Physical process); PROC (Process)  
(polished substrate; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 62-56-6, Thiourea, uses **2885-00-9, Octadecyl mercaptan**  
RL: TEM (Technical or engineered material use); USES (Uses)  
(polishing compn. component; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT **2917-26-2, Hexadecyl mercaptan**  
RL: MOA (Modifier or additive use); USES (Uses)  
(**surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 68-11-1D, alkyl esters  
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

STN Columbus

(water-based sulfur-contg. compn. chem. mech. polishing of metals)

RE.CNT 6 THERE ARE 6 CITED REFERENCES AVAILABLE FOR THIS RECORD  
RE

- (1) Anon; EP 0492487 A1 CAPLUS
- (2) Anon; GB 0956927 A
- (3) Anon; GB 1117510 A
- (4) Anon; US 3503883 A
- (5) Anon; US 3518098 A
- (6) Anon; US 5650385 A CAPLUS

L18 ANSWER 5 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2005:622423 CAPLUS  
DN 143:295501  
ED Entered STN: 19 Jul 2005  
TI Single Etch Patterning of Stacked **Silver** and Molybdenum Alloy Layers on Glass Using Microcontact Wave Printing  
AU Burdinski, Dirk; Brans, Harold J. A.; Decre, Michel M. J.  
CS Philips Research, Eindhoven, 5656 AA, Neth.  
SO Journal of the American Chemical Society (2005), 127(31), 10786-10787  
CODEN: JACSAT; ISSN: 0002-7863  
PB American Chemical Society  
DT Journal  
LA English  
CC 74-13 (Radiation Chemistry, Photochemistry, and Photographic and Other Reprographic Processes)  
Section cross-reference(s): 56  
AB Stacked thin layers of **silver** alloy (AgPdCu) and MoCr layers on 10  
× 15 cm<sup>2</sup> glass substrates were patterned by microcontact wave printing and etching. Patterns of etch-resistant **octadecanethiol** self-assembled monolayers (SAMs) were wave printed with regular backplane stabilized PDMS stamps. Pattern development was achieved by etching both metal layers in a single step, employing a nitric acid-based etching bath. Trifluoroacetic acid and a nitrite salt were identified as essential bath components for a homogeneous etching process. Etch defects could be eliminated by the addn. of a decanesulfonate, which stabilizes the SAM resist via a defect healing mechanism.  
ST etching **silver** molybdenum alloy electrode display  
IT Liquid crystal displays  
(active matrix; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing as electrodes for)  
IT **Surfactants**  
(**anionic**; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)  
IT Lithography  
(microcontact printing; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)  
IT Autocatalysis  
Electrodes  
Etching  
Glass substrates  
Self-assembled monolayers  
(single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)  
IT 64-19-7, Acetic acid, processes 76-05-1, Trifluoroacetic acid, processes 7632-00-0, Sodium nitrite 7664-38-2, Phosphoric acid, processes 7697-37-2, Nitric acid, processes

STN Columbus

RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)  
(etchant; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

IT 2885-00-9, 1-Octadecanethiol

RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

(ink, self-assembled monolayer; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

IT 188820-19-1 317855-00-8

RL: CPS (Chemical process); DEV (Device component use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)

(single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

IT 13419-61-9, Sodium decane sulfonate

RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)

(**surfactant** for etching soln.; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

RE.CNT 31 THERE ARE 31 CITED REFERENCES AVAILABLE FOR THIS RECORD  
RE

- (1) Addison, C; Chem Rev 1980, V80, P21 CAPLUS
- (2) Balbaud, F; Corros Sci 2000, V42, P1685 CAPLUS
- (3) Beake, B; J Chem Soc, Perkin Trans 2 1998, P1 CAPLUS
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L18 ANSWER 6 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2004:847649 CAPLUS

DN 141:353637

## STN Columbus

ED Entered STN: 15 Oct 2004  
 TI Pretreatment of **Ag**-alloy surface with organosulfur compounds for  
 tarnishing prevention  
 IN Johns, Peter Gammon; Harrison, Clare Elizabeth  
 PA Middlesex Silver Co. Limited, UK  
 SO PCT Int. Appl., 43 pp.  
 CODEN: PIXXD2  
 DT Patent  
 LA English  
 IC ICM C23F011-16  
 CC 56-6 (Nonferrous Metals and Alloys)  
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2004087996	A1	20041014	WO 2004-GB1373	20040330
	W:	AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, VZ, VN, YU, ZA, ZM, ZW			
	RW:	BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG			
	AU 2004225693	A1	20041014	AU 2004-225693	20040330
	CA 2520807	A1	20041014	CA 2004-2520807	20040330
	EP 1611267	A1	20060104	EP 2004-724313	20040330
	R:	AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, PL, SK			
	CN 1780937	A	20060531	CN 2004-80011375	20040330
	JP 2006523266	T	20061012	JP 2006-506057	20040330
	IN 2005DN04346	A	20070831	IN 2005-DN4346	20050926
	MX 2005010452	A	20060510	MX 2005-10452	20050928
	US 20070039665	A1	20070222	US 2005-551476	20050929
PRAI	GB 2003-7290	A	20030331		
	WO 2004-GB1373	W	20040330		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
WO 2004087996	ICM	C23F011-16
	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
AU 2004225693	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
CA 2520807	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
EP 1611267	IPCI	C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16; C23F011/16B
CN 1780937	IPCI	C23F0011-16 [I,A]; C23F0011-10 [I,C*]
	ECLA	C23F011/16; C23F011/16B
JP 2006523266	IPCI	C23F0011-00 [I,A]; C22C0005-06 [I,A]; C22C0005-08 [I,A]
	IPCR	C23F0011-00 [I,C]; C23F0011-00 [I,A]; C22C0005-06 [I,C]; C22C0005-06 [I,A]; C22C0005-08 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A]

## STN Columbus

FTERM 4K062/AA01; 4K062/BB21; 4K062/BC22; 4K062/FA16  
 IN 2005DN04346 IPCI C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C\*]  
 MX 2005010452 IPCI C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C\*]  
 ECLA C23F011/16; C23F011/16B  
 US 20070039665 IPCI C23G0001-00 [I,A]; C23C0022-58 [I,A]; C23C0022-05  
 [I,C\*]  
 NCL 148/271.000; 134/002.000

AB The **Ag** alloys contg. minor Ge (esp. **Ag**-Cu-Ge alloys) to decrease the fire stain discoloration are pretreated on the surface with an alkanethiol, alkyl thioglycollate, dialkyl sulfide, or dialkyl disulfide to prevent tarnishing. The treatment with organosulfur compds. is suitable for manufd. **Ag**-alloy articles to prevent tarnished appearance during transit and the subsequent extended display without special packaging. The **Ag**-alloy surface is optionally treated with aq. soln. contg. an alkanethiol, alkyl thioglycollate, dialkyl sulfide, or dialkyl disulfide, as well as a mixt. of **anionic surfactant** and amphoteric or **nonionic surfactant** to solubilize the treatment agent. The typical ternary alloy contains **Ag** 80-96, Cu 1-19.9, and Ge 0.1-5%.

ST **silver** copper germanium alloy tarnishing prevention organosulfur

IT **Surfactants**  
 (**anionic**, in tarnishing prevention; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT **Surfactants**  
 (in tarnishing prevention; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT **Surfactants**  
 (**nonionic**, in tarnishing prevention; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT Tarnishing  
 (prevention of; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT Thioethers  
 Thiols, uses  
 RL: TEM (Technical or engineered material use); USES (Uses)  
 (tarnishing prevention by; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT 7440-56-4, Germanium, uses  
 RL: MOA (Modifier or additive use); USES (Uses)  
 (**Ag** alloys contg., tarnishing prevention on; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT 106-94-5, n-Propyl bromide  
 RL: TEM (Technical or engineered material use); USES (Uses)  
 (solvent, in tarnishing prevention; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT **2885-00-9, Octadecyl mercaptan 2917-26-2, Cetyl mercaptan**  
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)  
 (tarnishing prevention by; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT 39282-03-6, Sterling **silver** 103221-24-5 476614-10-5  
 476614-12-7 476614-13-8  
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)  
 (tarnishing prevention on; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT 9080-17-5, Ammonium polysulfide  
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)

## STN Columbus

(test soln. with, for tarnishing; **Ag**-alloy surface treated  
with organosulfur compds. for tarnishing prevention)

RE.CNT 9 THERE ARE 9 CITED REFERENCES AVAILABLE FOR THIS RECORD  
RE

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L18 ANSWER 7 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:851241 CAPLUS

DN 139:330251

ED Entered STN: 30 Oct 2003

TI **Silver** (carboxylate-n-alkyl thiolate) particles for photothermographic  
of thermographic imaging

IN Ghyzel, Peter J.; Lelental, Mark; Dickinson, David A.; Pitt, Alan R.;  
Wear, Trevor J.

PA Eastman Kodak Company, USA

SO U.S., 14 pp.

CODEN: USXXAM

DT Patent

LA English

IC ICM G03C001-498

INCL 430619000; 430611000; 430620000; 430631000

CC 74-2 (Radiation Chemistry, Photochemistry, and Photographic and Other  
Reprographic Processes)

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 6638708	B1	20031028	US 2002-200417	20020722
	EP 1385047	A1	20040128	EP 2003-77179	20030710
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK				
	JP 2004054276	A	20040219	JP 2003-199297	20030718
PRAI	US 2002-200417	A	20020722		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 6638708	ICM	G03C001-498
	INCL	430619000; 430611000; 430620000; 430631000
	IPCI	G03C0001-498 [ICM, 7]
	IPCR	B41M0005-30 [I,C*]; B41M0005-323 [I,A]; G03C0001-498 [I,C*]; G03C0001-498 [I,A]
	NCL	430/619.000; 430/611.000; 430/620.000; 430/631.000
	ECLA	G03C001/498B; G03C001/498E1
EP 1385047	IPCI	G03C0001-498 [ICM, 7]
	IPCR	B41M0005-30 [I,C*]; B41M0005-323 [I,A]; G03C0001-498 [I,C*]; G03C0001-498 [I,A]
	ECLA	G03C001/498B; G03C001/498E1
JP 2004054276	IPCI	G03C0001-498 [ICM, 7]; B41M0005-30 [ICS, 7]
	IPCR	G03C0001-498 [I,A]; G03C0001-498 [I,C*]
	FTERM	2H026/AA07; 2H026/BB46; 2H123/AB00; 2H123/AB03; 2H123/AB25; 2H123/AB28; 2H123/BC00; 2H123/BC12; 2H123/CB00; 2H123/CB03

## STN Columbus

AB The present disclosure relates to dispersions of **silver**  
(carboxylate-n-alkyl thiolate). The carboxylates are typically **silver**  
salts of long chain fatty acids and the n-alkyl thiolate is preferably  
1-dodecanethiol. These **silver** (carboxylate-n-alkyl thiolate) particles  
can be used to formulate imaging forming compns. that are useful in aq.  
thermog. or photothermog. imaging elements.

ST photog emulsion **silver** carboxylate alkyl thiolate particle photothermog

IT Photographic emulsions  
(heat-developable; **silver** (carboxylate-n-alkyl thiolate)  
particles for photothermog. of thermog. imaging)

IT **Surfactants**  
(**nonionic**; **silver** (carboxylate-n-alkyl thiolate)  
particles for photothermog. of thermog. imaging)

IT Nanoparticles  
(**silver** (carboxylate-n-alkyl thiolate) particles for  
photothermog. of thermog. imaging)

IT 111-31-9, 1-Hexanethiol 112-55-0, 1-Dodecanethiol 112-85-6, Behenic  
acid **2885-00-9**, 1-Octadecanethiol

RL: TEM (Technical or engineered material use); USES (Uses)  
(**silver** (carboxylate-n-alkyl thiolate) particles for  
photothermog. of thermog. imaging)

RE.CNT 5 THERE ARE 5 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

(1) Anon; EP 0803764 A1 2001 CAPLUS

(2) Goffe; US 3666477 A 1972 CAPLUS

(3) Lelental; US 6391537 B2 2002 CAPLUS

(4) Voicu, R; Structure and Dynamics of Selectively Deuterated Self-Assembled  
Silver n-Octadecanethiolate Layered Materials P2266

(5) Voicu, R; Thermal Behavior of a Self-Assembled Silver n-Dodecanethiolate  
Layered Material Monitored by DSC P2642

L18 ANSWER 8 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:798402 CAPLUS

DN 139:311931

ED Entered STN: 12 Oct 2003

TI Metal coating of hair fibers for cosmetics

IN Vic, Gabin; Livoreil, Aude; Giroud, Franck

PA L'oreal, Fr.

SO Fr. Demande, 18 pp.  
CODEN: FRXXBL

DT Patent

LA French

IC ICM A61K007-075

CC 62-3 (Essential Oils and Cosmetics)

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----	----	-----	-----	-----
PI	FR 2838050	A1	20031010	FR 2002-4352	20020408
	FR 2838050	B1	20060714		
	CN 1449737	A	20031022	CN 2003-108449	20030331
	CN 1213719	C	20050810		
	BR 2003000873	A	20040817	BR 2003-873	20030403
	EP 1352630	A2	20031015	EP 2003-290860	20030407
	EP 1352630	A3	20040324		
	EP 1352630	B1	20060301		
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK				
	US 20030223944	A1	20031204	US 2003-407911	20030407
	JP 2003300840	A	20031021	JP 2003-104420	20030408

## STN Columbus

JP 3759120  
 PRAI FR 2002-4352  
 US 2002-372455P

B2 20060322  
 A 20020408  
 P 20020416

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
FR 2838050	ICM	A61K0007-075
	IPCI	A61K0007-075 [ICM, 7]
	IPCR	A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
	ECLA	A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10
CN 1449737	IPCI	A61K0007-06 [ICM, 7]; A61K0007-06 [ICS, 7]
	IPCR	A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
	ECLA	A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10
BR 2003000873	IPCI	A61K0007-06 [ICM, 7]
	IPCR	A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
	ECLA	A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10
EP 1352630	IPCI	A61K0008-19 [I,C]; A61K0008-30 [I,C]; A61Q0005-00 [I,C]; A61Q0005-10 [I,C]; A61Q0005-10 [I,A]; A61K0008-19 [I,A]; A61K0008-46 [I,A]; A61Q0005-00 [I,A]
	IPCR	A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61Q0005-10 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C]; A61K0008-30 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]



## STN Columbus

[I,C]; A61K0008-31 [I,A]; A61K0008-34 [I,A];  
A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46  
[I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C\*];  
A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891  
[I,A]; A61Q0001-02 [I,C\*]; A61Q0001-02 [I,A];  
A61Q0005-00 [I,C]; A61Q0005-00 [I,A]; A61Q0005-10  
[I,C]; A61Q0005-12 [I,C\*]; A61Q0005-12 [I,A]  
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;  
A61Q005/00; A61Q005/10  
US 20030223944 IPCI A61K0007-075 [ICM,7]; A61K0007-06 [ICS,7]  
IPCR A61K0008-19 [I,C\*]; A61K0008-19 [I,A]; A61K0008-30  
[I,C\*]; A61K0008-46 [I,A]; A61Q0005-12 [I,C\*];  
A61Q0005-12 [I,A]  
NCL 424/070.100; 510/119.000  
ECLA A61K008/19; A61K008/46; A61Q005/12  
JP 2003300840 IPCI A61K0008-00 [I,A]; A61Q0005-00 [I,A]; A61K0008-18  
[I,A]; A61Q0001-02 [I,A]  
IPCR A61K0008-00 [I,C\*]; A61K0008-00 [I,A]; A61K0008-18  
[I,C\*]; A61K0008-18 [I,A]; A61K0008-19 [I,C\*];  
A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23  
[I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A];  
A61K0008-27 [I,A]; A61K0008-30 [I,C\*]; A61K0008-31  
[I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A];  
A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64  
[I,A]; A61K0008-72 [I,C\*]; A61K0008-73 [I,A];  
A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02  
[I,C\*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C\*];  
A61Q0005-00 [I,A]; A61Q0005-10 [I,C\*]; A61Q0005-10  
[I,A]; A61Q0005-12 [I,C\*]; A61Q0005-12 [I,A]  
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;  
A61Q005/00; A61Q005/10  
AB The invention relates to a treatment process which confers cosmetic  
properties on hair fibers. The process consists of treating the fibers  
with a metal salt in the presence of a reducing agent, directly on the  
fiber to form the corresponding free metal. Thus, a lock of hair after  
being shampooed, was dried and an aq. soln. of AgNO<sub>3</sub> was applied onto the  
hair. After the addn. of NaBH<sub>4</sub>, the natural pigmented hair was dark, with  
metallic brilliance reflected on it.  
ST metal salt hair cosmetic  
IT Alcohols, biological studies  
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
(Uses)  
(C1-4; metal treatment of hair fibers for cosmetics)  
IT Alkanes, biological studies  
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
(Uses)  
(C5-10; metal treatment of hair fibers for cosmetics)  
IT Polyelectrolytes  
**Surfactants**  
(amphoteric; metal treatment of hair fibers for cosmetics)  
IT Fats and Glyceridic oils, biological studies  
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);  
PYP (Physical process); BIOL (Biological study); PROC (Process); USES  
(Uses)  
(animal; metal treatment of hair fibers for cosmetics)  
IT **Surfactants**  
(anionic; metal treatment of hair fibers for cosmetics)  
IT Polyelectrolytes

**Surfactants**

- (cationic; metal treatment of hair fibers for cosmetics)
- IT Cosmetics
  - (emollients; metal treatment of hair fibers for cosmetics)
- IT Sulfates, reactions
  - RL: RCT (Reactant); RACT (Reactant or reagent)
  - (hydrogen; metal treatment of hair fibers for cosmetics)
- IT Antifoaming agents
  - Antiperspirants
  - Cosmetics
  - Hair
  - Hair preparations
  - Perfumes
  - Pigments, nonbiological
  - Preservatives
  - Reducing agents
  - Shampoos
  - Sunscreens
  - Thickening agents
    - (metal treatment of hair fibers for cosmetics)
- IT Alkaline earth salts
  - Bromates
  - Carbonates, biological studies
  - Disulfides
  - Halides
  - Nitrates, biological studies
  - Paraffin oils
  - Phosphates, biological studies
  - Polymers, biological studies
  - Polysiloxanes, biological studies
  - Proteins
  - Rare earth salts
  - Sulfates, biological studies
  - Thioethers
  - Thiosulfates
  - Transition metal salts
  - Vitamins
  - RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)
  - (metal treatment of hair fibers for cosmetics)
- IT Bisulfites
  - Enzymes, reactions
  - Sulfites
  - Thiols, reactions
  - Thioredoxins
  - RL: RCT (Reactant); RACT (Reactant or reagent)
  - (metal treatment of hair fibers for cosmetics)
- IT Cosmetics
  - (moisturizers; metal treatment of hair fibers for cosmetics)
- IT **Surfactants**
  - (**nonionic**; metal treatment of hair fibers for cosmetics)
- IT Peroxysulfates
  - RL: RCT (Reactant); RACT (Reactant or reagent)
  - (peroxymonosulfates; metal treatment of hair fibers for cosmetics)
- IT Alcohols, biological studies
  - RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)
  - (polyhydric; metal treatment of hair fibers for cosmetics)

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- IT Sulfonic acids, biological studies  
 RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)  
 (salts; metal treatment of hair fibers for cosmetics)
- IT Sulfinic acids  
 Thiols, reactions  
 RL: RCT (Reactant); RACT (Reactant or reagent)  
 (salts; metal treatment of hair fibers for cosmetics)
- IT Salts, reactions  
 RL: RCT (Reactant); RACT (Reactant or reagent)  
 (thiol; metal treatment of hair fibers for cosmetics)
- IT Lactones  
 RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)  
 (thiolactones; metal treatment of hair fibers for cosmetics)
- IT Fats and Glyceridic oils, biological studies  
 RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)  
 (vegetable; metal treatment of hair fibers for cosmetics)
- IT 64-17-5, Ethanol, biological studies 67-63-0, Isopropanol, biological studies 67-64-1, Acetone, biological studies 78-93-3, Methyl ethyl ketone, biological studies 79-20-9, Methyl acetate 110-71-4 123-86-4, Butyl acetate 141-78-6, EtOAc, biological studies 7429-90-5D, Aluminum, salts 7439-89-6D, Iron, salts 7439-98-7D, Molybdenum, salts 7440-02-0D, Nickel, salts 7440-05-3D, Palladium, salts 7440-06-4D, Platinum, salts 7440-22-4D, **Silver**, salts 7440-31-5D, Tin, salts 7440-32-6D, Titanium, salts 7440-33-7D, Tungsten, salts 7440-36-0D, Antimony, salts 7440-50-8D, Copper, salts 7440-57-5D, Gold, salts 7440-66-6D, Zinc, salts 7440-74-6D, Indium, salts 7758-89-6, Cuprous chloride 7761-88-8, **Silver** nitrate, biological studies 7775-41-9, **Silver** fluoride 7783-89-3, **Silver** bromate 7783-90-6, **Silver** chloride, biological studies 7783-96-2, **Silver** iodide 7785-23-1, **Silver** bromide 7787-70-4, Cuprous bromide 10025-98-6, Dipotassium palladium tetrachloride 10294-26-5, **Silver** sulfate 10294-28-7, Gold tribromide 16903-35-8 16923-58-3, Disodium hexachloroplatinate 19045-66-0D, Thiocarbamic acid, salts 73506-93-1, Diethoxyethane  
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 (metal treatment of hair fibers for cosmetics)
- IT 50-81-7, Ascorbic acid, reactions 53-57-6, NaDPH 58-68-4, NaDH 68-11-1, Thioglycolic acid, reactions 77-92-9D, Citric acid, salts 106-51-4, 2,5-Cyclohexadiene-1,4-dione, reactions 123-31-9, Hydroquinone, reactions 280-64-8, 9-BBN 1758-73-2, Formamidinesulfinic acid **2885-00-9**, 1-Octadecanethiol 3483-12-3, Dithiothreitol 6838-83-1, Diisoamylborane 7772-98-7 7775-14-6 7803-51-2, Phosphine 13762-51-1 14451-43-5 16853-85-3 16940-66-2 17836-88-3 25895-60-7, Sodium cyanoborohydride 37318-49-3, Protein disulfide isomerase 56553-60-7 131760-67-3 145626-87-5  
 RL: RCT (Reactant); RACT (Reactant or reagent)  
 (metal treatment of hair fibers for cosmetics)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD  
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L18 ANSWER 9 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:737150 CAPLUS  
 DN 139:250305  
 ED Entered STN: 19 Sep 2003  
 TI Invisible patch for the controlled delivery of cosmetic, dermatological,  
 and pharmaceutical active ingredients onto the skin  
 IN Shefer, Adi; Shefer, Samuel  
 PA USA  
 SO U.S. Pat. Appl. Publ., 17 pp., Cont.-in-part of U. S. Ser. No. 91,935.  
 CODEN: USXXCO  
 DT Patent  
 LA English  
 IC ICM A61K031-715  
 ICS A61K009-70  
 INCL 424449000; 514061000  
 CC 63-6 (Pharmaceuticals)  
 Section cross-reference(s): 62

FAN.CNT 2

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 20030175333	A1	20030918	US 2003-376736	20030228
	US 20030175328	A1	20030918	US 2002-91935	20020306
	CA 2515098	A1	20040916	CA 2004-2515098	20040227
	WO 2004078122	A2	20040916	WO 2004-US6106	20040227
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PRAI	US 2002-91935	A2	20020306		
	US 2003-376736	A	20030228		
	WO 2004-US6106	W	20040227		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 20030175333	ICM	A61K031-715
	ICS	A61K009-70
	INCL	424449000; 514061000
	IPCI	A61K0031-715 [ICM,7]; A61K0009-70 [ICS,7]
	IPCR	A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61F0013-02 [I,C*]; A61F0013-02 [I,A]; A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-02 [I,C*]; A61K0008-02 [I,A]; A61K0008-11 [I,C*]; A61K0008-11 [I,A];

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 A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00;  
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 NCL 424/449.000  
 ECLA A61K008/02C; A61K008/35; A61K008/368; A61K008/44;  
 A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97;  
 A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00;  
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A61K0008-49 [I,A]; A61K0008-55 [I,A]; A61K0008-58 [I,A]; A61K0008-60 [I,A]; A61K0008-72 [I,C]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61K0008-84 [I,A]; A61K0008-88 [I,A]; A61K0009-70 [I,C]; A61K0009-70 [I,A]; A61K0045-00 [I,C]; A61K0045-00 [I,A]; A61K0047-10 [I,C]; A61K0047-10 [I,A]; A61K0047-12 [I,C]; A61K0047-12 [I,A]; A61K0047-14 [I,C]; A61K0047-14 [I,A]; A61K0047-16 [I,C]; A61K0047-18 [I,A]; A61K0047-20 [I,C]; A61K0047-20 [I,A]; A61K0047-22 [I,C]; A61K0047-22 [I,A]; A61K0047-24 [I,C]; A61K0047-24 [I,A]; A61K0047-28 [I,C]; A61K0047-28 [I,A]; A61K0047-32 [I,C]; A61K0047-32 [I,A]; A61K0047-34 [I,C]; A61K0047-34 [I,A]; A61K0047-36 [I,C]; A61K0047-36 [I,A]; A61K0047-38 [I,C]; A61K0047-38 [I,A]; A61K0047-42 [I,C]; A61K0047-42 [I,A]; A61M0037-00 [I,C\*]; A61M0037-00 [I,A]; A61Q0019-00 [I,C]; A61Q0019-00 [I,A]

FTERM 4C076/AA72; 4C076/AA95; 4C076/BB31; 4C076/CC01; 4C076/CC03; 4C076/CC04; 4C076/CC18; 4C076/DD03; 4C076/DD04; 4C076/DD07; 4C076/DD08; 4C076/DD09; 4C076/DD13; 4C076/DD17; 4C076/DD38A; 4C076/DD66A; 4C076/EE06A; 4C076/EE10A; 4C076/EE12A; 4C076/EE13A; 4C076/EE17A; 4C076/EE23A; 4C076/EE26A; 4C076/EE27; 4C076/EE30A; 4C076/EE31A; 4C076/EE32A; 4C076/EE38A; 4C076/FF31; 4C076/FF35; 4C083/AA112; 4C083/AB032; 4C083/AC122; 4C083/AC131; 4C083/AC181; 4C083/AC371; 4C083/AC391; 4C083/AC421; 4C083/AC441; 4C083/AC532; 4C083/AC682; 4C083/AC772; 4C083/AC781; 4C083/AC791; 4C083/AD041; 4C083/AD042; 4C083/AD051; 4C083/AD071; 4C083/AD072; 4C083/AD091; 4C083/AD111; 4C083/AD131; 4C083/AD151; 4C083/AD201; 4C083/AD202; 4C083/AD211; 4C083/AD241; 4C083/AD261; 4C083/AD271; 4C083/AD281; 4C083/AD282; 4C083/AD351; 4C083/AD391; 4C083/AD642; 4C083/AD662; 4C083/CC02; 4C083/DD12; 4C083/EE12; 4C083/EE13; 4C083/EE14; 4C083/EE16; 4C083/EE22; 4C084/AA17; 4C084/MA32; 4C084/MA63; 4C084/NA10; 4C084/ZA891

AB The present invention relates to a patch for controlled topical or transdermal delivery of effective levels of cosmetic, dermatol., and pharmaceutical active ingredients onto the skin, hair follicles, and sebaceous glands, with minimal discomfort and ease of use. The patch can be transparent or clear and comprises a rate-controlling matrix layer. The matrix layer comprises water-sensitive, bioadhesive, film forming polymers, a water sol. oligomer, and a **surfactant**. The cosmetic, dermatol., and pharmaceutical active ingredients are sol. or dispersed in the matrix. The patch becomes tacky when wetted and adheres onto the skin. The adhesive properties of the patch are sufficient to maintain the patch in place on the skin for the recommended treatment period while allowing the patch to be readily removed without causing skin irritation or leaving adhesive residue on the skin. For example, an antibiotic patch contained polyvinyl alc. 50, PVP 1, polysorbate 20 5, Maltrin 180 10, lactitol 5, glycerin 10, and chloramphenicol 0.55%.

ST patch bioadhesive polymer oligosaccharide **surfactant**; antibiotic patch PVA PVP polysorbate chloramphenicol

IT Glycosides

RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(alkyl polyglycosides; invisible patches contg. bioadhesive polymers and **surfactants**)

IT **Surfactants**

STN Columbus

- (amphoteric; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**  
(**anionic**; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**  
(cationic; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Essential oils  
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
USES (Uses)  
(clove; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Hair preparations  
(conditioners; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics  
(depilatories; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Acne  
Burn  
Dandruff  
Pruritus  
Rhus diversiloba  
Rhus toxicodendron  
(drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Alcohols, biological studies  
Amides, biological studies  
Esters, biological studies  
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
USES (Uses)  
(ethoxylated; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Hair preparations  
(growth stimulants; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Vein, disease  
(hemorrhoid, drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Syrups (sweetening agents)  
(hydrolyzed starch; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Allergy inhibitors  
Aloe barbadensis  
Analgesics  
Anti-infective agents  
Anti-inflammatory agents  
Antibacterial agents  
Antibiotics  
Antiemetics  
Antihistamines  
Antimicrobial agents  
Antioxidants  
Antiperspirants  
Antitussives  
Antiviral agents  
Chelating agents  
Chemotherapy  
Cholinergic antagonists



Deodorants  
 Disinfectants  
 Fungicides  
 Hemostatics  
 Immunomodulators  
 Insecticides  
 Radical scavengers  
 Sunscreens  
 Suntanning agents  
 Vasoconstrictors  
 Vasodilators  
 Wound healing promoters  
 (invisible patches contg. bioadhesive polymers and **surfactants**  
 )

- IT Amine oxides
- Amino acids, biological studies
- Carbohydrates, biological studies
- Caseins, biological studies
- Flavonoids
- Gelatins, biological studies
- Glycerides, biological studies
- Lanolin
- Lecithins
- Oligosaccharides, biological studies
- Paraffin oils
- Peptides, biological studies
- Polyamides, biological studies
- Polyesters, biological studies
- Polyoxyalkylenes, biological studies
- Polyoxyalkylenes, biological studies
- Polysaccharides, biological studies
- Proteins
- Retinoids
- Vitamins
- RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
- USES (Uses)  
 (invisible patches contg. bioadhesive polymers and **surfactants**  
 )
- IT Anesthetics  
 (local; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Cosmetics  
 (moisturizers; invisiblepatches contg. bioadhesive polymers and  
**surfactants**)
- IT **Surfactants**  
 (**nonionic**; invisible patches contg. bioadhesive polymers and  
**surfactants**)
- IT Amines, biological studies  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
- USES (Uses)  
 (polyamines, nonpolymeric; invisible patches contg. bioadhesive  
 polymers and **surfactants**)
- IT Alcohols, biological studies  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
- USES (Uses)  
 (polyhydric, propoxylated; invisible patches contg. bioadhesive  
 polymers and **surfactants**)
- IT Quaternary ammonium compounds, biological studies  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
- USES (Uses)

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- (polymers; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Skin, disease  
(rash, drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics  
(skin-lightening; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Drug delivery systems  
(tapes; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics  
(wrinkle-preventing; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**  
(**zwitterionic**; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 36574-66-0D, N-coco acyl derivs.  
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)  
(cocoamidopropylbetaine; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 68-26-8, Retinol 96-26-4, Dihydroxyacetone 814-71-1, Calcium **thioglycolate** 34452-51-2, Potassium **thioglycolate**  
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)  
(invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 50-70-4, Sorbitol, biological studies 50-70-4D, Sorbitol, oligomers contg. 50-78-2, Aspirin 50-81-7, Vitamin C, biological studies 50-99-7D, Glucose, esters 50-99-7D, D-Glucose, oligomers contg. 55-56-1, Chlorhexidine 56-81-5, Glycerin, biological studies 56-86-0D, Glutamic acid, N-acyl derivs. 57-48-7D, Fructose, oligomers contg. 57-50-1D, Sucrose, esters 57-50-1D, Sucrose, oligomers contg. 57-55-6, Propylene glycol, biological studies 58-86-6D, Xylose, oligomers contg. 59-23-4D, Galactose, oligomers contg. 59-87-0, Nitrofurazone 60-54-8, Tetracycline 69-65-8D, Mannitol, oligomers contg. 69-72-7, Salicylic acid, biological studies 69-79-4D, Maltose, oligomers contg. 87-99-0D, Xylitol, oligomers contg. 106-11-6, Diethylene glycol monostearate 107-36-8D, Isethionic acid, cocoyl derivs. 108-46-3, Resorcinol, biological studies 108-95-2, Phenol, biological studies 114-07-8, Erythromycin 115-83-3, Pentaerythritol tetrastearate 144-55-8, Sodium bicarbonate, biological studies 151-21-3, Sodium lauryl sulfate, biological studies 404-86-4, Capsaicin 497-19-8, Sodium carbonate, biological studies 585-86-4D, Lactitol, oligomers contg. 585-88-6D, Maltitol, oligomers contg. 770-35-4, Phenoxyisopropanol 1338-41-6, Sorbitan monostearate 1406-18-4, Vitamin E 2216-51-5 3380-34-5, Triclosan 3458-28-4D, D-Mannose, oligomers contg. 6284-40-8 7439-97-6, Mercury, biological studies 7440-22-4, **Silver**, biological studies 7553-56-2, Iodine, biological studies 8011-96-9, Calamine 8050-81-5, Simethicone 9000-01-5, Gum arabic 9002-89-5, Polyvinyl alcohol 9002-98-6 9003-05-8, Polyacrylamide 9003-39-8, Polyvinylpyrrolidone 9004-64-2, Hydroxypropyl cellulose 9005-25-8, Starch, biological studies 9005-25-8D, Starch, hydrolyzates 9005-64-5, Polysorbate 20 9011-13-6, Styrene-maleic anhydride copolymer 9011-16-9, Methyl vinyl ether-maleic anhydride copolymer 11099-07-3, Glycerin stearate 11111-12-9, Cephalosporin 11140-06-0, Glycerin palmitate 12694-22-3, Diglyceryl monostearate 13718-94-0D, Palatinose, oligomers contg. 15687-27-1, Ibuprofen 18323-44-9, Clindamycin 25322-68-3, Polyethylene glycol 25322-69-4 25655-41-8, Povidone iodine 26658-19-5, Sorbitan tristearate 27195-16-0, Sucrose distearate

## STN Columbus

30233-64-8, Glyceryl monobehenate 39529-26-5, Decaglyceryl decastearate  
 42852-72-2 53998-08-6, Sarcosinate 63119-59-5, Diglycerin distearate  
 68424-04-4, Polydextrose 71185-87-0, Hexaglyceryl tristearate  
 75537-01-8, Gantrez S-97 95461-64-6, Decaglyceryl pentastearate  
 99734-29-9, Tetraglyceryl tristearate 99880-64-5, Glyceryl dibehenate  
 106392-12-5, Polyoxyethylene polyoxypropylene block copolymer  
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);  
 USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**  
 )

IT 56-75-7, Chloramphenicol 94-09-7, Benzocaine

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**  
 )

L18 ANSWER 10 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1992:536001 CAPLUS

DN 117:136001

OREF 117:23503a,23506a

ED Entered STN: 04 Oct 1992

TI Aqueous emulsion for temporary protection of **silver** and copper surfaces  
 against tarnishing

IN Grossmann, Hermann

PA Doduco GmbH und Co. Dr. Eugen Duerrwaechter, Germany

SO Eur. Pat. Appl., 6 pp.

CODEN: EPXXDW

DT Patent

LA German

IC ICM C23F011-16

CC 56-10 (Nonferrous Metals and Alloys)

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----	----	-----	-----	-----
PI	EP 492487	A1	19920701	EP 1991-121903	19911220
	EP 492487	B1	19960320		
	R: DE, ES, FR, GB, IT, NL				
	DE 4041596	A1	19920702	DE 1990-4041596	19901222
	ES 2086471	T3	19960701	ES 1991-121903	19911220
PRAI	DE 1990-4041596	A	19901222		
	DE 1991-4124955	A	19910727		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
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EP 492487	ICM	C23F011-16
	IPCI	C23F0011-16 [ICM,5]; C23F0011-10 [ICM,5,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16B
DE 4041596	IPCI	C23F0011-12 [ICM,5]; C23F0011-16 [ICS,5]; C23F0011-10 [ICS,5,C*]; C09K0015-06 [ICA,5]; C09K0015-12 [ICA,5]; C09K0015-00 [ICA,5,C*]; B01F0017-42 [ICA,5]; B01F0017-38 [ICA,5]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16B
ES 2086471	IPCI	C23F0011-16 [ICM,6]; C23F0011-10 [ICM,6,C*]
	IPCR	C23F0011-10 [I,C*]; C23F0011-16 [I,A]
	ECLA	C23F011/16B

AB The emulsion of pH 1-10 (preferably 2-4) comprises a hydrophobic inhibitor  
 of a C<sub>≥12</sub> thioalc. with ≥ 1 SH group and its ester 0.05-50

(preferably 2-20), emulsifier 0.05-50 (2-20), and an **anionic** or **nonionic surfactant**  $\leq 2$  (0.05-1 g/L). The emulsifier comprises an alkoxyated and preferably ethoxyated branched C4-20 alc., an alkyl or alkylphenyl ether of polyethylene glycol. **Ag**, Cu, and their alloys are treated with the emulsion at  $>T$  (m.p. of inhibitor), rinsed with H<sub>2</sub>O at  $<T$ , and dried with hot air. An example emulsion of pH 3 and suitable for treatment of **Ag** and **Ag** alloys contains **octadecanethiol** 0.5-30, polyethylene glycol alkyl ether 0.5-30, and SDS  $\leq 1$  g/L H<sub>2</sub>O.

- ST tarnishing inhibitor **silver** copper; thiol SDS tarnishing inhibitor **silver**; SDS thiol tarnishing inhibitor copper; polyethylene glycol ether tarnishing inhibitor
- IT Thiols, uses  
RL: USES (Uses)  
(corrosion inhibitors, for copper and **silver**, with emulsifiers of alkyl or alkylphenyl ether of polyethylene glycol)
- IT Tarnishing  
(of **silver** and copper alloys, aq. emulsion for prevention of)
- IT Corrosion inhibitors  
(thiols, with emulsifiers of alkyl or alkyl Ph ether of polyethylene glycol)
- IT Alcohols, compounds  
RL: PROC (Process)  
(C8-16, ethoxyated, corrosion inhibitor emulsion contg., thiol, for copper and **silver** and their alloys)
- IT copper alloy, base  
**silver** alloy, base  
RL: RCT (Reactant); RACT (Reactant or reagent)  
(tarnishing of, thiol inhibitor for)
- IT 25322-68-3D, Polyethylene glycol, alkyl and alkylphenyl ethers 151-21-3, uses  
RL: PROC (Process)  
(corrosion inhibitor emulsion contg., thiol, for copper and **silver** and their alloys)
- IT **2885-00-9, Octadecanethiol**  
RL: PROC (Process)  
(corrosion inhibitors, for copper and **silver**, with emulsifiers of alkyl or alkylphenyl ether of polyethylene glycol)
- IT 7440-22-4, **Silver**, reactions 7440-50-8, Copper, reactions  
RL: RCT (Reactant); RACT (Reactant or reagent)  
(tarnishing of, thiol inhibitor for)

L18 ANSWER 11 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1991:89162 CAPLUS

DN 114:89162

OREF 114:15093a,15096a

ED Entered STN: 09 Mar 1991

TI **Silver** metal liquidlike films (MELLFs). The effect of **surfactants**

AU Yogeve, D.; Efrima, S.

CS Dep. Chem., Ben-Gurion Univ. Negev, Beer-Sheva, 84105, Israel

SO Langmuir (1991), 7(2), 267-71

CODEN: LANGD5; ISSN: 0743-7463

DT Journal

LA English

CC 66-4 (Surface Chemistry and Colloids)

Section cross-reference(s): 73, 74

AB The effects of **surfactants** on the prodn. and stabilization of **Ag** metal liquidlike films (MELLFs) were studied. The main role of the **surfactant** is in stabilizing the **Ag** MELLFs and improving their properties

(reflectivity, "fluidity"). A variety of different **surfactants** were found to be active, and of those investigated, **anionic** fluoroalkyl **surfactants** seem to be the most effective. In the case of **anionic surfactants**, the counteraction has a significant effect on the **Ag** MELLF, esp. if it is a surface-active agent in itself. The effects of the **surfactants** on the interfacial tension and their effect on the measured reflectivities of the MELLFs are discussed in the context of the interfacial colloidal model of **Ag** MELLFs.

- ST **silver** metal liquidlike film formation; **surfactant** effect metal liquidlike film; interfacial tension metal liquidlike film
- IT Films  
(metal liq.-like, **surfactant** effects on formation of)
- IT Interfacial tension  
(of **surfactant** solns., **silver** metal liq.-like film formation in relation to)
- IT Sulfonic acids, compounds  
RL: PRP (Properties)  
(perfluoroalkane, ammonium and potassium salts, **surfactant** effect of, on **silver** metal liq.-like film formation)
- IT **Surfactants**  
(**silver** metal liq.-like film formation in presence of)
- IT Carboxylic acids, compounds  
RL: PRP (Properties)  
(perfluoro, ammonium salts, **surfactant** effect of, on **silver** metal liq.-like film formation)
- IT 7440-22-4, **Silver**, uses and miscellaneous  
RL: USES (Uses)  
(liq.-like metal film formation by, **surfactant** effects on)
- IT 577-11-7 **2885-00-9**, 1-Octadecanethiol 9002-93-1, Triton X 100 52584-45-9, Monflor 31 57534-41-5, Zonyl FSN 60529-61-5, Monflor 32 67479-85-0, Zonyl FSC 67479-86-1, Zonyl FSP  
RL: PRP (Properties)  
(**silver** metal liq.-like film formation in presence of)

L18 ANSWER 12 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1987:33631 CAPLUS

DN 106:33631

OREF 106:5655a,5658a

ED Entered STN: 07 Feb 1987

TI Maleimide copolymer and thermoplastic resin prepared by using this copolymer

IN Kimura, Atsushi; Toyooka, Yutaka; Kishida, Kazuo

PA Mitsubishi Rayon Co., Ltd., Japan

SO PCT Int. Appl., 41 pp.

CODEN: PIXXD2

DT Patent

LA Japanese

IC ICM C08F002-18

ICS C08F212-04; C08L033-14; C08L035-06; C08L051-04

CC 35-4 (Chemistry of Synthetic High Polymers)

Section cross-reference(s): 38

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----	---	-----	-----	-----
PI	WO 8604337	A1	19860731	WO 1986-JP17	19860117
	W: AU, US				
	RW: DE, FR, GB, IT, NL				
	JP 61163903	A	19860724	JP 1985-4907	19850117
	JP 61174248	A	19860805	JP 1985-12705	19850128

## STN Columbus

AU 8653567	A	19860813	AU 1986-53567	19860117
EP 208790	A1	19870121	EP 1986-900840	19860117
R: DE, FR, GB, IT, NL				
CA 1262299	A1	19891010	CA 1986-518902	19860923
PRAI JP 1985-4907	A	19850117		
JP 1985-12705	A	19850128		
WO 1986-JP17	A	19860117		

## CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
-----	-----	-----
WO 8604337	ICM	C08F002-18
	ICS	C08F212-04; C08L033-14; C08L035-06; C08L051-04
	IPCI	C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08L0033-14 [ICS, 4]; C08L0033-00 [ICS, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*]
	IPCR	C08F0002-12 [I, C*]; C08F0002-18 [I, A]; C08F0222-00 [I, C*]; C08F0222-40 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-04 [I, A]
	ECLA	C08F222/40; C08L035/06+B5; C08L051/04+B2
JP 61163903	IPCI	C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08F0002-00 [ICA, 4]
JP 61174248	IPCI	C08L0033-18 [ICM, 4]; C08L0033-00 [ICM, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*]
	IPCR	C08L0033-00 [I, C*]; C08L0033-00 [I, A]; C08L0007-00 [I, C*]; C08L0007-00 [I, A]; C08L0021-00 [I, C*]; C08L0021-00 [I, A]; C08L0023-00 [I, C*]; C08L0023-00 [I, A]; C08L0033-02 [I, A]; C08L0033-18 [I, A]; C08L0033-24 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-00 [I, A]; C08L0051-02 [I, A]; C08L0051-04 [I, A]; C08L0101-00 [I, C*]; C08L0101-00 [I, A]
AU 8653567	IPCI	C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08L0033-14 [ICS, 4]; C08L0033-00 [ICS, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*]
	IPCR	C08F0002-12 [I, C*]; C08F0002-18 [I, A]; C08F0222-00 [I, C*]; C08F0222-40 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-04 [I, A]
	ECLA	C08F222/40; C08L035/06+B5; C08L051/04+B2
EP 208790	IPCI	C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08L0033-14 [ICS, 4]; C08L0033-00 [ICS, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*]
	IPCR	C08F0002-12 [I, C*]; C08F0002-18 [I, A]; C08F0222-00 [I, C*]; C08F0222-40 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-04 [I, A]
	ECLA	C08F222/40; C08L035/06+B5; C08L051/04+B2
CA 1262299	IPCI	C08F0212-04 [ICM, 4]; C08F0212-00 [ICM, 4, C*]; C08L0025-02 [ICS, 4]; C08L0025-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*]
	IPCR	C08F0212-00 [I, C*]; C08F0212-04 [I, A]; C08L0025-00

# STN Columbus

[I,C\*]; C08L0025-02 [I,A]; C08L0051-00 [I,C\*];  
C08L0051-04 [I,A]

- AB A maleimide polymer with excellent heat stability during high-temp. molding and giving a product with excellent resistance to discoloration, heat, and impact when blended with a graft rubber, is prepd. by polymn. of a monomer selected from an arom. vinyl monomer, an unsatd. nitrile, and Me methacrylate 50-95, a maleimide 5-50, and other monomers 0-30% in the presence of a Ca phosphate-based dispersing agent and a **nonionic surfactant** [RO(CH<sub>2</sub>CH<sub>2</sub>O)<sub>n</sub>]mPO(OA)<sub>3</sub>-m (R = C<sub>8</sub>-30 alkyl, aralkyl; A = H, metal; m = 1-3, n = 5-50). The process minimizes the scale formation of formed polymers on a reactor wall during polymn. Thus, a mixt. of acrylonitrile 20, styrene 170, and N-phenylmaleimide 10 parts in 100 parts water contg. AIBN 0.1, tert-Bu benzoate 0.1, tert-dodecyl **mercaptan** 0.3, Gafac GB 520 0.003, and Ca<sub>3</sub>PO<sub>4</sub> 0.5 part was suspension-polymd. at 80° for 3 h and at 120° for 2 h to give polymer beads (particle diam. 180 μ, glass-transition temp. 125°). During the polymn., no scale formation was obsd. A blend of 55 parts maleimide copolymer and 45 parts graft polymer from polybutadiene 50, acrylonitrile 15, and styrene 35 parts contg. Mg stearate 0.3, tris(nonylphenyl) phosphite 0.1, and Antage W 400 0.2 phr was injection-molded at 280-290° to give a sample exhibiting yellowing index (at 280°) 31, notched Izod impact strength 16.4 kg-cm/cm<sup>2</sup>, Rockwell hardness (R) 102, and Vicat softening point 108°, with no **silver** streak formation, compared with 44, 16, 101, and 104, with **silver** streak formation, when a maleimide copolymer prepd. in the presence of poly(vinyl alc.) as a dispersing agent was used.
- ST phenylmaleimide copolymer suspension polymn; acrylonitrile copolymer suspension polymn; styrene copolymer suspension polymn; calcium phosphate dispersant suspension polymn; polyethylene glycol lauryl ether phosphate; **nonionic** phosphate **surfactant** suspension polymn; scale prevention suspension polymn dispersant; ABS blend maleimide copolymer molding; heat stability maleimide copolymer molding
- IT Plastics, molded  
RL: USES (Uses)  
(ABS polymer-maleimide-contg. polymers, heat- and impact-resistant, heat-stable)
- IT Heat-resistant materials  
(maleimide-contg. polymers, heat stability improvement of)
- IT Dispersing agents  
(polyalkylene glycol phosphate-tricalcium phosphate, in suspension polymn. of maleimide-contg. monomer mixts., for scale formation prevention)
- IT Scale (coating)  
(prevention of, on reactor wall during suspension polymn. of maleimide-contg. monomer mixts., dispersing agents for)
- IT Polymerization  
(suspension, of maleimide-contg. monomer mixts., dispersing agents for, for scale formation prevention)
- IT 9003-56-9  
RL: USES (Uses)  
(phenylmaleimide copolymer blends, heat-stable, resistant to discoloration, heat and impact)
- IT 31621-07-5P, Acrylonitrile-N-phenylmaleimide-styrene copolymer  
94858-30-7P, Acrylonitrile-α-methylstyrene-N-phenylmaleimide-styrene copolymer  
101482-57-9P, Acrylonitrilemethyl methacrylate-N-phenylmaleimide-styrene copolymer  
RL: PREP (Preparation)

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(prepn. of, by suspension polymn., dispersing agents for, for improved heat stability and scale prevention during polymn.)

IT 51811-79-1, Gafac RE 610

RL: USES (Uses)

(suspending agents, Gafac RE 610, in suspension polymn. of maleimide-contg. monomer mixts., for scale formation prevention during polymn.)

IT 35604-29-6, Gafac GB 520

RL: USES (Uses)

(suspension agent, Gafac GB 520, in suspension polymn. of maleimide-contg. monomer mixts., for scale formation prevention during polymn.)

IT 7758-87-4, Tricalcium phosphate

RL: USES (Uses)

(suspension agent, in suspension polymn. of maleimide-contg. monomer mixts., for scale formation prevention during polymn.)

RE.CNT 7 THERE ARE 7 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Anon; JP 4983785 A
- (2) Anon; JP 5495689 A
- (3) Anon; JP 57125242 A CAPLUS
- (4) Anon; JP 57167341 A CAPLUS
- (5) Anon; JP 58129043 A CAPLUS
- (6) Anon; JP 58206657 A CAPLUS
- (7) Anon; JP 59184243 A CAPLUS

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COST IN U.S. DOLLARS

SINCE FILE	TOTAL
ENTRY	SESSION
172.85	182.49

FULL ESTIMATED COST

DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS)

SINCE FILE	TOTAL
ENTRY	SESSION
-22.96	-22.96

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